

CPU LIST			
I3-	TGL	6025B0436701	QU7M
I5-	TGL	6025B0436401	QU7K
I7-	TGL	6025B0436301	QU7J

GPU LIST	
NV N18S-G5	6019B2036901

VRAM LIST		
Hynix	H5GC8H24MJR-R0C	6019B1542101
Micron	MT51J256M32HF-70:A	6019B1486001
Samsung	K4G80325FB-HC28	6019B1485901
Hynix	H5GC8H24AJR-R2C A	6019B1723701
Micron	MT51J256M32HF-80:B B	6019B1721101
Samsung	K4G80325FC-HC25	6019B1926601

SSID
UMA 8819
DIS 881A

HEDWIG

INTEL TIGER LAKE-UP3 15W

DIS : 24.5X24.5

GPU : N18S-G5
VRAM : GDDR5 256MX32X2PCS
MV BUILD
2021.03.25

LOCATION	LEVEL	CO-LAY
PAD6015	PVBAT	SHORT
PAD60200	P5V0A	SHORT
PAD60203	P5V0AL	OPEN
PAD60210	PVBAT	SHORT
PAD60100	P3V3A	SHORT
PAD60110	PVBAT	SHORT
PAD60103	P3V3AL	SHORT
PAD60310	PVBAT	SHORT
PAD60300	P1V2	SHORT R60399 OPEN
PAD60350	P0V6S	SHORT
PAD60410	P3V3A	SHORT
PAD60400	P2V5	SHORT
PAD6970	P1V8A	SHORT
PAD6980	P5V0A	SHORT
PAD66020	PVBAT	SHORT
PAD66010	PVBAT	SHORT
PAD66610	PVBAT	SHORT
PAD2500	P5V0A_USBPWR	OPEN
PAD67010	PVBAT	SHORT R67010 OPEN
PAD67200	P1V35S_DGPU	SHORT
PAD67210	PVBAT	SHORT
PAD67410	P3V3A	SHORT
PAD67610	P3V3A	SHORT
PAD67600	P1V0S_DGPU	SHORT
PAD7402	P1V8S_MAIN1	SHORT
PAD7401	P1V8S_AO1	SHORT

ID PIN FOR BIOS

GPU_ID	UMA	DIS
R4587	MOUNT	OPEN
R4588	MOUNT	MOUNT
3V	3V	0V
GPU_ID	UMA	DIS
R4591	MOUNT	OPEN
WWAN_SKU_ID	WWAN	Non WWAN
R4523	MOUNT	OPEN
R4524	OPEN	MOUNT
3V	3V	0V
BOARD_ID0	ATI	NV
R4559	MOUNT	OPEN
R4618	OPEN	MOUNT
3V	3V	0V
BOARD_ID1	DIS	UMA
R4535	MOUNT	OPEN
R4536	OPEN	MOUNT
3V	3V	0V
BOARD_ID2	U42	U22
R4632	MOUNT	OPEN
R4514	OPEN	MOUNT
3V	3V	0V
PROJECT_ID0	VRAM 2G	VRAM 4G
R4579	MOUNT	OPEN
R4578	OPEN	MOUNT
3V	3V	0V
PROJECT_ID1	T7-SNAPE	HEDWIG
R4530	MOUNT	OPEN
R4526	OPEN	MOUNT
3V	3V	0V
PROJECT_ID2	U4-GRANDER	U4-SILVERBEE
R4532	MOUNT	OPEN
R4533	OPEN	MOUNT
3V	3V	0V

ID PIN FOR EC

GPU_UMA_SEL	DIS	UMA
R392	MOUNT	OPEN
R393	OPEN	MOUNT
	3V	0V

Phase_ID	SI	DB	PV / Mv
R337	10K_short	10K_short	10K_open
R322	10K_open	10K_short	10K_short
	3V	1.5V	0V

GPU_ID	NV	ATI
R390	MOUNT	OPEN
R391	OPEN	MOUNT
	3V	0V

EC_PROJECT_ID	SNAPE17	GRANGER14
R310	10K_short	10K_open
R311	10K_short	10K_short
	3V	0V

ADP_SEL	65W	45W
R307	MOUNT	OPEN
R309	OPEN	MOUNT
	3V	0V

CPU_ID	R42_15W	J22_15W
R343	MOUNT	OPEN
R338	OPEN	MOUNT
	3V	0V

HEDWIG TGL + N18S-G5 6050A3285801 (8L)

DAUGHTER BOARD (8L)
PICK BUTTON BOARD (TYPE C) 6050A3163901 (8L)
CARD READER BOARD (TYPE C) 6050A3283201 (8L)

DATE	CHANGE NO.	REV
21-OCT-2002		

DESIGN/DRAWER	DATE	21-OCT-2002	TITLE	MLB 17" - RANGERS	Main Board
CHECK	XXX		SIZE	A3	
APPROVAL	1301000000-0-0		CODE	CS	
FILE NAME	6050A3285801		SHEET	1	
PCB PIN	PCB VER	XXX			

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7 CHARGER_BQ24725A
8 DC PROCHOT#
9 P5V0A_SYV126C
10 P3V3A_SYV126B
11 DDR POWER(P1V2_P0V675S)
12 P2V5_AP2132B
13 P1V8A_RT8068A
14 CPU VR CONTROLLER RT3613EE
15 VCORE MOS
16 PVCCIN AUX MP2941
17 CPU POWER LOAD SW
18 POWER LOAD SW
19 ENABLE PIN
20 PDG SEQUENCE
21 THERMAL & FAN
22 MCP_MEMORY
23 SPI ROM
24 MCP-GPIO1, LPC, SPI
25 MCP-GPIO2, I2C, UART
26 MCP-MISC, HDA, JTAG
27 MCP-CSI, CNV
28 MCP-PCIE, USB3, USB2
29 MCP-CLK, RTC, CFG
30 DDI, TCP
31 MCP-POWER MANAGEMENT
32 MCP-POWER1
33 MCP-POWER2
34 MCP-POWER3
35 MCP-GND, RSVD
36 MCP-STRAPS-1

37 MCP-STRAPS-1
38 DDR4 DIMM0
39 DDR4 DIMM1
40 EC
41 KB CONN & LED
42 SATA HDD
43 MUX FOR SATA /PCIE SSD
44 SSD_M2_2280_S3_M-KEY
45 HDMI
46 30PIN LCM
47 TPM 2.0 & FINGER PRINTER
48 USB3.0 CONN_2 PORT
49 USB3.0 CHARGER
50 WLAN_M2_2230_E-KEY
51 AUDIO CODEC
52 LAN_RTL8166EH
53 TRANSFORMER & RJ45
54 EMC CAP
55 RF SOLUTION
56 MB TO DB CONN & SCREW
57 MB TO CR BOARD
58 DB COVER
59 DB1-USB3.0
60 DB1-USB3.0 HUB
61 DB1-USB3.0 TYPE_C
62 DB1-CARD READER
63 DB1-POWER BUTTON & LID
64 DB2-PICK BUTTON
65 GPU COVER
66 GPU-1
67 GPU-2
68 GPU-3
69 GPU-4
70 GPU-5
71 GPU VRAM
72 PVCORE_DGPU (RT8816A 2 PHASE)

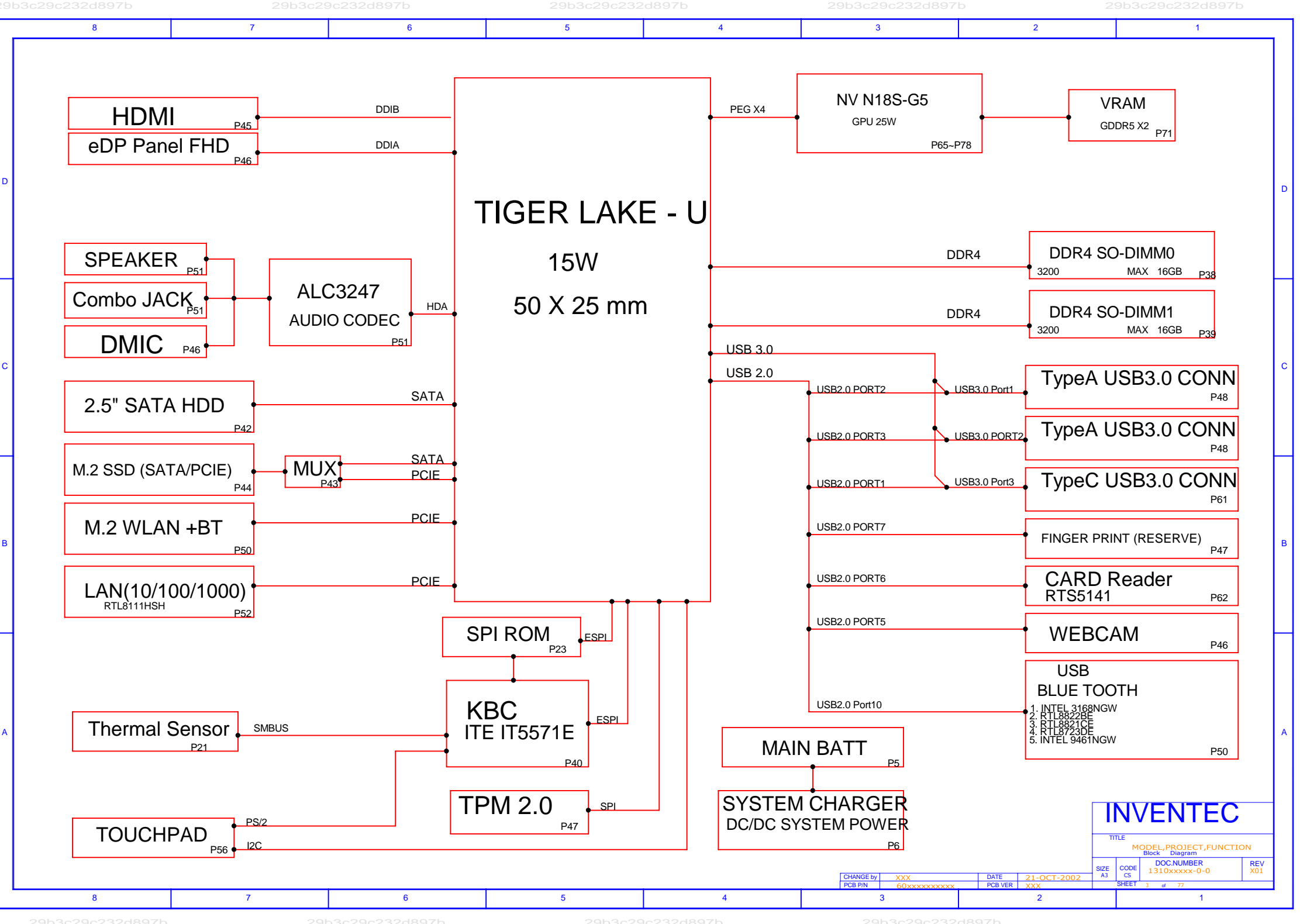
73 P1V35S_DGPU (NB685A)
74 P1V8S_DGPU (RT8097A)
75 P1V0S_DGPU (RT8097A)
76 DGPU POWER SEQUENCE
77 GPU DISCHARGE
78 GPU SEQUENCE

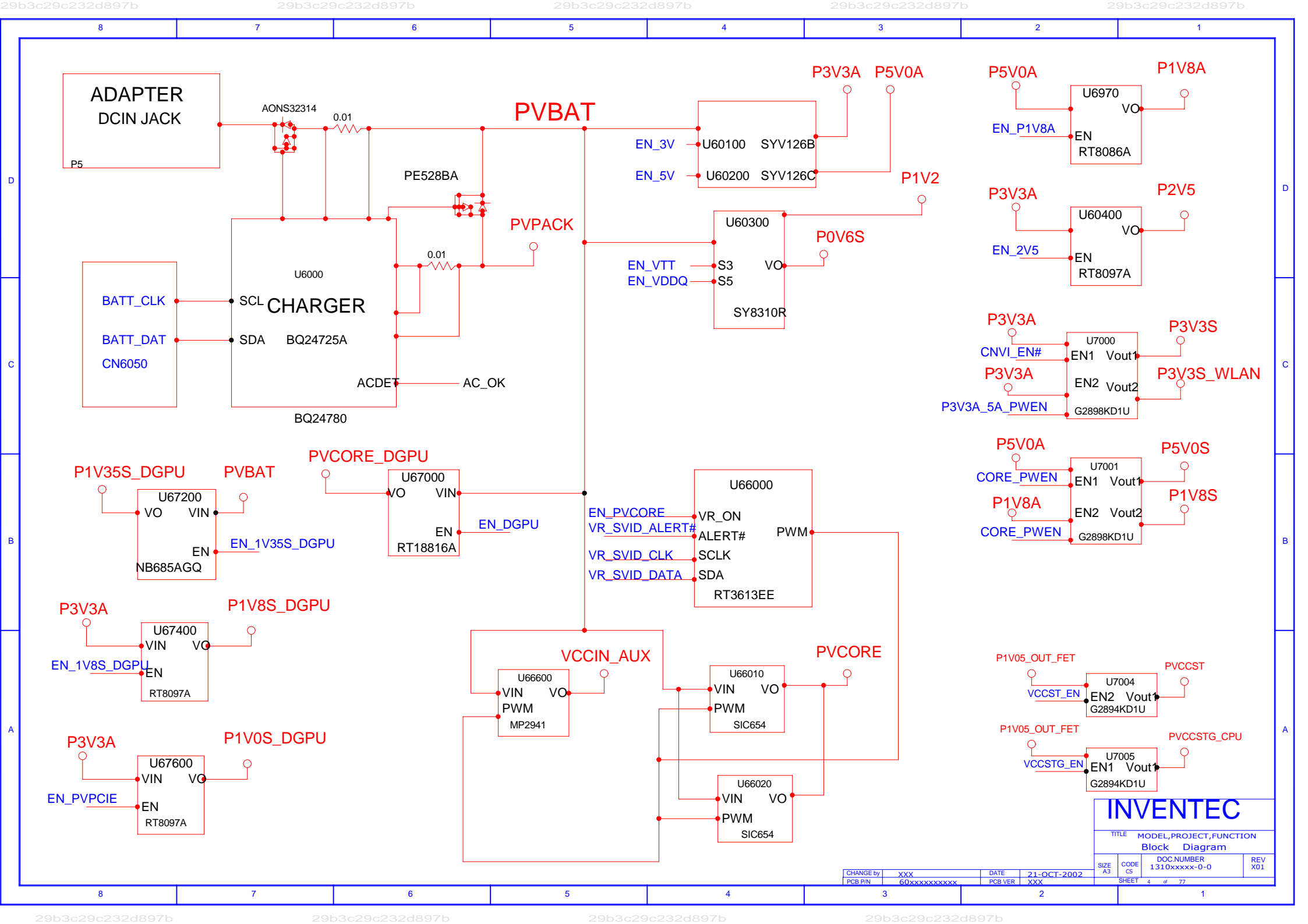
INVENTEC

TITLE MODEL,PROJECT,FUNCTION
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CHANGE by PCB P/N	XXX 60xxxxxxxxxx	DATE PCB VER	21-OCT-2002 XXX
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INVENTEC

TITLE MODEL,PROJECT,FUNCTION
Block Diagram

SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
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VER.04_20171113



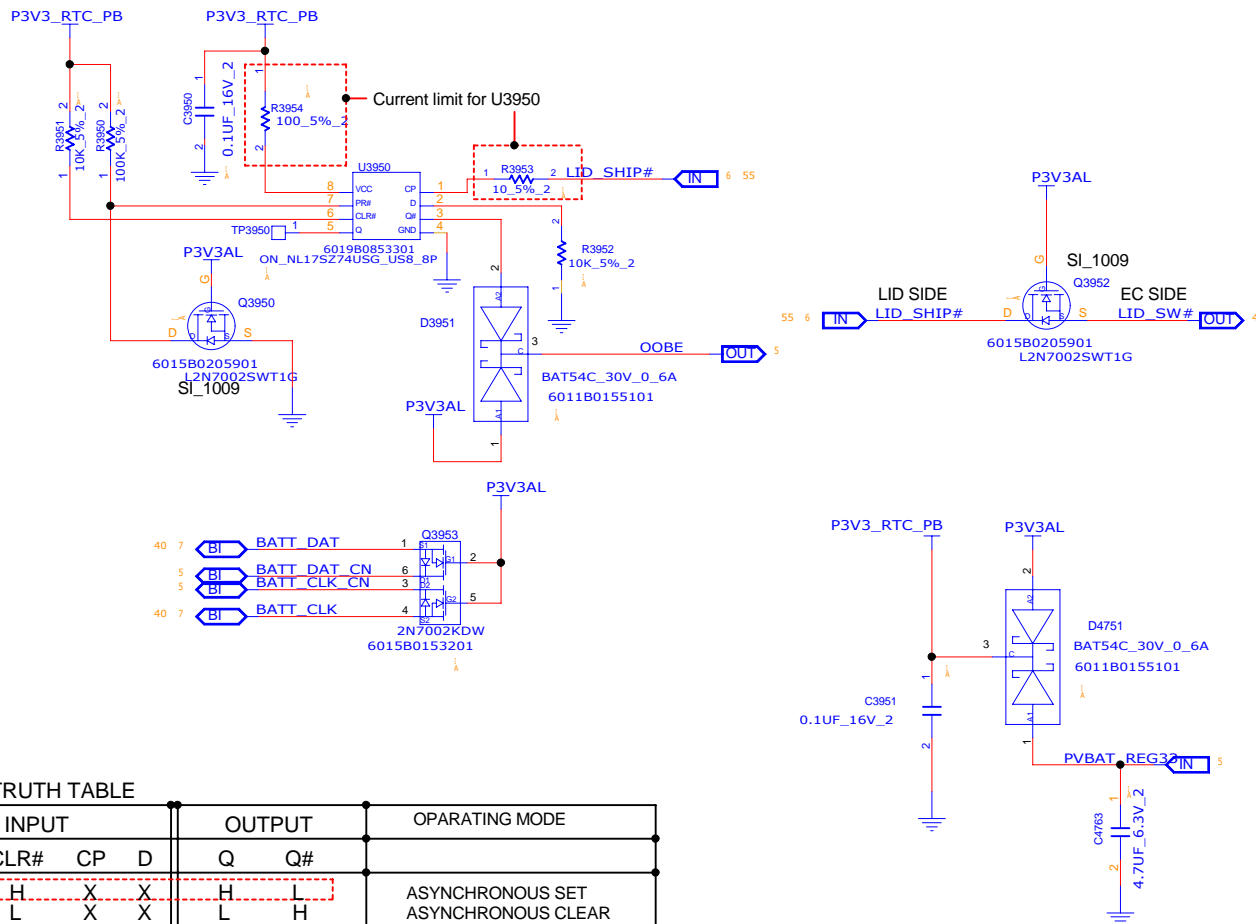
TITLE	MODEL, PROJECT, FUNCTION
Block	Diagram

SIZE A3	CODE CS	DOC.NUMBER 1310xxxxx-0-0	REV X01
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STORAGE MODE

VER.01_20170918



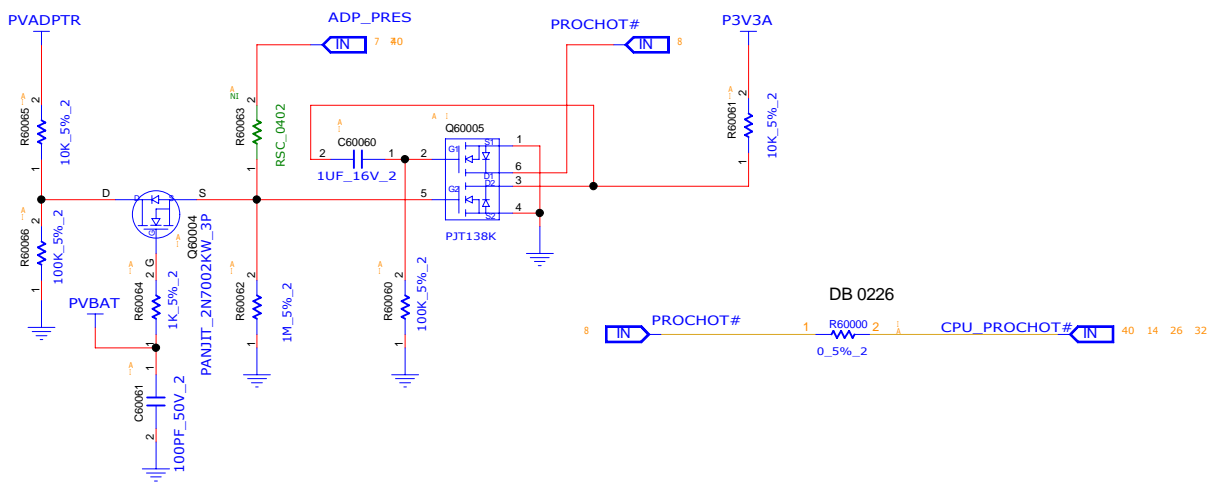
INVENTEC

TITLE
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INVENTEC

TITLE

MODEL,PROJECT,FUNCTION

Block Diagram

SIZE
A3

CODE
CS

DOC NUMBER
1310xxxxx-0-0

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X01

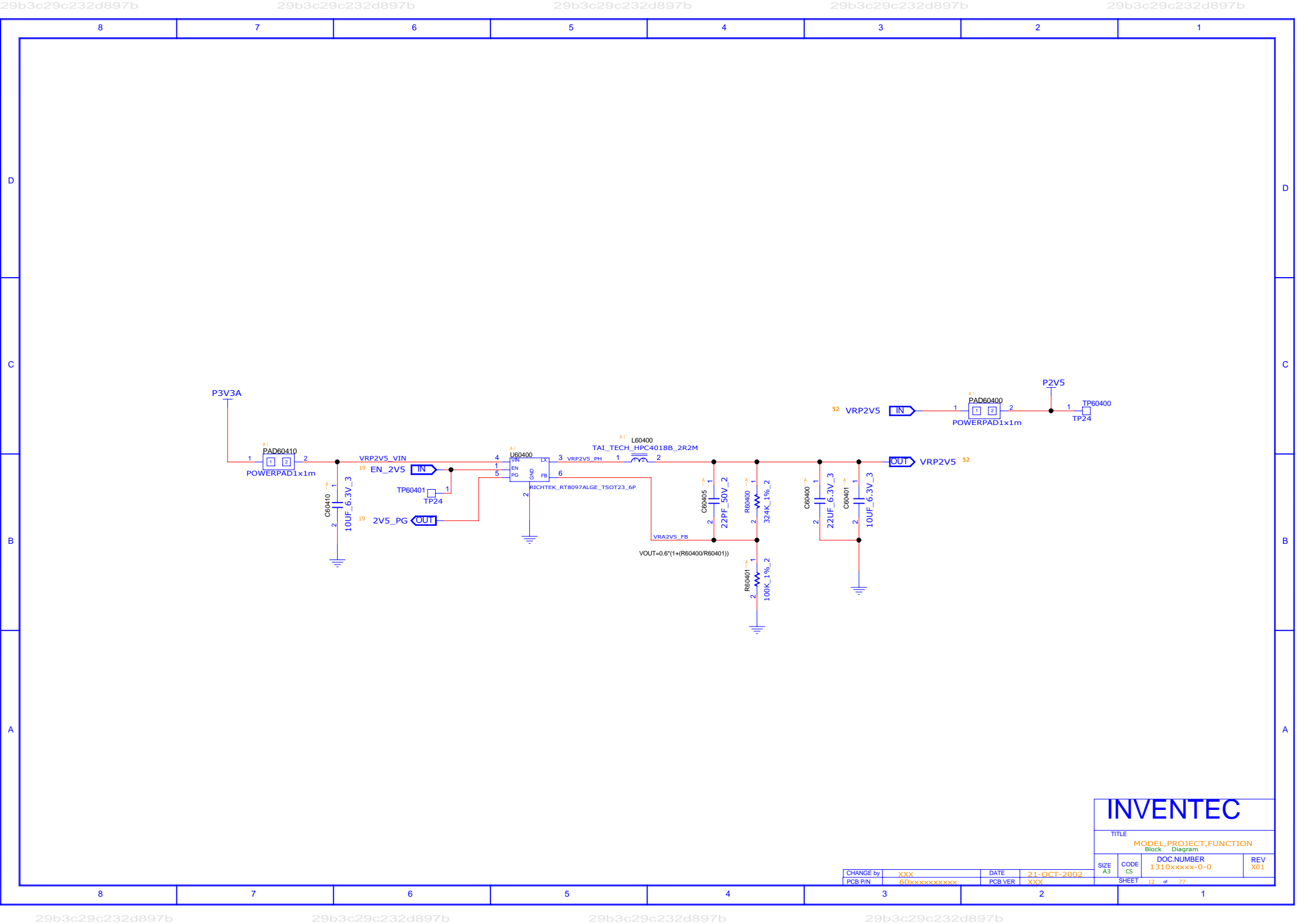
CHANGE by
PCB P/N

XXX
60xxxxxxxxxxx

DATE
PCB VER

21-OCT-2002
XXX

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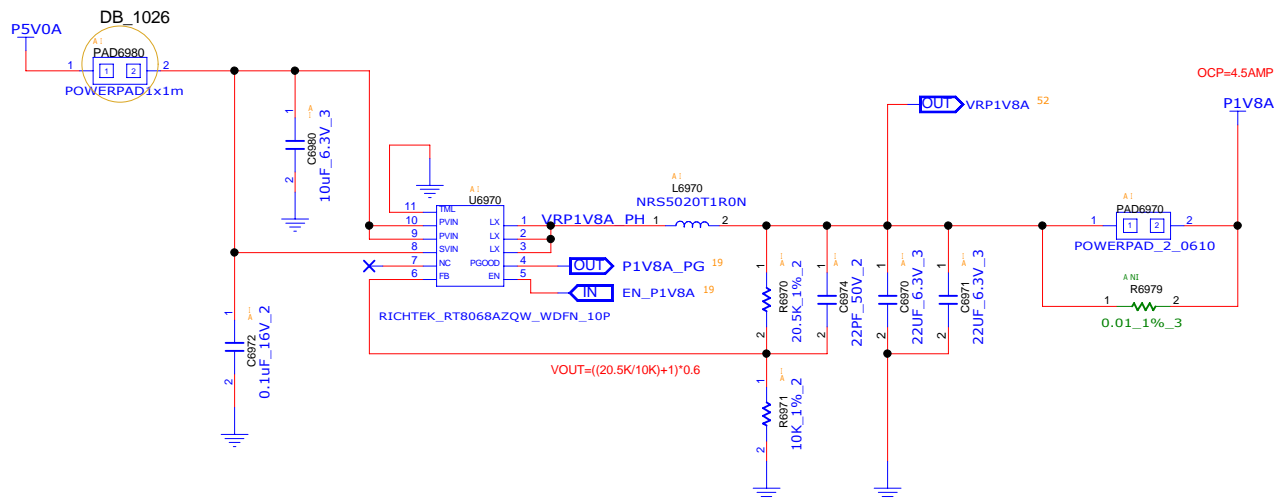


INVENTEC

TITLE
MODEL,PROJECT,FUNCTION
Block Diagram

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CHANGE by PCB P/N	XXX 60xxxxxxxxxxx	DATE PCB VER	21-OCT-2002 XXX
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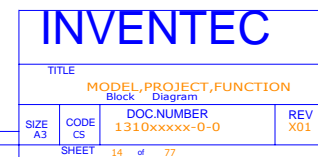


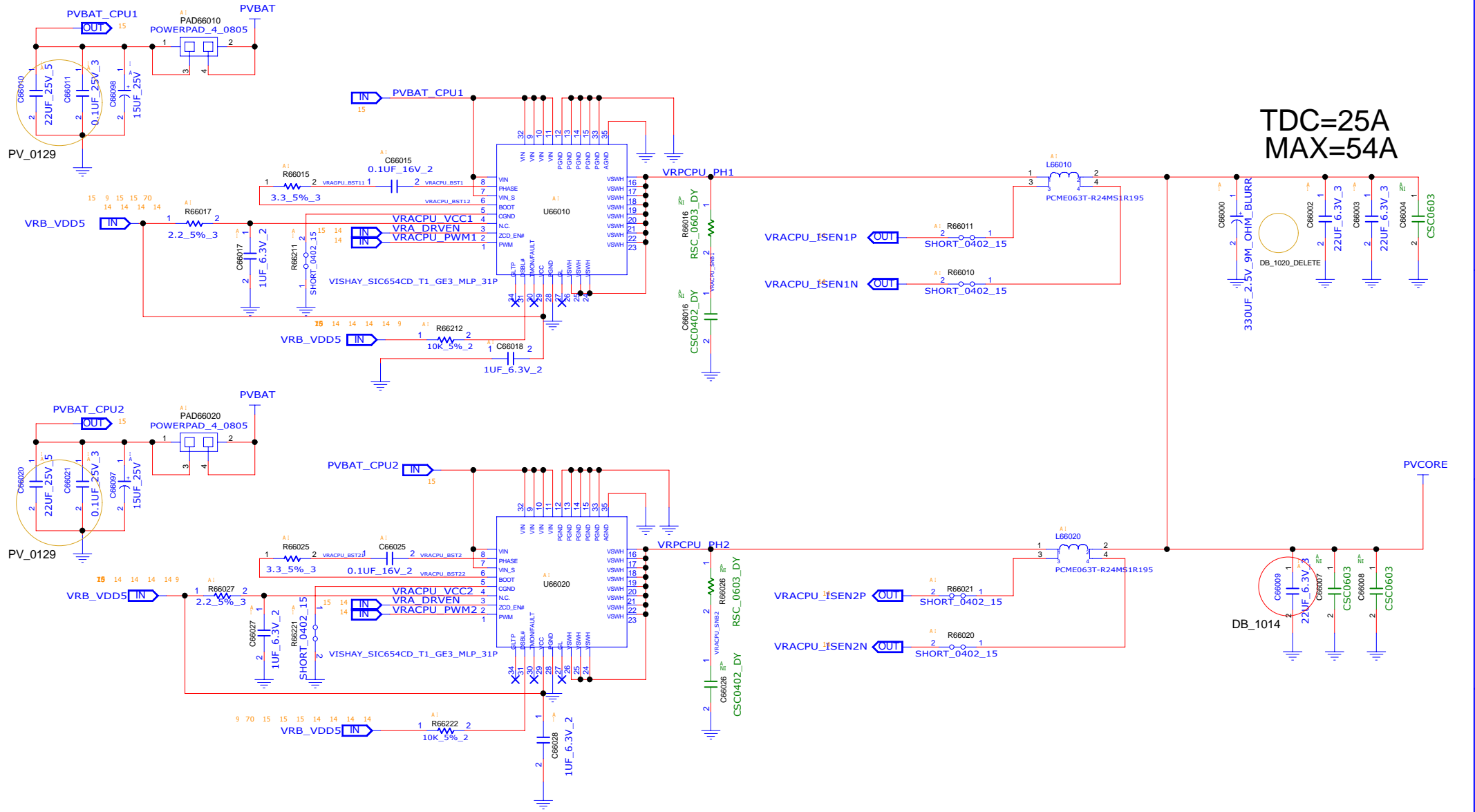
INVENTEC

TITLE
MODEL,PROJECT,FUNCTION
Block Diagram

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IA				AUX		PL(W)		
TGL 15	Thermal sku	IccMax (A)	I_PL2 (A)	LL (mΩ)	IccMax (A)	I_PL2 (A)	PL1	PL2
U42	Baseline	47	30	2	27	14	15	51

INVENTEC

TITLE			
MODEL,PROJECT,FUNCTION			
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PCB P/N 60xxxxxxxxxx	PCB VER XXX

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MODEL PROJECT, FUNCTION Block Diagram			
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FIGURE 11-29. ICE LAKE NON-DSX SYSTEM ARCHITECTURE BLOCK DIAGRAM

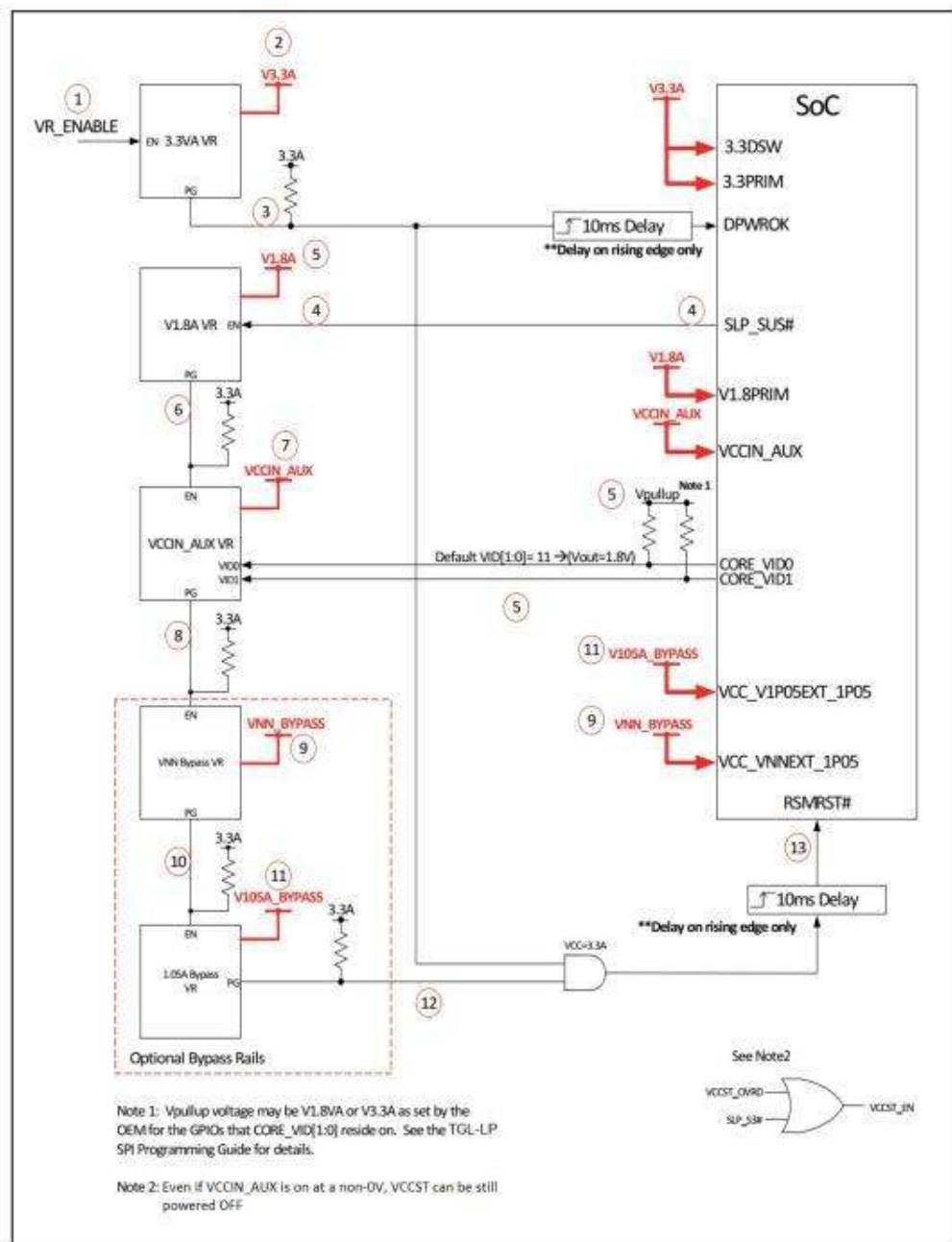


Table 195. System with M3 State Supported

Rails	SKUs	S0/M0 3	C102	S0ix/M- off ¹	S3/M3	S3/M- off	S4 and S5/M3	S4 and S5/M- off	Deep S4/S5	G31
VCCRTC	All	ON	ON	ON	ON	ON	ON	ON	ON	ON
VCCDSW_3P3	All	ON	ON	ON	ON	ON	ON	ON	ON	No Power
VBATA (VDC)	All	ON	ON	ON	ON	ON	ON	ON	ON	No Power
V5.0A	All	ON	ON	ON	ON	ON	ON	ON	OFF	No Power
VCCPRIM_3P3	All	ON	ON	ON	ON	ON	ON	ON	OFF	No Power
VCCPRIM_1P8	All	ON	ON	ON	ON	ON	ON	ON	OFF	No Power
VCC_VNNEXT_1P05	All	ON	ON	ON	ON	ON	ON	ON	OFF	No Power
VCC_V1P0SEXT_1P05	All	ON	ON	ON	ON	ON	ON	ON	OFF	No Power
V3.3M ⁵	All	ON	ON	OFF	ON ¹⁰	OFF	ON ¹⁰	OFF	OFF	No Power
V1.8M ⁵	All	ON	ON	OFF	ON ¹⁰	OFF	ON ¹⁰	OFF	OFF	No Power
VDDQ	All	ON	ON	ON	ON	ON	OFF	OFF	OFF	No Power
V2.5U (VPP)	All	ON	ON	ON	ON	ON	OFF	OFF	OFF	No Power
VCCST	All	ON	ON	ON	ON ¹³	ON ¹³	OFF ⁶	OFF ⁶	OFF	No Power
VCCSTG	All	ON	OFF ²	OFF	OFF	OFF	OFF	OFF	OFF	No Power
V3.3S	All	ON	ON	ON	OFF	OFF	OFF	OFF	OFF	No Power
VCCIN	All	ON	ON	ON ¹¹	OFF	OFF	OFF	OFF	OFF	No Power
VCCIN_AUX	All	ON	ON	ON ¹¹	OFF ¹⁴	OFF ¹⁴	OFF ¹⁴	OFF ¹⁴	OFF	No Power

- Notes:
1. The state of the system without RTC well powered can also be considered G3.
 2. VCCSTG can be turned off when the processor is in C10.
 3. S0/M0 state includes all Package C-states from C0-C10.
 4. Assume SLP_SUS# and CPU_C10_GATE# have asserted from the PCH.
 5. V3.3M and V1.8M are platform rails used by external devices which ME operates during Sx/M3 states. These rails are not used directly by the CPU/PCH, and are not present on non-M3 supported systems.
 6. VCCST and VCCSTG can remain powered during S4 and S5 power states for board cost optimization. VCCST, VCCSTG may also remain powered in S4 and S5 for debug purposes. Refer to Platform Debug and Test Hooks chapter for more details.
 7. NA
 8. NA
 9. VCCSTG is allowed to be ramped to 0V during S0 only when CPU_C10_GATE# is asserted. Specific exit latency targets are required when this feature is implemented. If VCCSTG power gating is not supported on the platform (shared with VCCST), VCCSTG is allowed to stay ON during S0ix and S3 states. Note that merging power rails may reduce power optimization opportunities on the platform.
 10. For no M3 support on external devices, V3.3M/V1.8M will be OFF in Sx/M3.
 11. This supply is expected to be 0V during states where SLP_SUS# is asserted. It may be left on during this condition, but the SoC will not achieve it's lowest power consumption. Specific power up latencies apply when exiting this state. Applicable to form factors with battery only (ie. A10)Optional depending platform design; ON if AC is present.
 12. NA
 13. For additional power savings in S3, Refer Power Sequencing Timing Diagrams Legacy Signals on page 416.
 14. VCCIN_AUX may be ON in these power states if required by the SOC.

INVENTEC

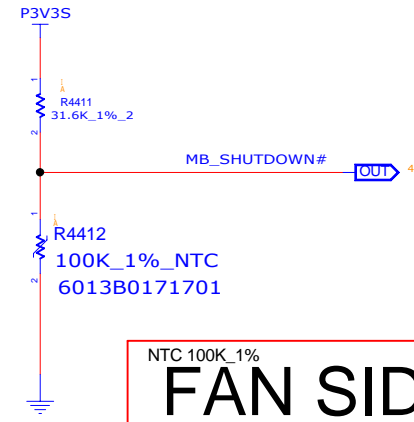
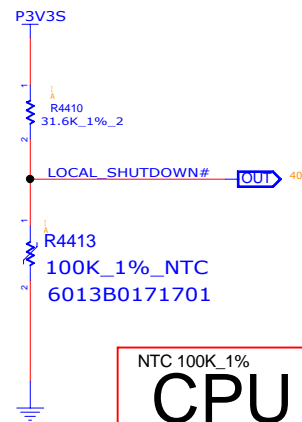
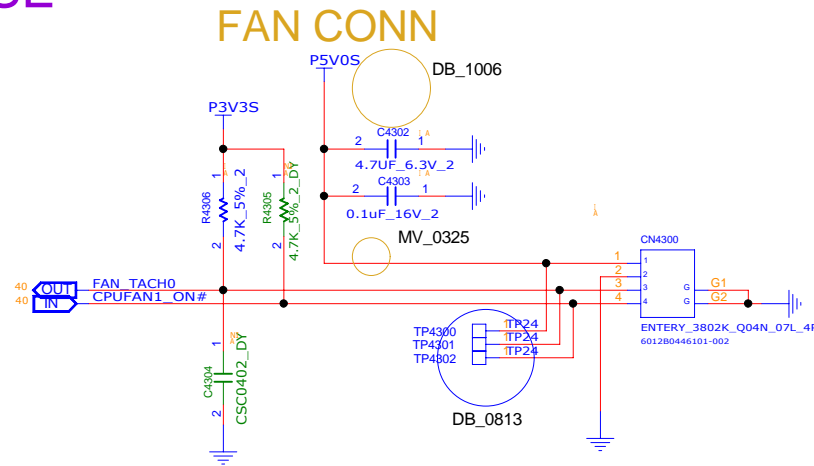
TITLE			
MODEL, PROJECT, FUNCTION			
SIZE	CODE	DOC NUMBER	REV
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PCB P/N	60xxxxxxxxxx	PCB VER	XXX

FAN & THERMAL

FOR BIG CORE USE

VER.04_20171011



INVENTEC

TITLE

MODEL PROJECT,FUNCTION

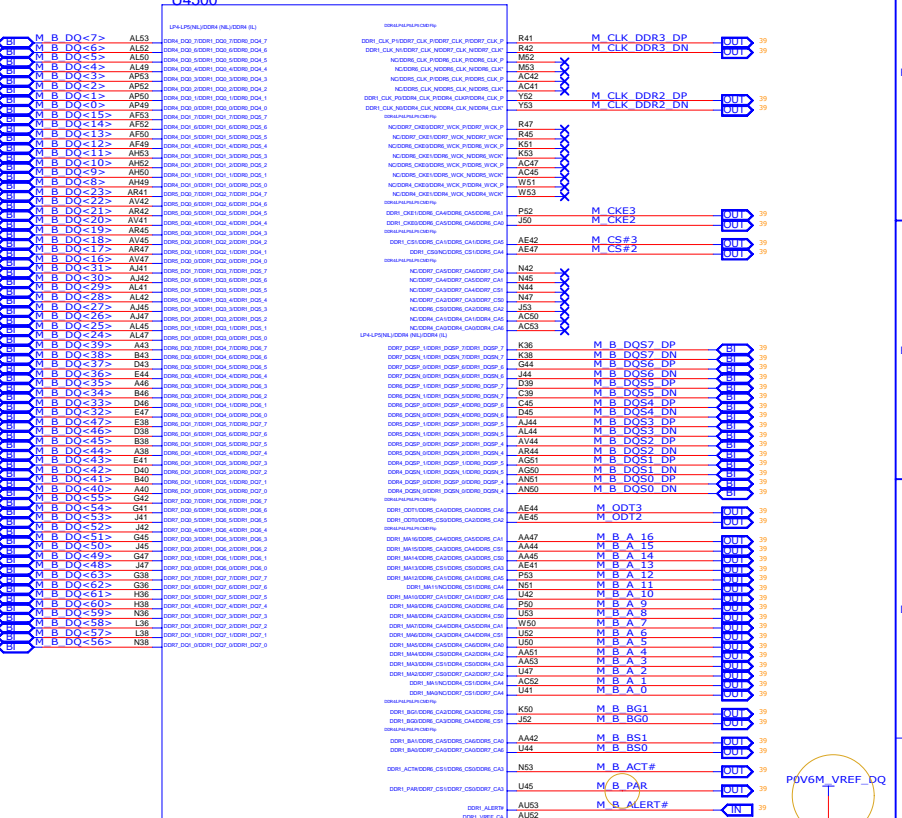
THERMAL & FAN

SIZE A3 CODE CS DOC NUMBER 1310xxxxx-0-0 REV X01

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CHANGE by XENG> DATE 21-OCT-2002
PCB P/N 60xxxxxxx PCB VER XVER>

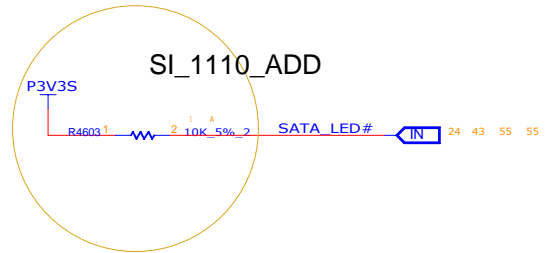
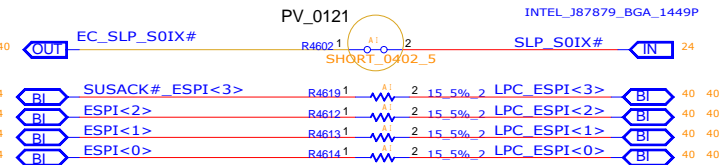
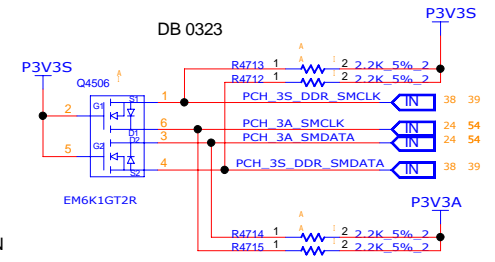
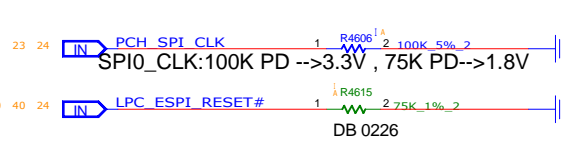
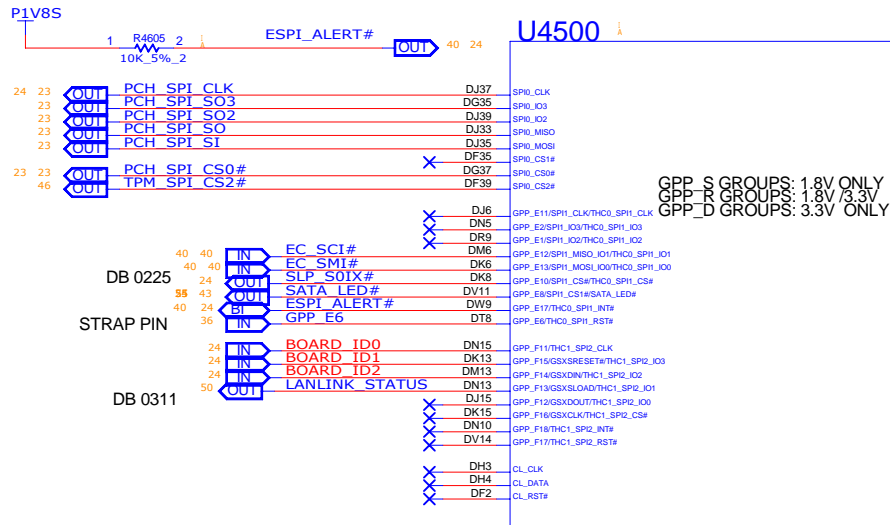
U4500



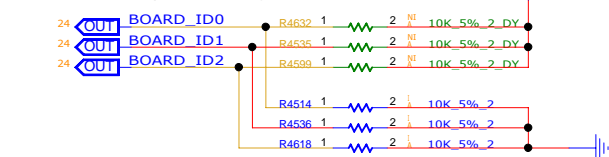
CHANGE BY	XXX	DATE		SIZE	C	CODE	CS	DOC NUMBER	1310xxxxx-0-0	REV	X01
PCB P/N	60xxxxxxx	PCB VER	1	SHEET				of	22		77

REV
X01

MCP-GPIO1/LPC/SPI



Reserve (no use)



BOARD_ID0	RESERVED	RESERVED
R4632	MOUNT	OPEN
R4514	OPEN	MOUNT
	3V	0V
BOARD_ID1	I3 CPU	I5 & I7 CPU
R4535	MOUNT	OPEN
R4536	OPEN	MOUNT
	3V	0V
BOARD_ID2	RESERVED	RESERVED
R4599	MOUNT	OPEN
R4618	OPEN	MOUNT
	3V	0V

DB 1012 UPDATE

REFERENCE:4500~4949

SCI / SMI# and NMI

SCI capability is available on all GPIOs, while SMI and NMI capability is available on only select GPIOs.

Below are the PCH GPIOs that can be routed to generate SMI# or NMI:

- GPP_B14, GPP_B20, GPP_B23
- GPP_C[23:22]
- GPP_D[4:0]
- GPP_E[8:0], GPP_E[16:13]

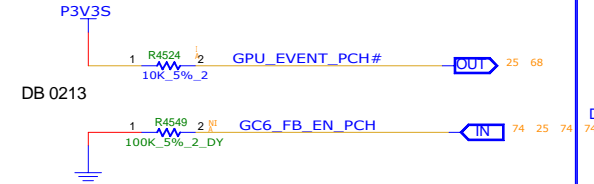
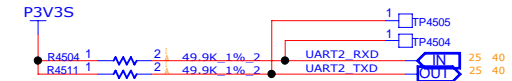
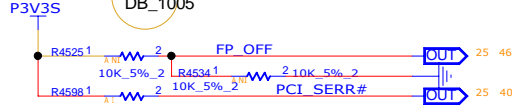
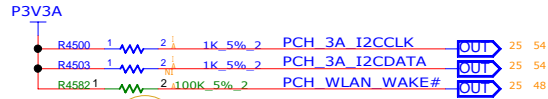
INVENTEC

TITLE			
MODEL,PROJECT,FUNCTION			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxxx-0-0	X01
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CHANGE by	XENG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxx	PCB VER	XVER>

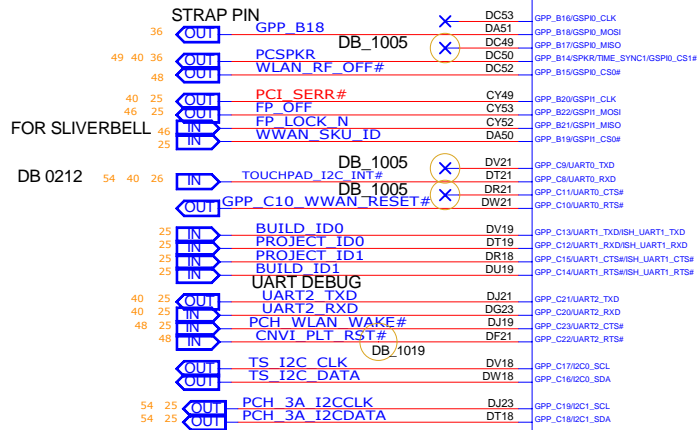
MCP-GPIO2/I2C/UART

REFERENCE:4500~4949

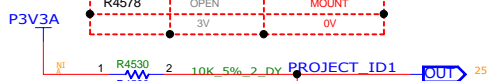
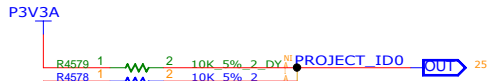
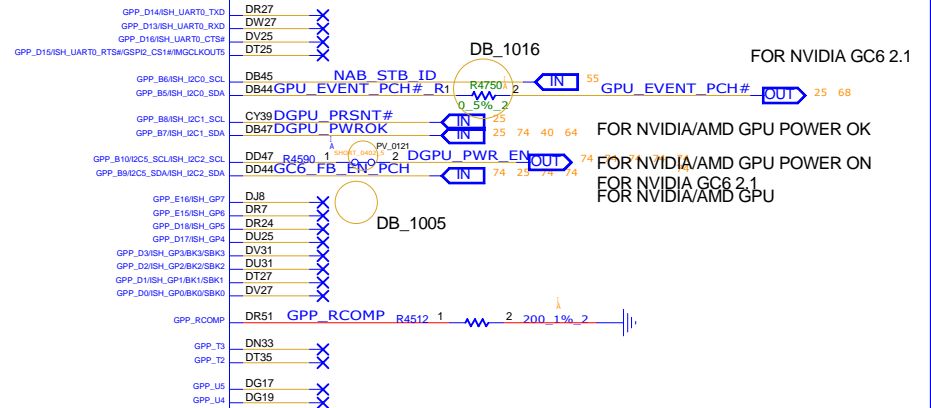


- GPP_B14, GPP_B20, GPP_B23
- GPP_C[23:22]
- GPP_D[4:0]
- GPP_E[8:0], GPP_E[16:13]

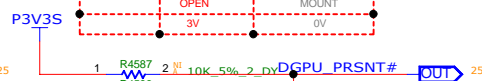
U4500



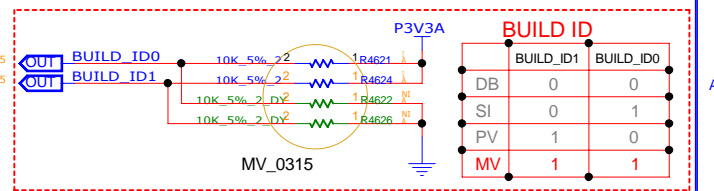
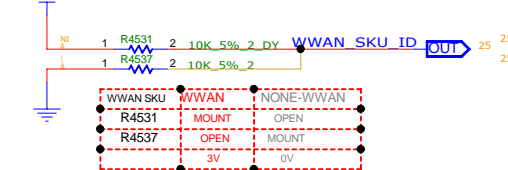
GPP_S GROUPS: 1.8V ONLY
GPP_T GROUPS: 1.8V/3.3V
GPP_D GROUPS: 3.3V ONLY



DB_1019_DELETE



6025B0422101 INTEL_I87879_BGA_1449P



INVENTEC

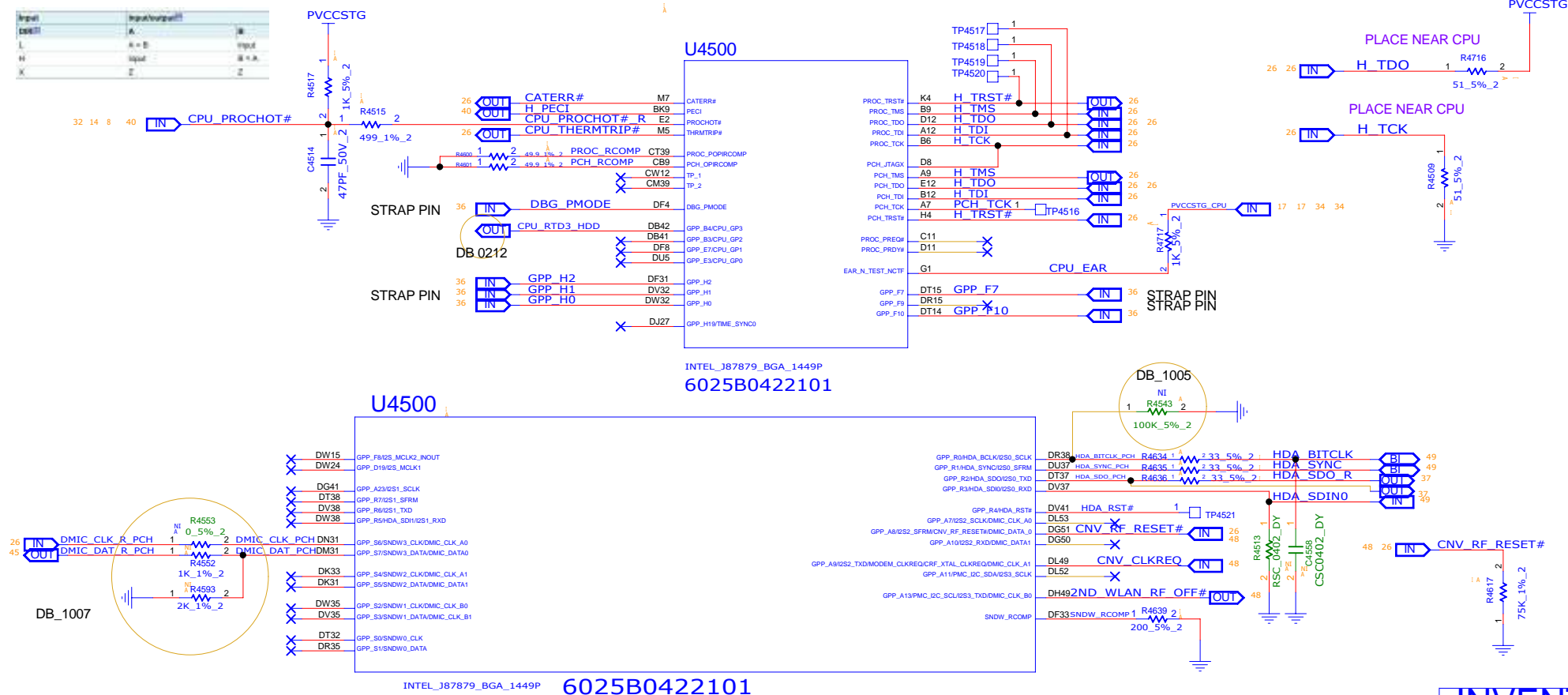
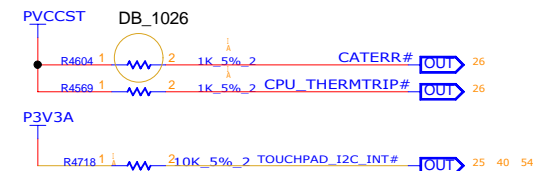
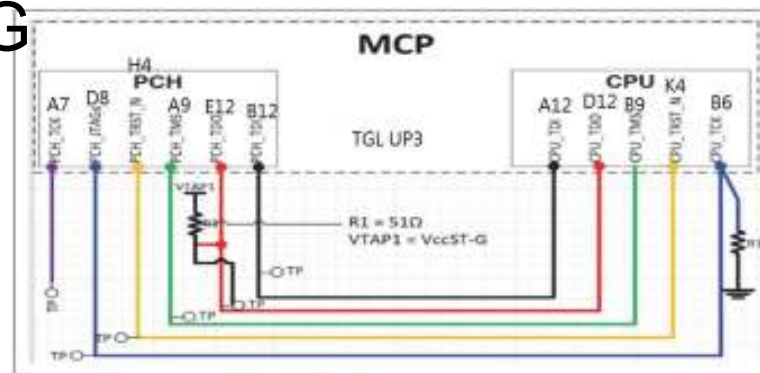
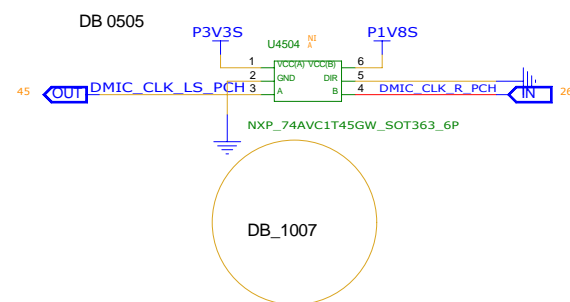
CHANGE by	XENG>	DATE	21-OCT-2002
PCB PIN	60xxxxxxx	PCB VER	XVER>

TITLE MODEL,PROJECT,FUNCTION

SIZE A3 CODE CS DOC NUMBER 1310xxxx-0-0 REV X01

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MCP-MISC/HDA/JTAG

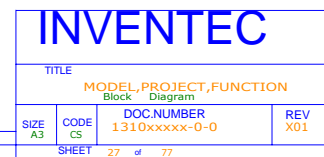


INVENTEC

REFERENCE:4500~4949

CHANGE by	XXX	DATE	21-OCT-2002	SIZE A3	CODE CS	1310xxxxx-0-0	X01
PCB P/N	60xxxxxxxxxx	PCB VER	XXX	SHEET 26 of 77			

REFERENCE:4500~4949



MCP-PCIE/USB3/USB2

Table 72. PCH PCIe* Configuration Lane Reversal Mapping

PCIe* Configuration	PCI Express* Lanes				PCI Express* Down Device or Connector Lanes
	PCIe* Controller #1	PCIe* Controller #2 PCH-LP (UP3)	PCIe* Controller #3 PCH-LP (UP4)	PCIe* Controller #3	
1x4	1	5	Not Available	9	3
	2	4	Not Available	10	2
	3	7	Not Available	11	1
	4	8	Not Available	12	0

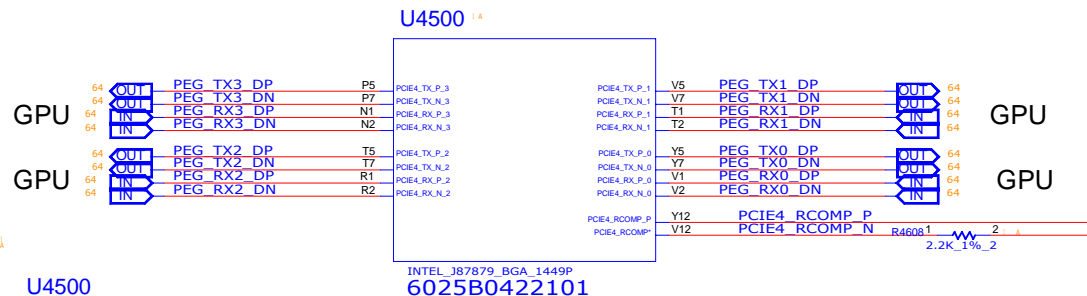
PORT# TABLE

M2.SSD	PCIE	PCIE4
0	12	0
1	11	1
2	10	2
3	9	3

DOC:575683

PCI Express* Support

The TGL UP4/UP3 processor PCI Express* interface is a 4-lane (x4) port. The interconnect between the TGL UP4/UP3 processor and NVMe* storage provided through the M.2 connector. In addition, it will support graphics PCIe Gen4 devices too.



SATA FOR HDD

SATA FOR SSD

SL1126_MODIFY

LAN

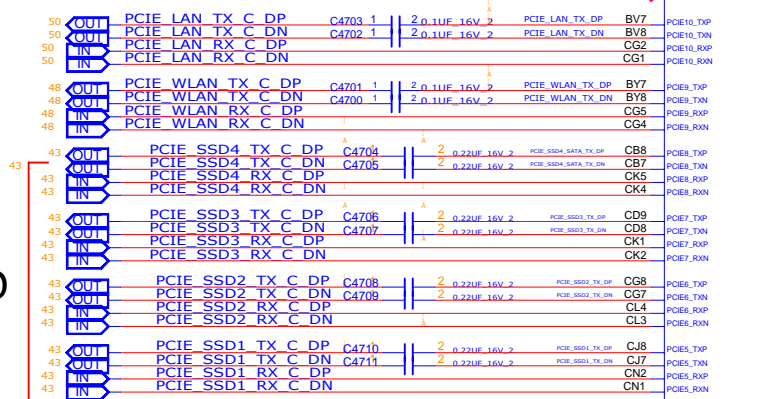
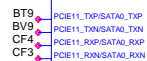
WLAN

SSD

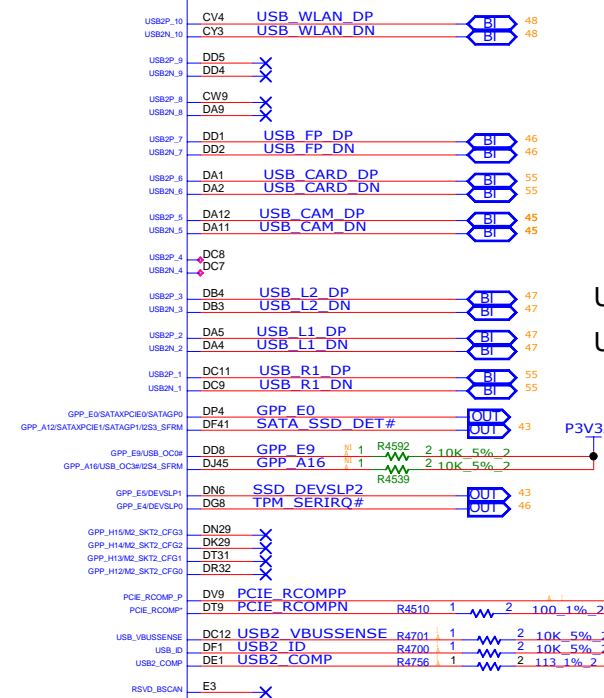
USB3.0 PORT R1

USB3.0 PORT L2

USB3.0 PORT L1



INTEL J87879_BGA_1449P
6025B0422101



BLUETOOTH

17 FOR ODD / 14 FOR FP

CARD READER

WEBCAM

USB2.0 PORT L2 MB

USB2.0 PORT L1 MB

USB2.0 PORT R1 DB



INVENTEC

TITLE
MODEL,PROJECT,FUNCTION
Block

SIZE
A3

CODE
CS

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X01

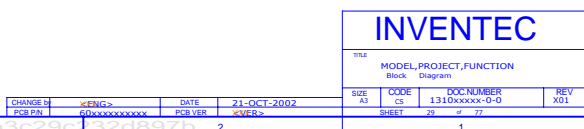
CHANGE by
PCB PN

DATE
PCB VER

21-OCT-2002
XVER>

REFERENCE:4500~4949

REFERENCE:4500~4949



MCP-DDI/TCP

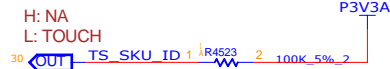
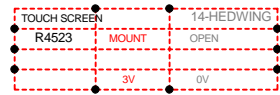
5.3

Display Interfaces

Table 35.

DDI Ports Availability

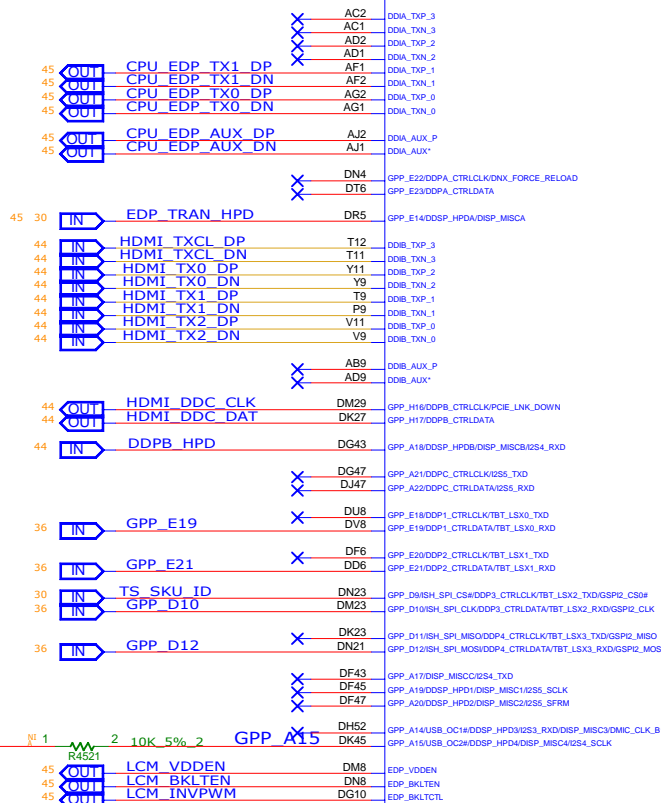
SKU	UP4 Processor Line Quad Core GT2	UP3 Processor Line Quad Core GT2
DDI A	eDP*/MIPI_0	eDP*/MIPI_0
DDI B	DP*/HDMI*/MIPI_1	DP*/HDMI*
TCP0	DP*/HDMI*	DP*/HDMI*



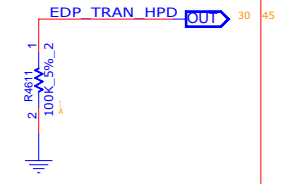
U4500

EDP

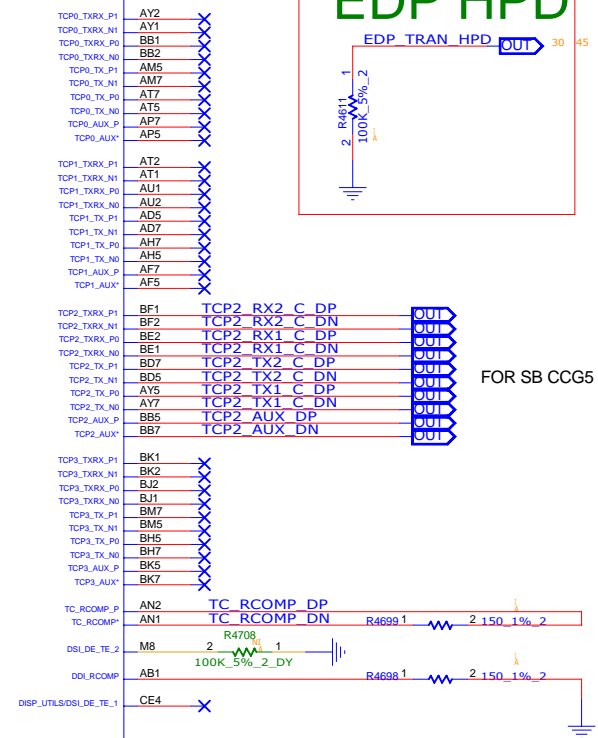
HDMI



EDP HPD



FOR SB CCG5



INTEL_J87879_BGA_1449P

6025B0422101

REFERENCE:4500~4949

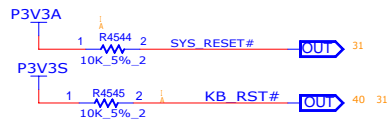
INVENTEC

CHANGE by	XENG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxx	PCB VER	XVER>

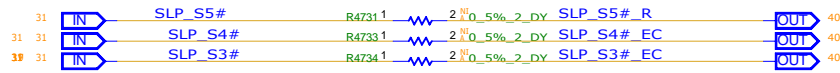
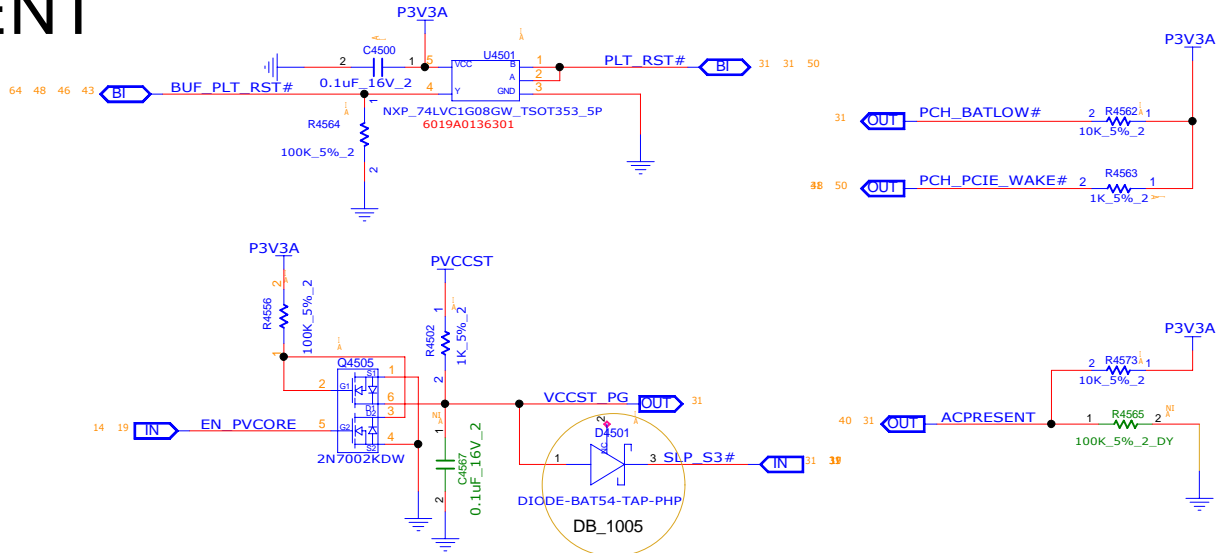
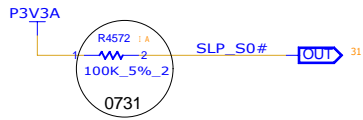
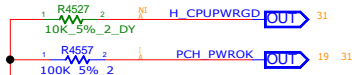
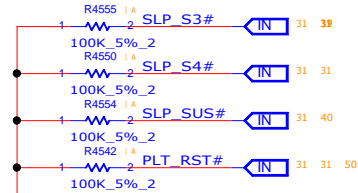
TITLE			
MODEL,PROJECT,FUNCTION			
Block Diagram			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxxx-0-0	X01
SHEET		30	of 77

MCP-POWER MANAGEMENT

08/13

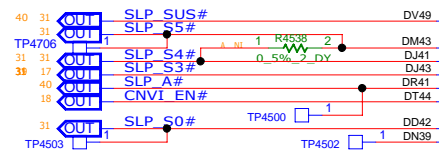


DG #607872
TABLE 102

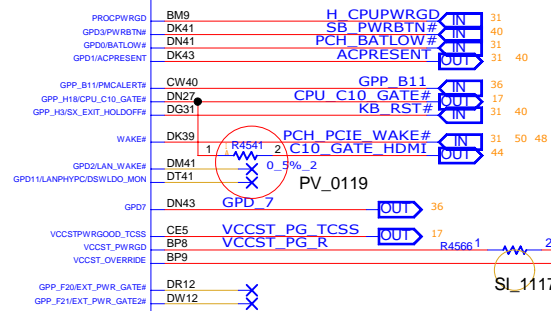


DB_1016 DELETE

U4500



INTEL_J87879_BGA_1449P
6025B0422101



SL_1117

DIODE-BAT54-TAP-PHP_DY
DB_1005

INVENTEC

TITLE			
MODEL,PROJECT,FUNCTION			
Block Diagram			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxxx-0-0	X01
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CHANGE by	XENG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxx	PCB VER	XVER>

REFERENCE:4500~4949

VCCIN: 47A
VCCIN_AUX: 27A
VCCSTG: 0.3A
VCCST: 0.5A
VDD2_CPU: 3.25A
VCCPRIM_3P3: 0.202A
VCCDSW_3P3: 0.003A
VCCPRIM_1P8: 1.3A
VCCRTC: 0.005A
VCCA_CLKLDO 1P8: 0.165A

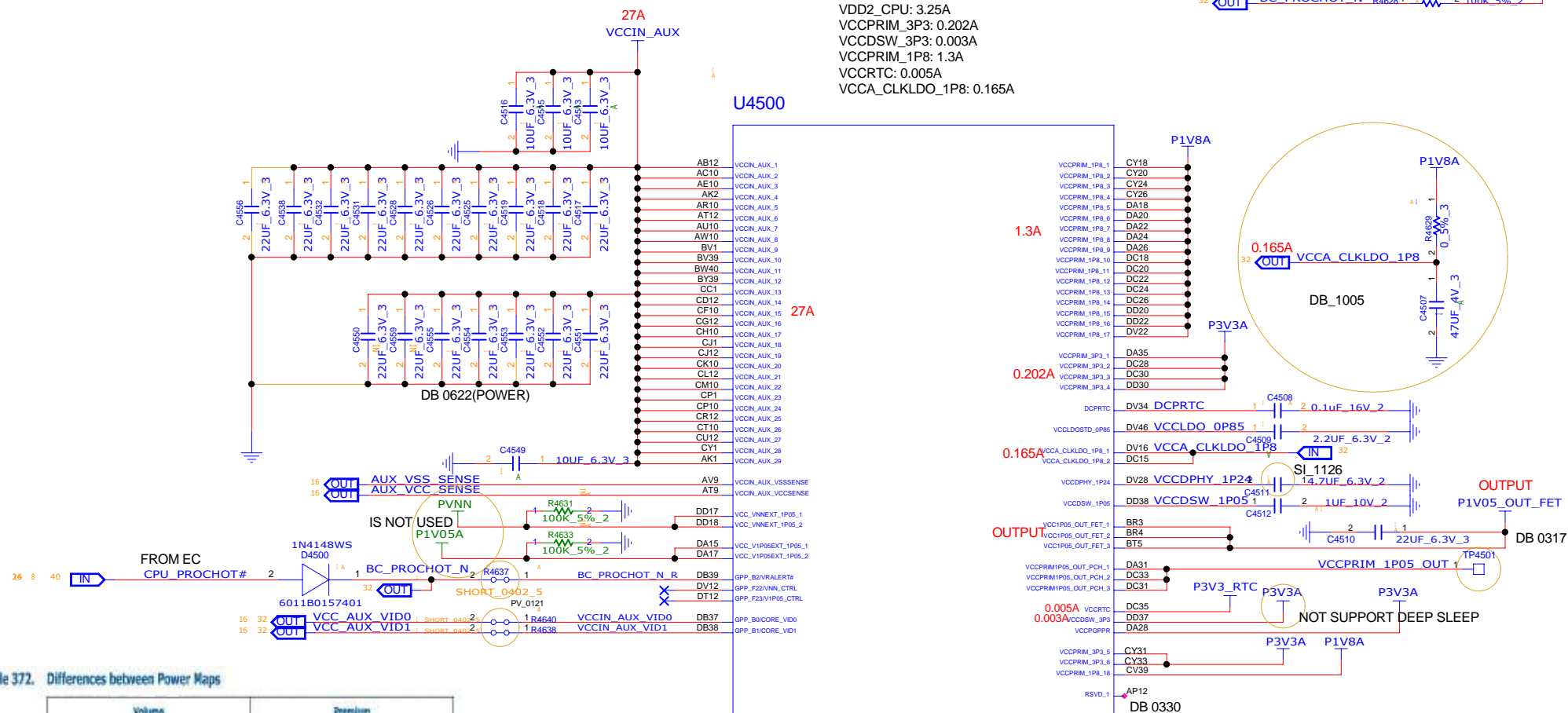


Table 372. Differences between Power Maps

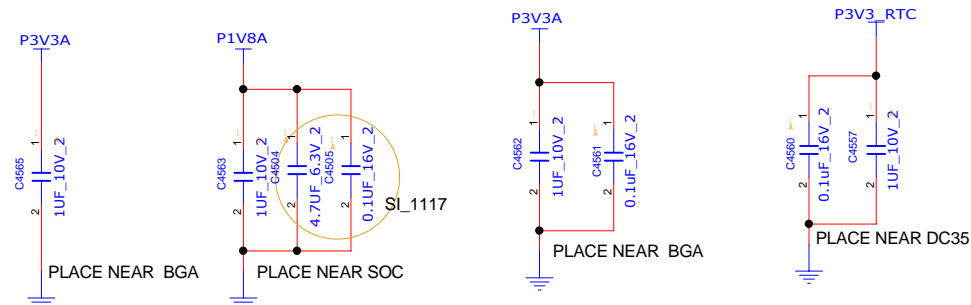
Volume	Premium
YesSTG gated by SLP_S3#	YesSTG gated by (CPU_CIO_GATE#)
VCC_VINNEXT_1P05 is not used	VCC_VINNEXT_1P05 is supplied by small dedicated VIN VR to bypass PCH F1VR during light load
VCC_VIPOSEXT_1P05 is not used	VCC_VIPOSEXT_1P05 is supplied by small dedicated V1_05A VR to bypass PCH F1VR during light load
Various system devices share load switches	Various system devices have their own independent load switches

Note:

1. VCC_VINNEXT_1P05 is also known as VIN BYP
2. VCC_VIPOSEXT_1P05 is also known as VIPO5 BYP
3. Other changes may be present. Refer to the Power Map for details.

INTEL_J87879_BGA_1449P

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INVENTEC

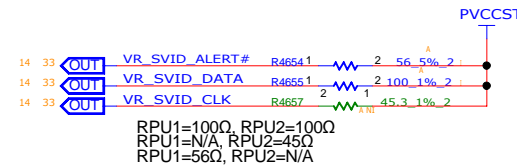
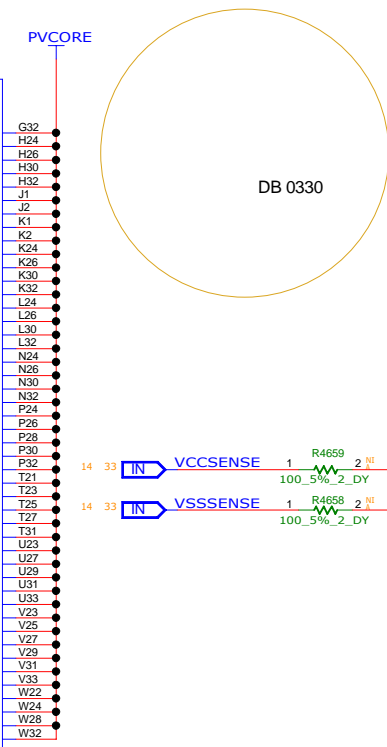
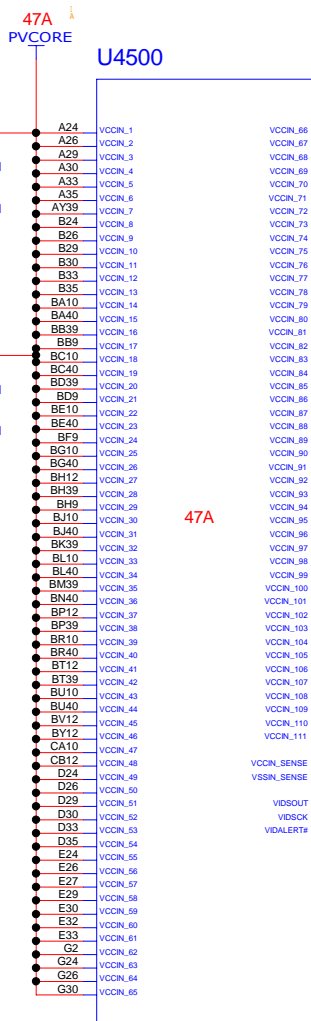
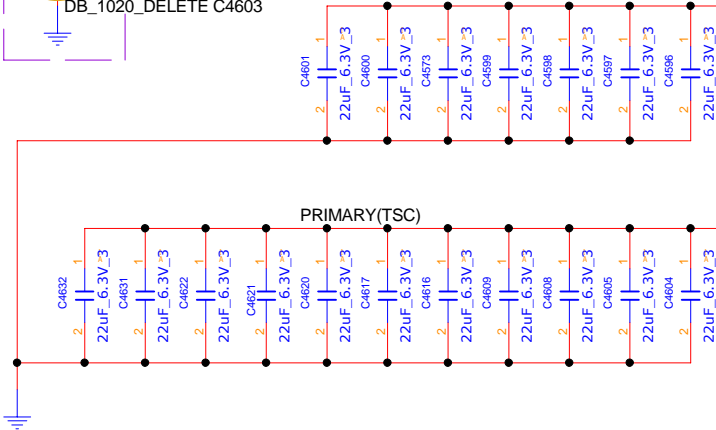
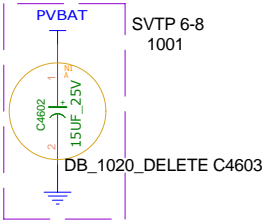
TITLE

MODEL, PROJECT, FUNCTION
Block Diagram

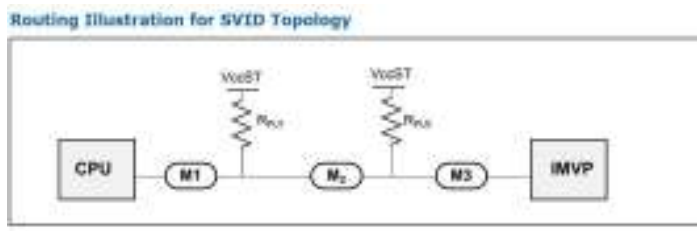
SIZE	CODE	DOC.NUMBER	
		1318-00000-00	

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MCP-POWER2



INTEL_J87879_BGA_1449P
6025B0422101



SVID Signals	VDDOUT, VDDCK, VDDALERT#
VDDOUT platform resistors	Rpu1=1000, Rpu2=1000
VDDCK platform resistors	Rpu1=Empty, Rpu2=100
VDDALERT# platform resistors	Rpu1=560, Rpu2=Empty

INVENTEC

TITLE

MODEL,PROJECT,FUNCTION

DOC NUMBER

1310xxxxx-0-0

REV

X01

SIZE

A3

CODE

CS

SHEET

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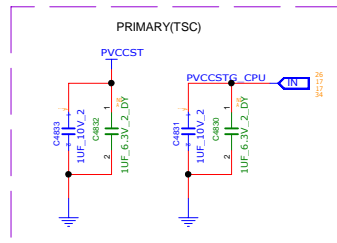
of

77

REFERENCE:4500~4949

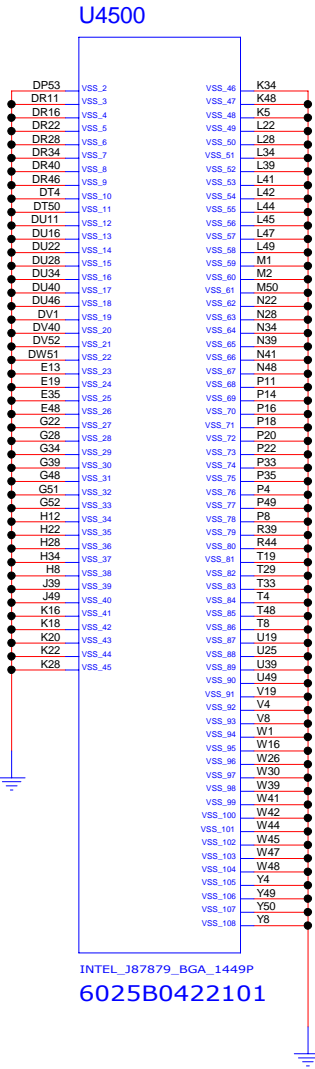
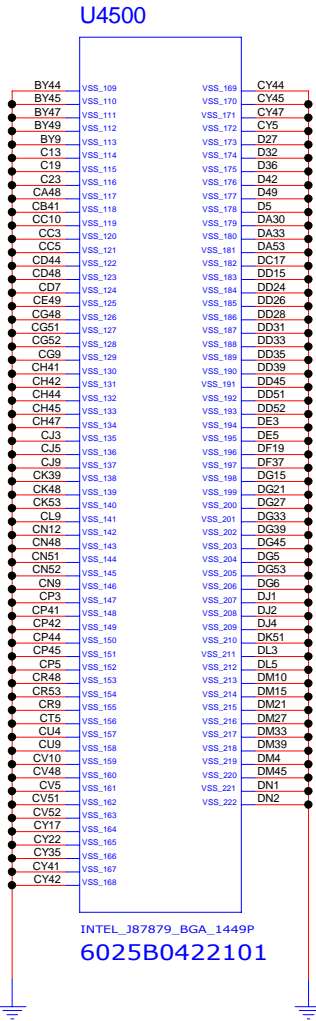
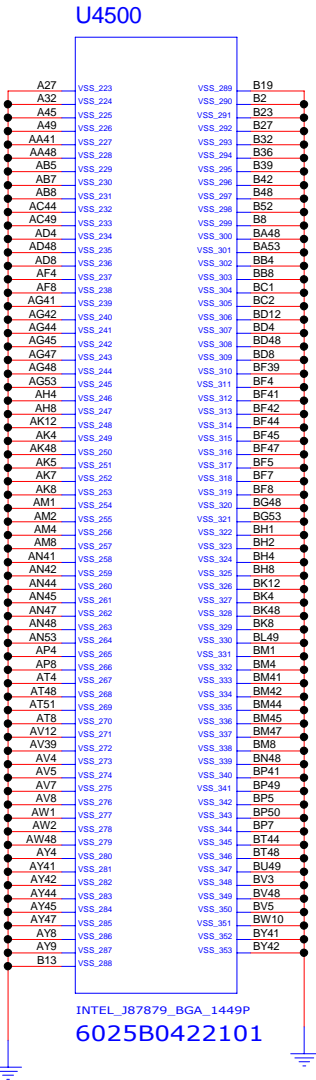
CHANGE by	X&ENG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxx	PCB VER	X&VER>

REFERENCE:4500~4949



INVENTEC			
TITLE			
MODEL,PROJECT,FUNCTION Block Diagram			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310XXXXXX-0-0	X01
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MCP-GND

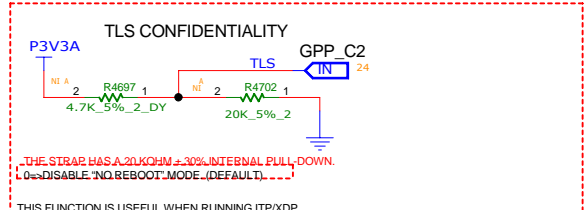
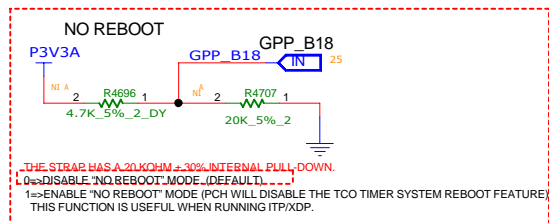
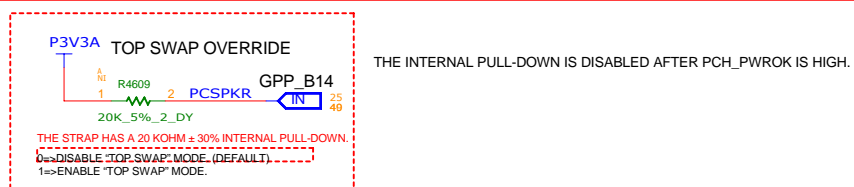


REFERENCE:4500~4949

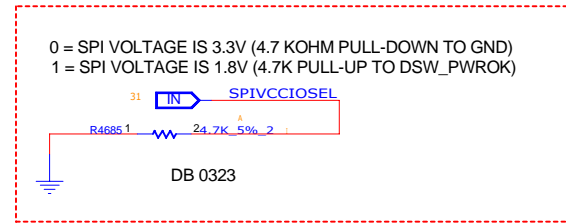
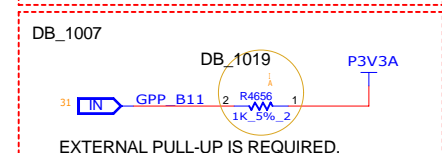
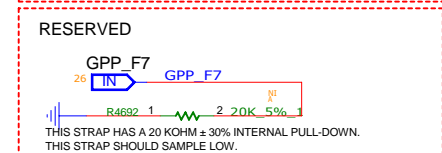
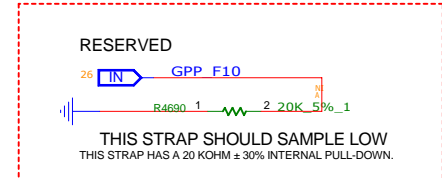
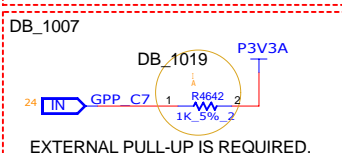
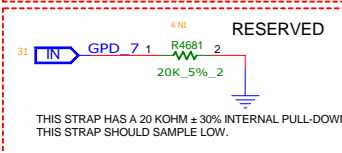
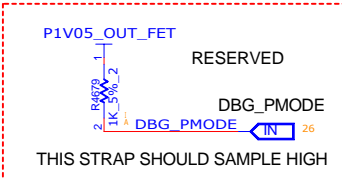
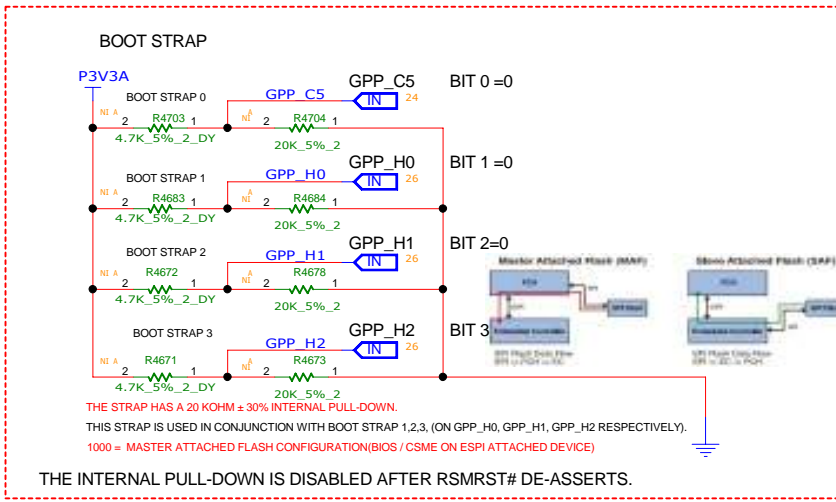
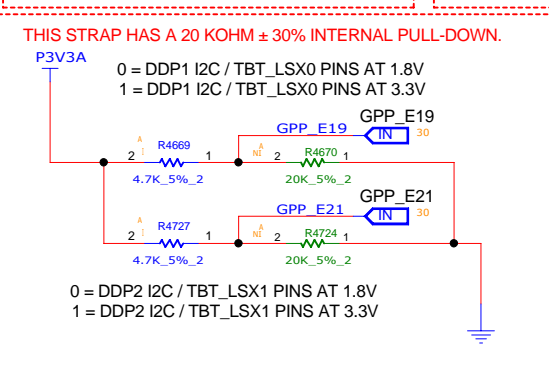
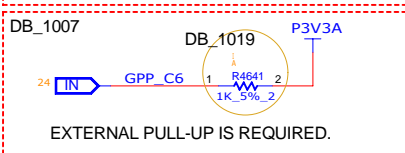
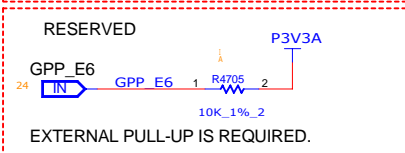
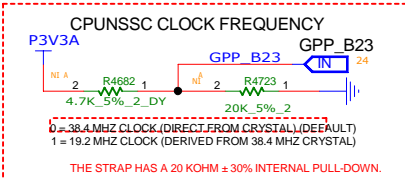
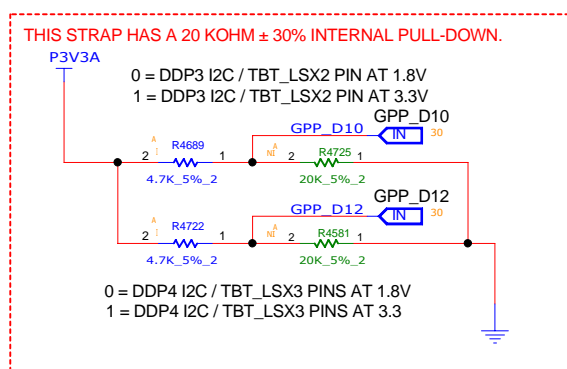
INVENTEC				
TITLE				
MODEL,PROJECT,FUNCTION				
Block Diagram				
SIZE	CODE	DOC NUMBER	REV	
A3	CS	1310xxxxx-0-0	X01	
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CHANGE by	DATE	21-OCT-2002
PCB P/N	PCB VER	

#576591 PIN STRAP



Signal	Usage	Where Sourced	Comments
SPIC_I2C	Reserved	Using edge of SPICSTR	External pull-up is required. Recommended 10K if pulled up to 3.3V or 75K if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on-board devices driving it to opposite direction during strap sampling.
SPIC_I2C	Reserved	Using edge of SPICSTR	External pull-up is required. Recommended 10K if pulled up to 3.3V or 75K if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on-board devices driving it to opposite direction during strap sampling.
SPIC_I2C	Reserved	Using edge of SPICSTR	External pull-up is required. Recommended 10K if pulled up to 3.3V or 75K if pulled up to 1.8V. This strap should sample HIGH. There should NOT be any on-board devices driving it to opposite direction during strap sampling.

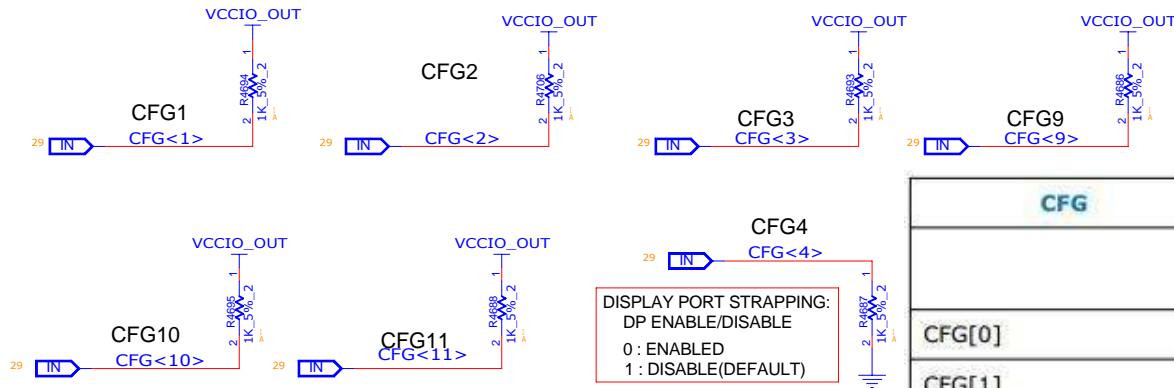


INVENTEC			
TITLE			
MODEL,PROJECT,FUNCTION			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxxx-0-0	X01
SHEET		36 of 77	

CHANGE by	XXX	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxx	PCB VER	XXX

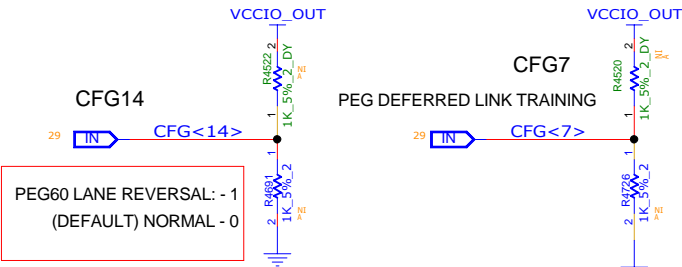
MCP-STRAPS-1

607872 TABLE62



DISPLAY PORT STRAPPING:
DP ENABLE/DISABLE
0 : ENABLED
1 : DISABLE(DEFAULT)

FOR CPU-PCIE4 PORT PEG TO GPU

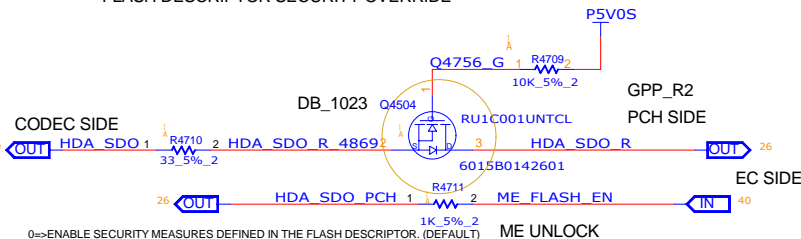


PEG60 LANE REVERSAL: - 1
(DEFAULT) NORMAL - 0

CFG	Description	Termination	Resistor
	Operation; No stall. - 0 = Stall		
CFG[0]	RSVD	None	
CFG[1]	RSVD	Pull-up to VCCIO	1K ohm
CFG[2]	RSVD	Pull-up to VCCIO	1K ohm
CFG[3]	RSVD	Pull-up to VCCIO	1K ohm
CFG[4]	eDP enable Strap: - 1 = Disabled. - 0 = Enabled.	Pull-up to VCCIO / Pull-down- Platform design dependent	1K ohm
CFG[6:5]	RSVD	None	
CFG[7]	PEG deferred link training	Pull-up to VCCIO / Pull-down- Platform design dependent	1K ohm
CFG[8]	RSVD	None	
CFG[11:9]	RSVD	Pull-up to VCCIO	1K ohm
CFG[13:12]	RSVD	None	
CFG[14]	PEG60 Lane Reversal: - 1 - (Default) Normal - 0 - Reversed	Pull-up to VCCIO / Pull-down- Platform design dependent	1K ohm
CFG[1 7:15]	RSVD	None	

ME UNLOCK FLASH

FLASH DESCRIPTOR SECURITY OVERRIDE



0==>ENABLE SECURITY MEASURES DEFINED IN THE FLASH DESCRIPTOR. (DEFAULT)
1==>DISABLE FLASH DESCRIPTOR SECURITY (OVERRIDE).
THIS STRAP SHOULD ONLY BE ASSERTED HIGH USING EXTERNAL PULL-UP IN MANUFACTURING/DEBUG ENVIRONMENTS ONLY.

INVENTEC

TITLE
MODEL,PROJECT,FUNCTION
Block Diagram
SIZE A3
CODE CS
DOC NUMBER 1310xxxx-0-0
REV X01
SHEET 37 of 77

CHANGE by XXX
PCB P/N 60xxxxxxxxxxx
DATE 21-OCT-2002
PCB VER XXX



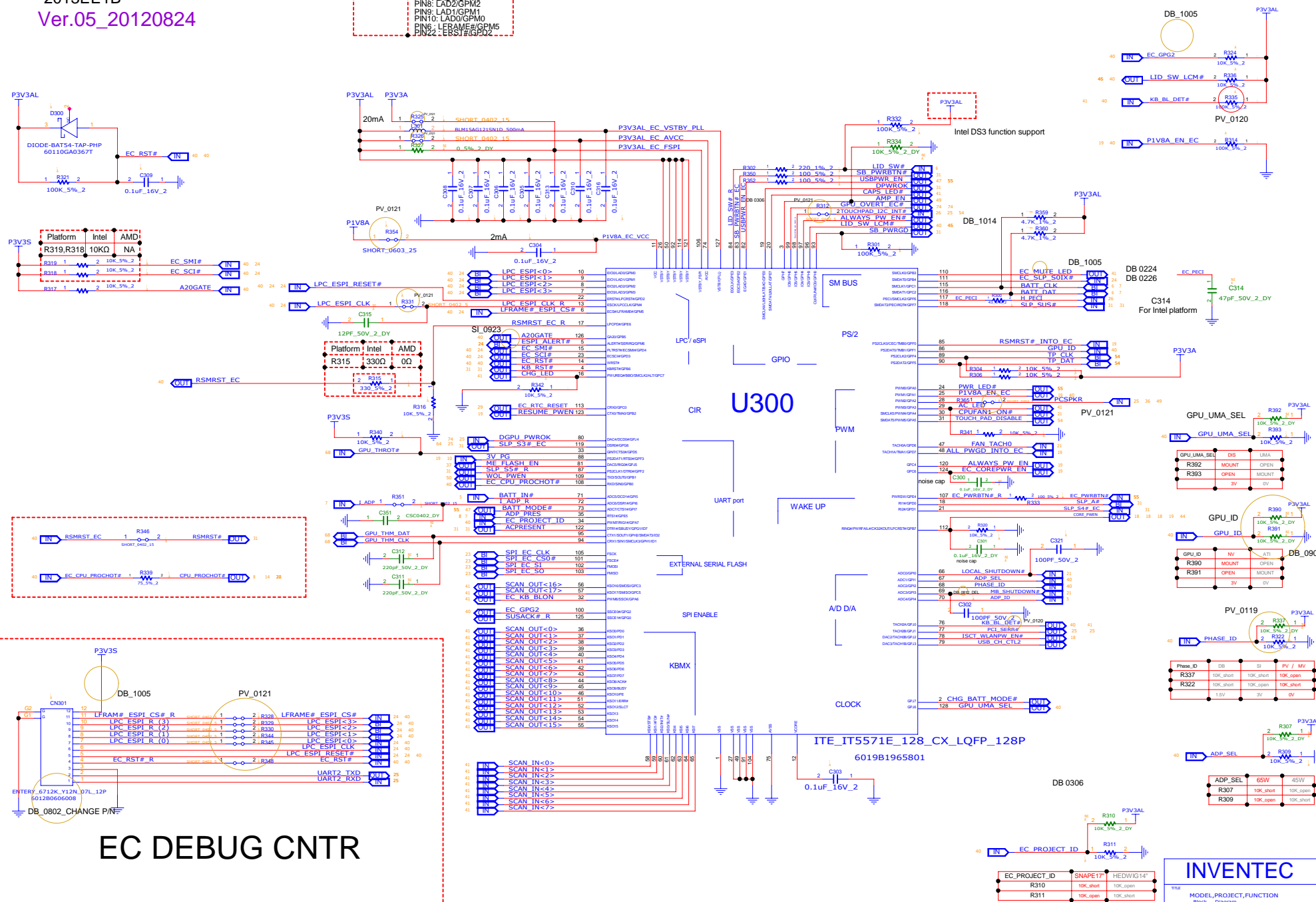
EVENT N:ON ECC DIMM:KEEP A PULL UP IF NO PIN IN PCH



INVENTEC

TITLE		MODEL,PROJECT,FUNCTION	
		Block	Diagram
SIZE A3	CODE CS	DOC. NUMBER 1310xxxxx-0-0	
SHEET		30	33

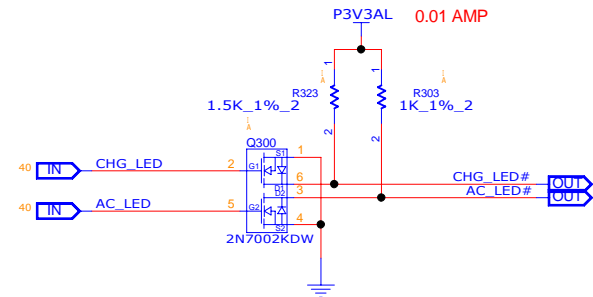
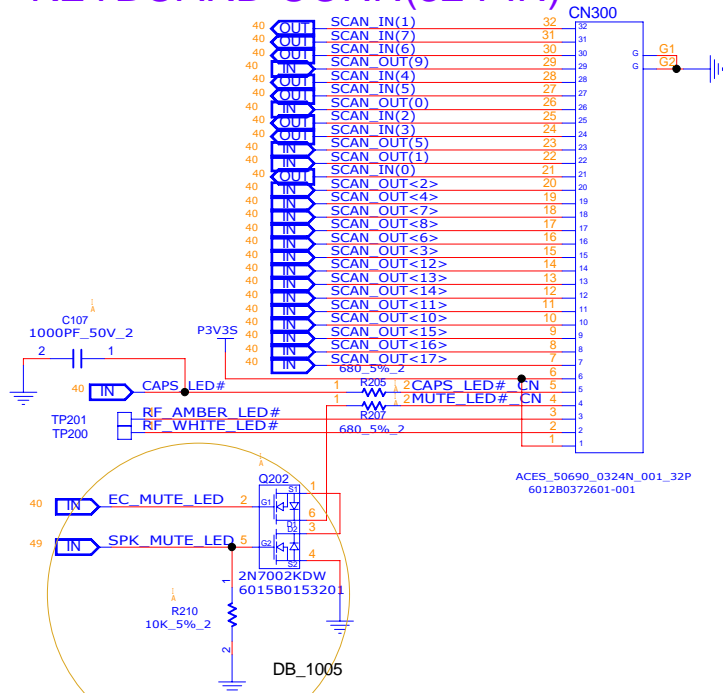
Location 300 ~ 389
2013EE1B
Ver.05_20120824



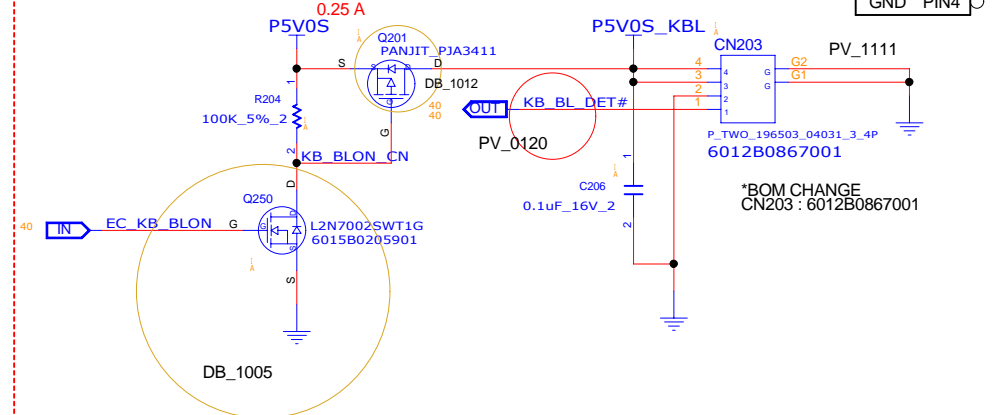
INVENTEC

TITLE	MODEL, PROJECT, FUNCTION
Block Diagram	

VER.07_20171110



KEYBOARD BACKLIGHT

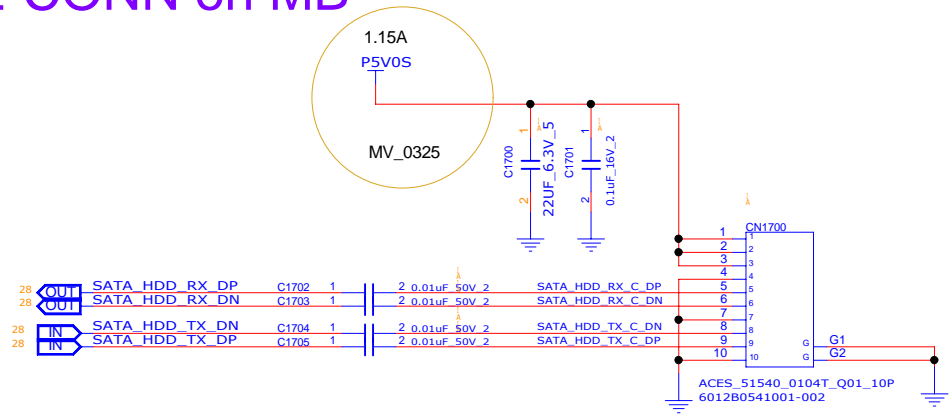


TITLE	MODEL,PROJECT,FUNCTION
	KB CONN & LED

CHANGE by	XENG>	DATE	21-OCT-2002	SIZE	A3	CODE	CS	1310xxxxx-0-0	X01
PCB P/N	60xxxxxxxxxx	PCB VER	XVER>	SHEET	41	of	77		

SATA HDD CABLE CONN on MB

VER.01_20170918



INVENTEC

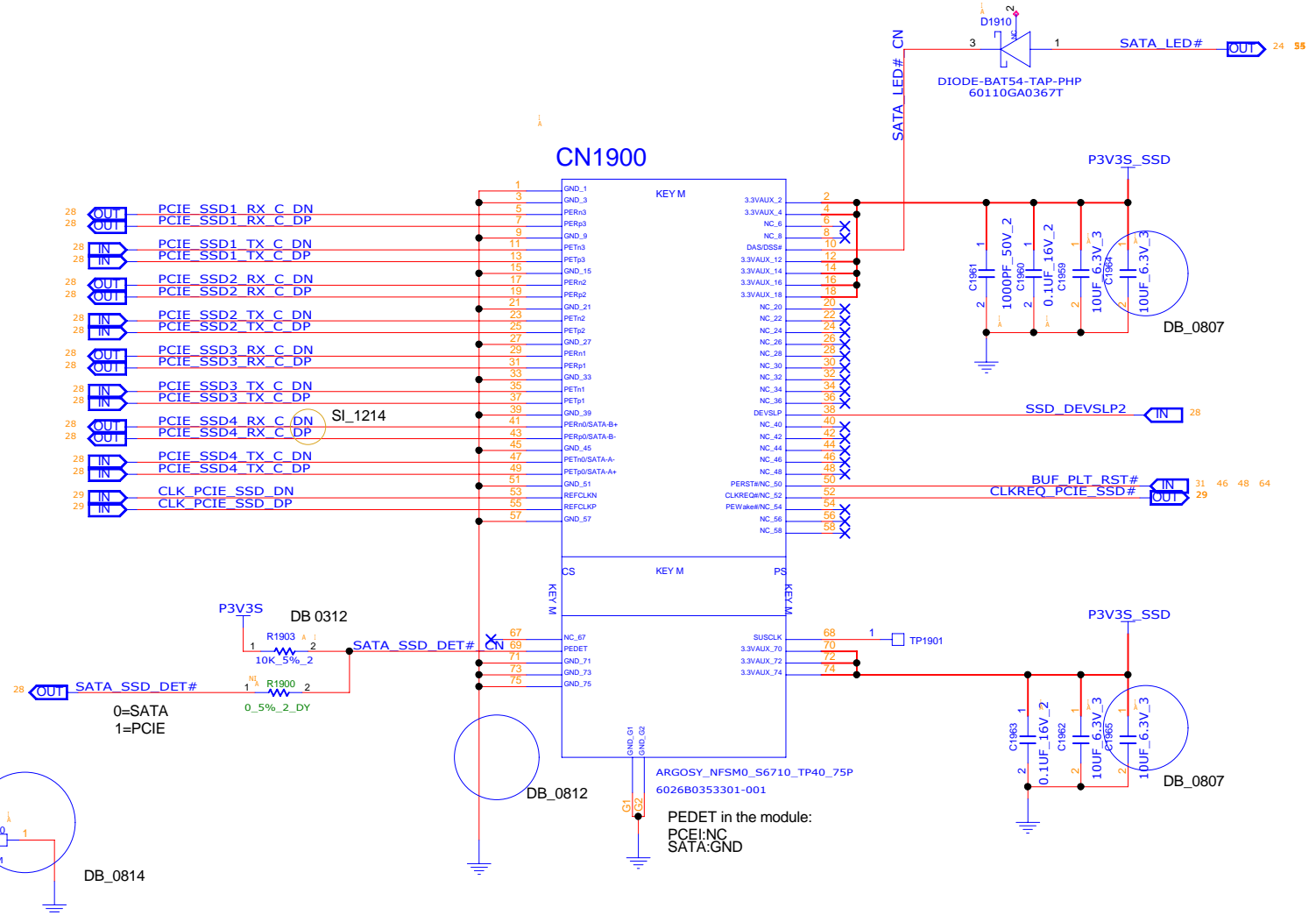
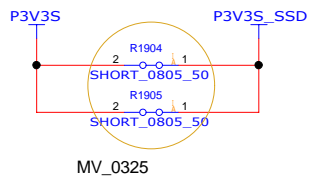
TITLE
MODEL,PROJECT,FUNCTION
SATA HDD S. SATA HDD

SIZE A3 CODE CS DOC NUMBER 1310xxxxx-0-0 REV X01

CHANGE by XXX DATE PCB VER. 2002

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VER.03_20171004



INVENTEC

TITLE	MODEL,PROJECT,FUNCTION
1.1	1.1.1
1.2	1.2.1
1.3	1.3.1
1.4	1.4.1
1.5	1.5.1
1.6	1.6.1
1.7	1.7.1
1.8	1.8.1
1.9	1.9.1
1.10	1.10.1
1.11	1.11.1
1.12	1.12.1
1.13	1.13.1
1.14	1.14.1
1.15	1.15.1
1.16	1.16.1
1.17	1.17.1
1.18	1.18.1
1.19	1.19.1
1.20	1.20.1
1.21	1.21.1
1.22	1.22.1
1.23	1.23.1
1.24	1.24.1
1.25	1.25.1
1.26	1.26.1
1.27	1.27.1
1.28	1.28.1
1.29	1.29.1
1.30	1.30.1
1.31	1.31.1
1.32	1.32.1
1.33	1.33.1
1.34	1.34.1
1.35	1.35.1
1.36	1.36.1
1.37	1.37.1
1.38	1.38.1
1.39	1.39.1
1.40	1.40.1
1.41	1.41.1
1.42	1.42.1
1.43	1.43.1
1.44	1.44.1
1.45	1.45.1
1.46	1.46.1
1.47	1.47.1
1.48	1.48.1
1.49	1.49.1
1.50	1.50.1
1.51	1.51.1
1.52	1.52.1
1.53	1.53.1
1.54	1.54.1
1.55	1.55.1
1.56	1.56.1
1.57	1.57.1
1.58	1.58.1
1.59	1.59.1
1.60	1.60.1
1.61	1.61.1
1.62	1.62.1
1.63	1.63.1
1.64	1.64.1
1.65	1.65.1
1.66	1.66.1
1.67	1.67.1
1.68	1.68.1
1.69	1.69.1
1.70	1.70.1
1.71	1.71.1
1.72	1.72.1
1.73	1.73.1
1.74	1.74.1
1.75	1.75.1
1.76	1.76.1
1.77	1.77.1
1.78	1.78.1
1.79	1.79.1
1.80	1.80.1
1.81	1.81.1
1.82	1.82.1
1.83	1.83.1
1.84	1.84.1
1.85	1.85.1
1.86	1.86.1
1.87	1.87.1
1.88	1.88.1
1.89	1.89.1
1.90	1.90.1
1.91	1.91.1
1.92	1.92.1
1.93	1.93.1
1.94	1.94.1
1.95	1.95.1
1.96	1.96.1
1.97	1.97.1
1.98	1.98.1
1.99	1.99.1
2.00	2.00.1
2.01	2.01.1
2.02	2.02.1
2.03	2.03.1
2.04	2.04.1
2.05	2.05.1
2.06	2.06.1
2.07	2.07.1
2.08	2.08.1
2.09	2.09.1
2.10	2.10.1
2.11	2.11.1
2.12	2.12.1
2.13	2.13.1
2.14	2.14.1
2.15	2.15.1
2.16	2.16.1
2.17	2.17.1
2.18	2.18.1
2.19	2.19.1
2.20	2.20.1
2.21	2.21.1
2.22	2.22.1
2.23	2.23.1
2.24	2.24.1
2.25	2.25.1
2.26	2.26.1
2.27	2.27.1
2.28	2.28.1
2.29	2.29.1
2.30	2.30.1
2.31	2.31.1
2.32	2.32.1
2.33	2.33.1
2.34	2.34.1
2.35	2.35.1
2.36	2.36.1
2.37	2.37.1
2.38	2.38.1
2.39	2.39.1
2.40	2.40.1
2.41	

SIZE A3	CODE CS	DOC.NUMBER 1310xxxxx-0-0	REV X01
SHEET of 43 77			

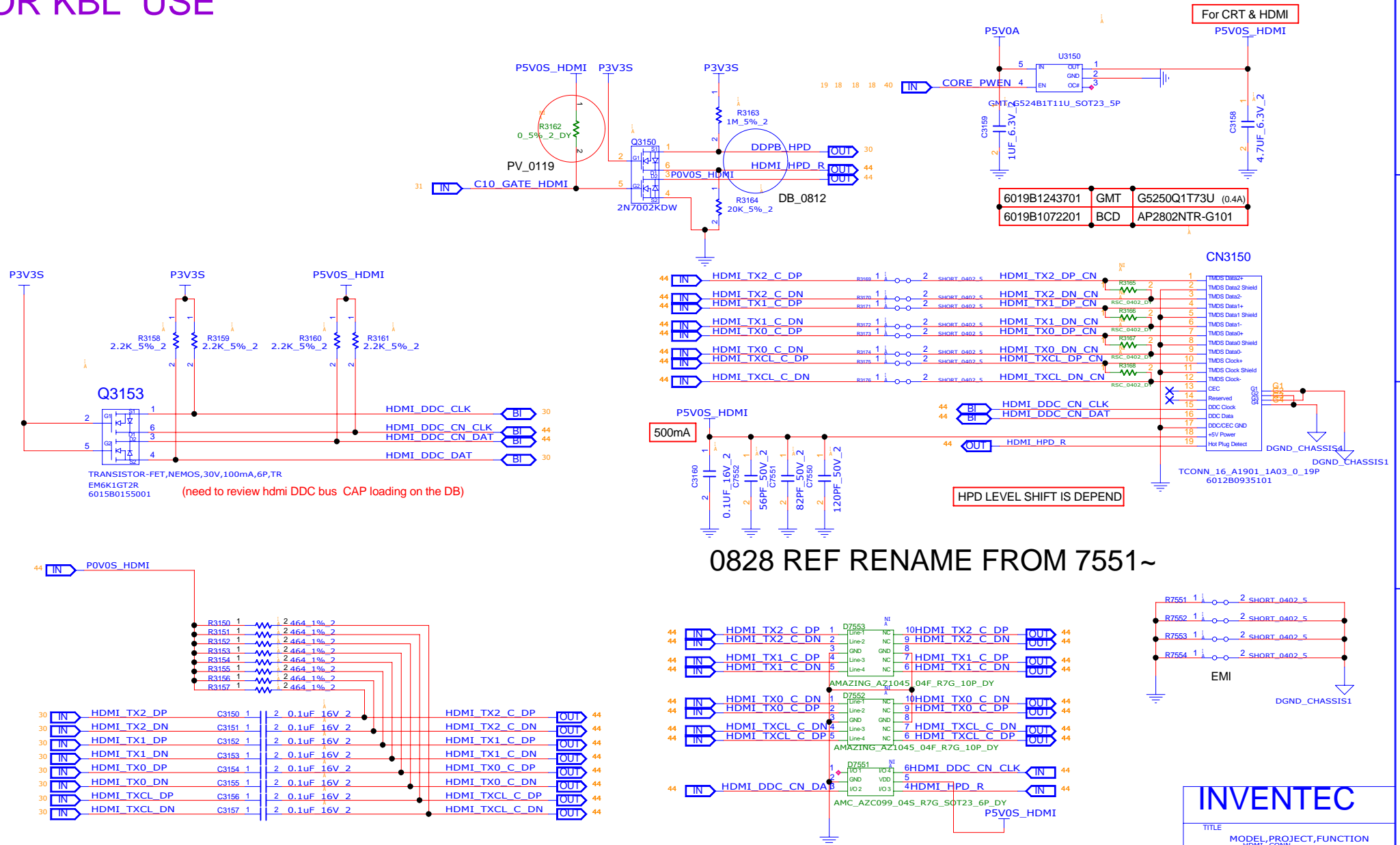
CHANGE by	XENIG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxxx	PCB VER	XVER>

HDMI

Location 3150 ~ 3199

VER.08_20171115-2

FOR KBL USE



0828 REF RENAME FROM 7551~

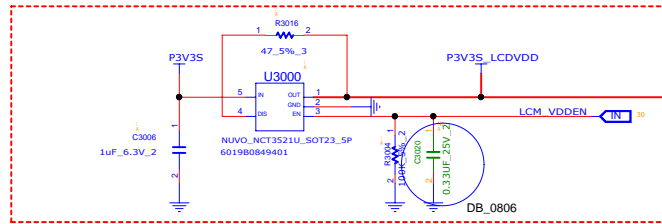
INVENTEC

CHANGE by	XENG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxx	PCB VER	XVER>

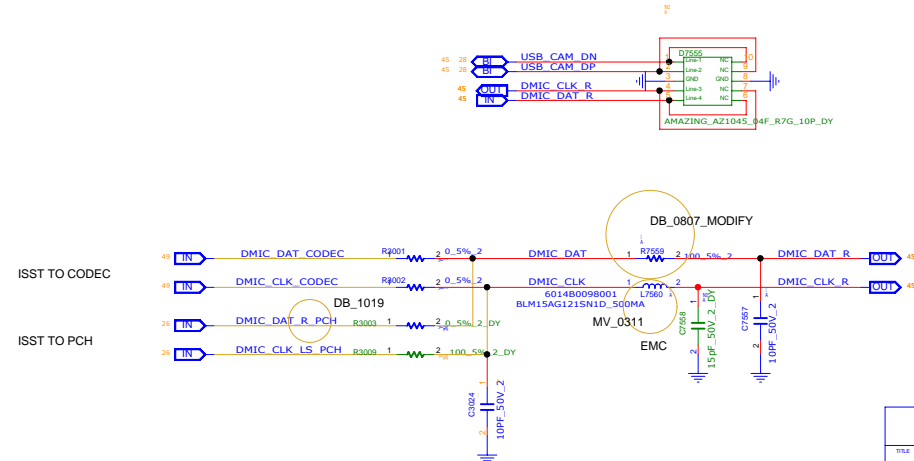
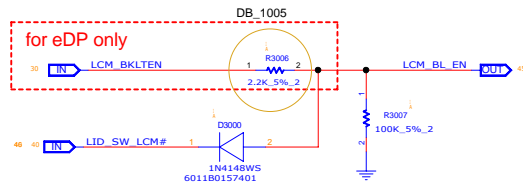
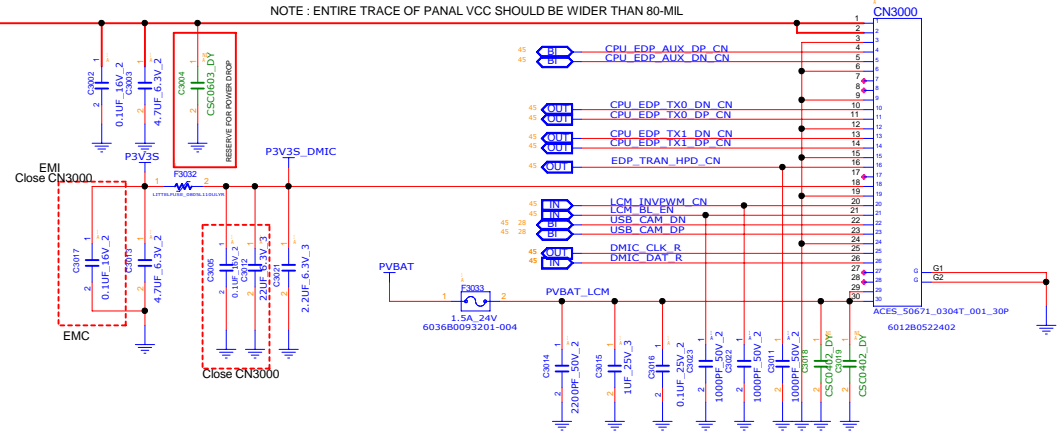
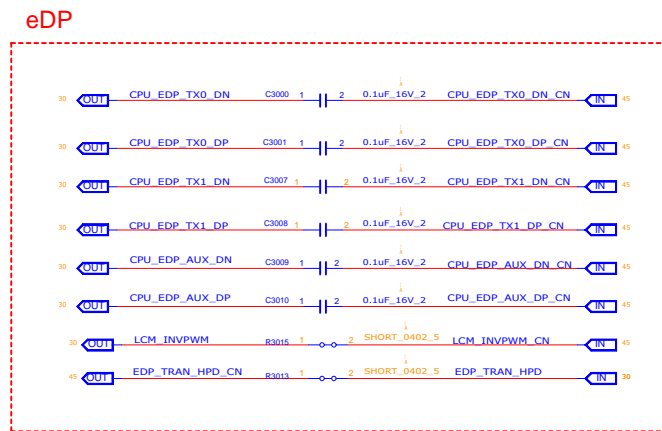
MODEL,PROJECT,FUNCTION			
HDMI CONN			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxxx-0-0	X01
SHEET 44 of 77			

eDP

LOCATION 3000 ~ 3049



NOTE : ENTIRE TRACE OF PANAL VCC SHOULD BE WIDER THAN 80-MIL



ISST TO CODEC

ISST TO PCH

INVENTEC

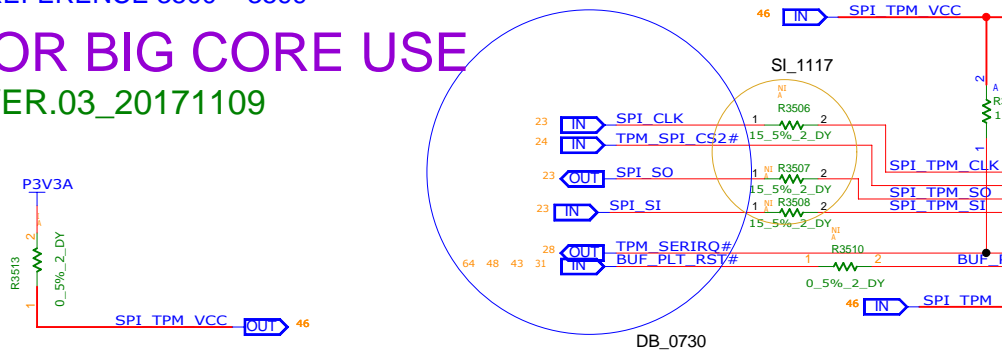
TITLE			
MODEL,PROJECT,FUNCTION			
LVDS			
SIZE	CODE	DOC NUMBER	REV
C	CS	1310XXXXX-0-0	X01
SHEET		of 45	77

TPM2.0

REFERENCE 3500 ~ 3599

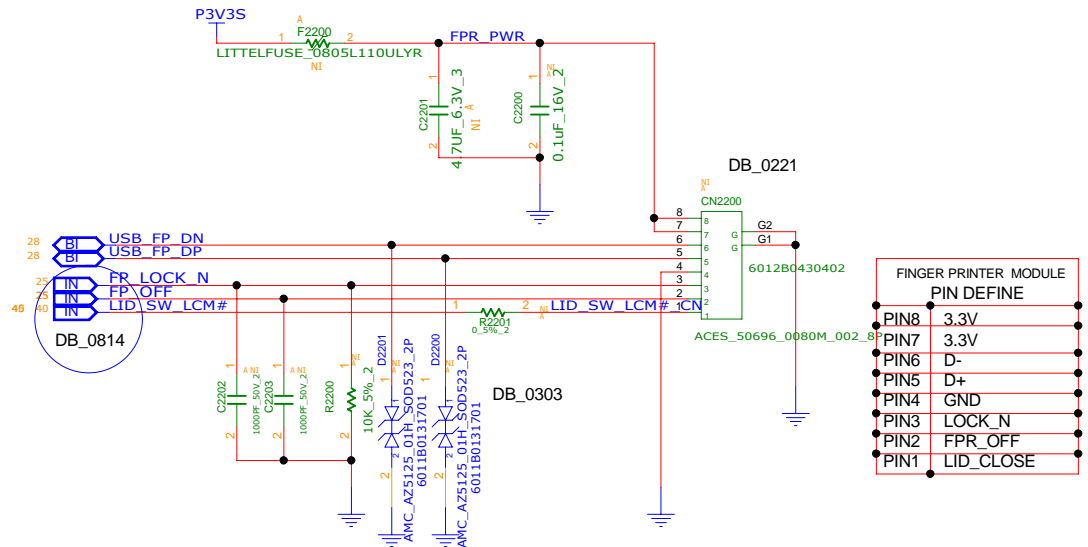
FOR BIG CORE USE

VER.03_20171109



FINGER PRINTER

REFERENCE:2200~2299



INVENTEC

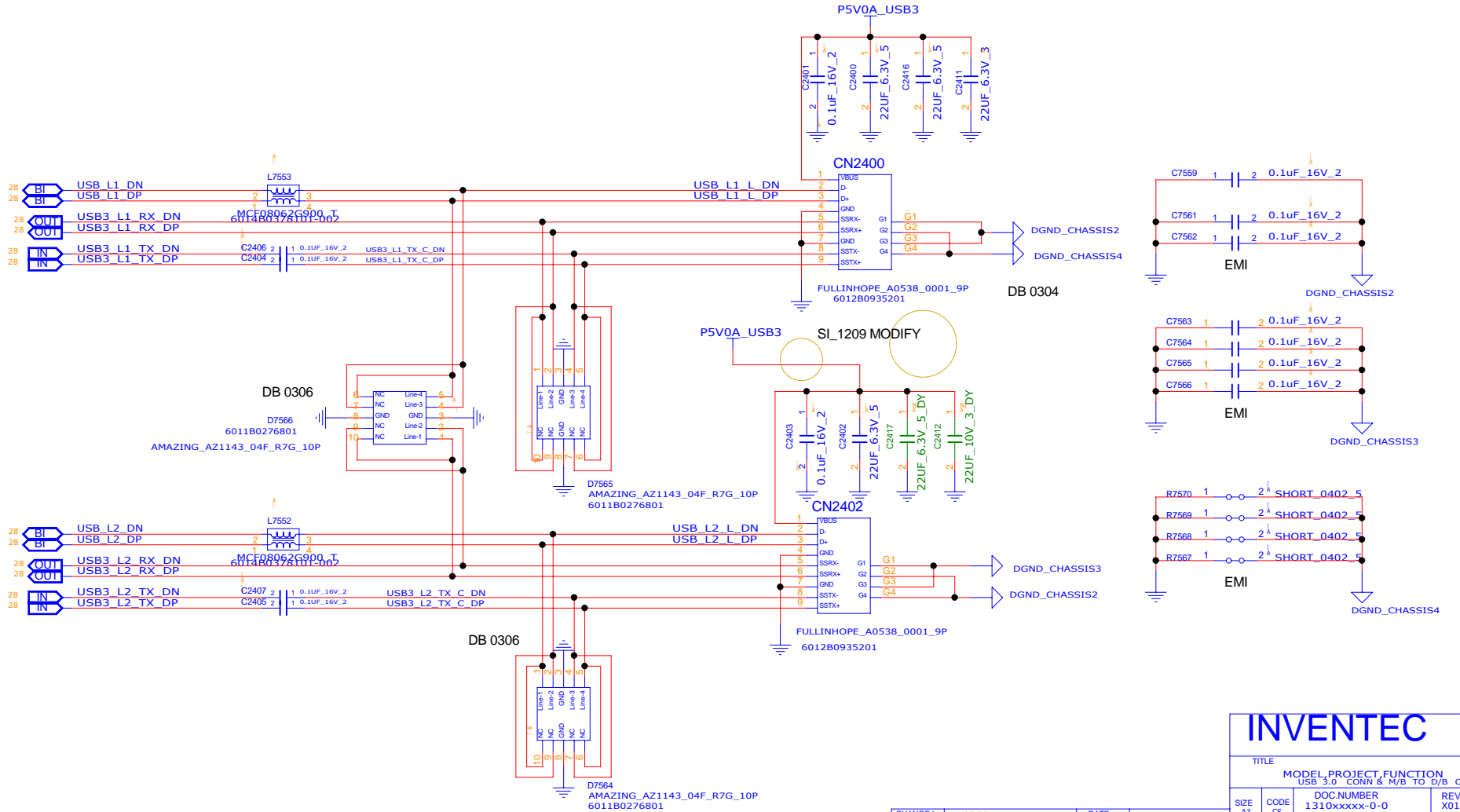
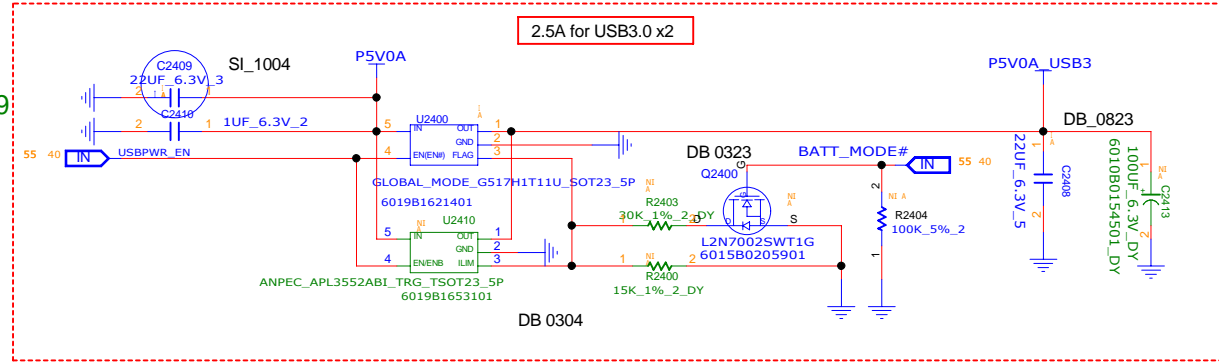
TITLE			
MODEL,PROJECT,FUNCTION			
Block Diagram			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxxx-0-0	X01
SHEET 46 of 77			

CHANGE by	X'ENG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxx	PCB VER	X'WER>

USB3.0

LOCATION 2400~2499

VER.08_20171119



INVENTEC

TITLE
MODEL PROJECT FUNCTION
USB3.0_CONN & M/B TO D/B_CONN

SIZE CODE DOC NUMBER REV
A3 CS 1310xxxxx-0-0 X01

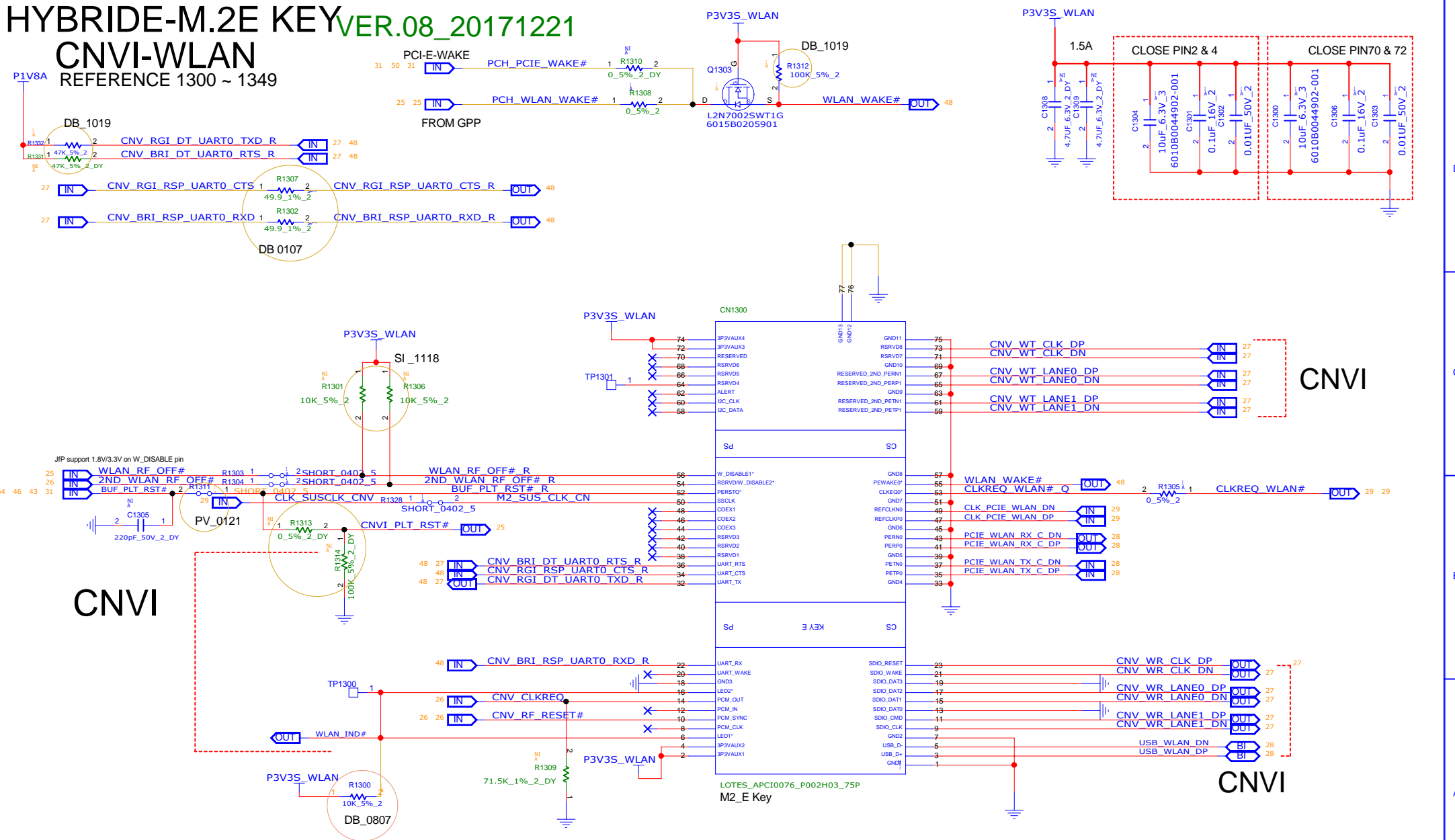
CHANGE by XXX
PCB P/N 60N8xxxxxxx DATE
PCB VER. 0010CT-2002

SHEET of 47 77

HYBRIDE-M.2E KEY

CNVI-WLAN

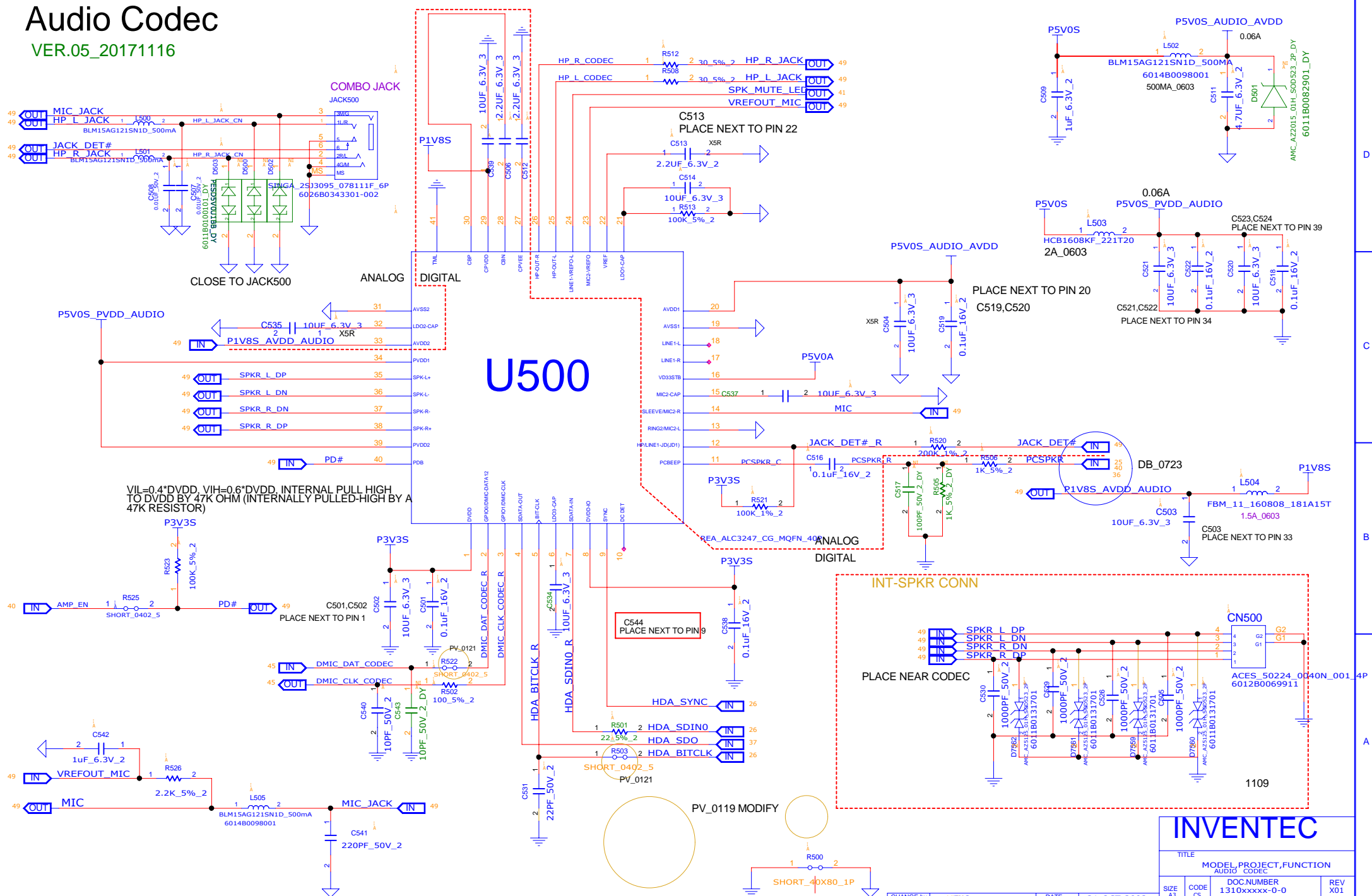
REFERENCE 1300 ~ 1349



INVENTEC			
TITLE			
MODEL,PROJECT,FUNCTION WLAN & BT			
SIZE	CODE	DOC NUMBER	REV
3	CS	1310xxxx-0-0	X01
SHEET of 48 77			

CHANGE by	XXX	DATE	2002-10-01
PCB P/N	60N8xxxxxxx	PCB VER	001

VER.05_20171116

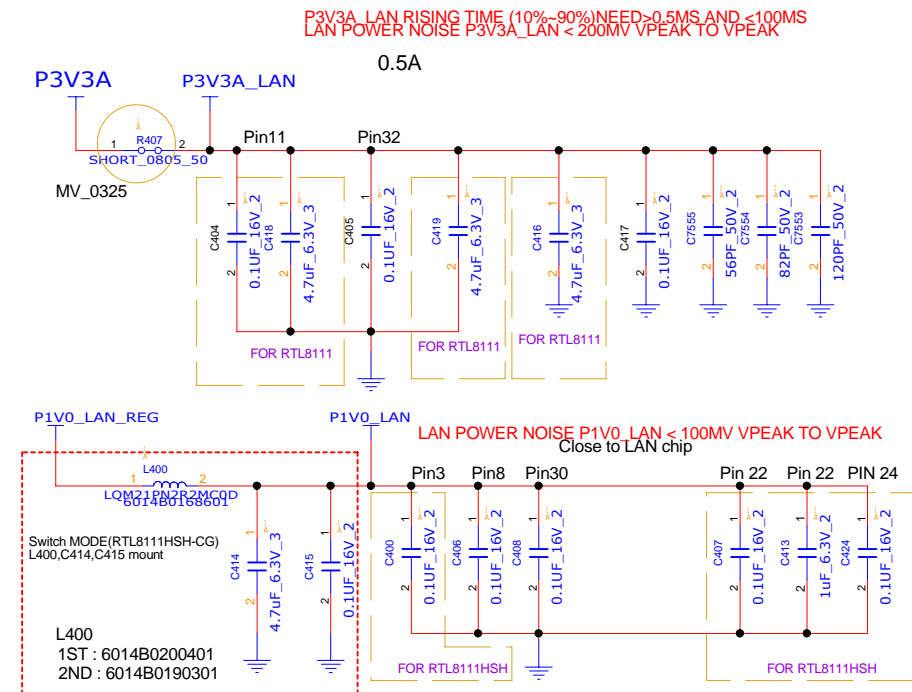


CHANGE by	XENG>	DATE	21-OCT-2002	SHEET	CS	1310xxxxx-U-0	X01
PCB P/N	60xxxxxxxxxx	PCB VER	XVER>	SHEET	49 of 77		

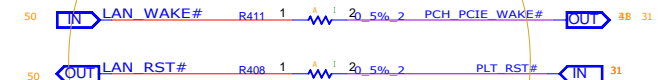
Location 400 ~ 469
VER.05_20171115-2

Location 400 ~ 469
VER.05_20171115-2

★ 6019B1264001	RTL8111HSH-CGT	10/100/1000
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DB_1005



DB 0323

FOR DONGTING WAKE ON WLAN
DONGTING MOUNT
HEDWIG DY

INVENTEC

TITLE			
MODEL,PROJECT,FUNCTION			
Block		Diagram	
SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
SHEET		50 of 77	

CHANGE by	XXX	DATE	21-OCT-2002
PCR P/N	60xxxxxxxxxx	PCR VER	YYY

LAN (Transformer & RJ45)

Location 470 ~ 499

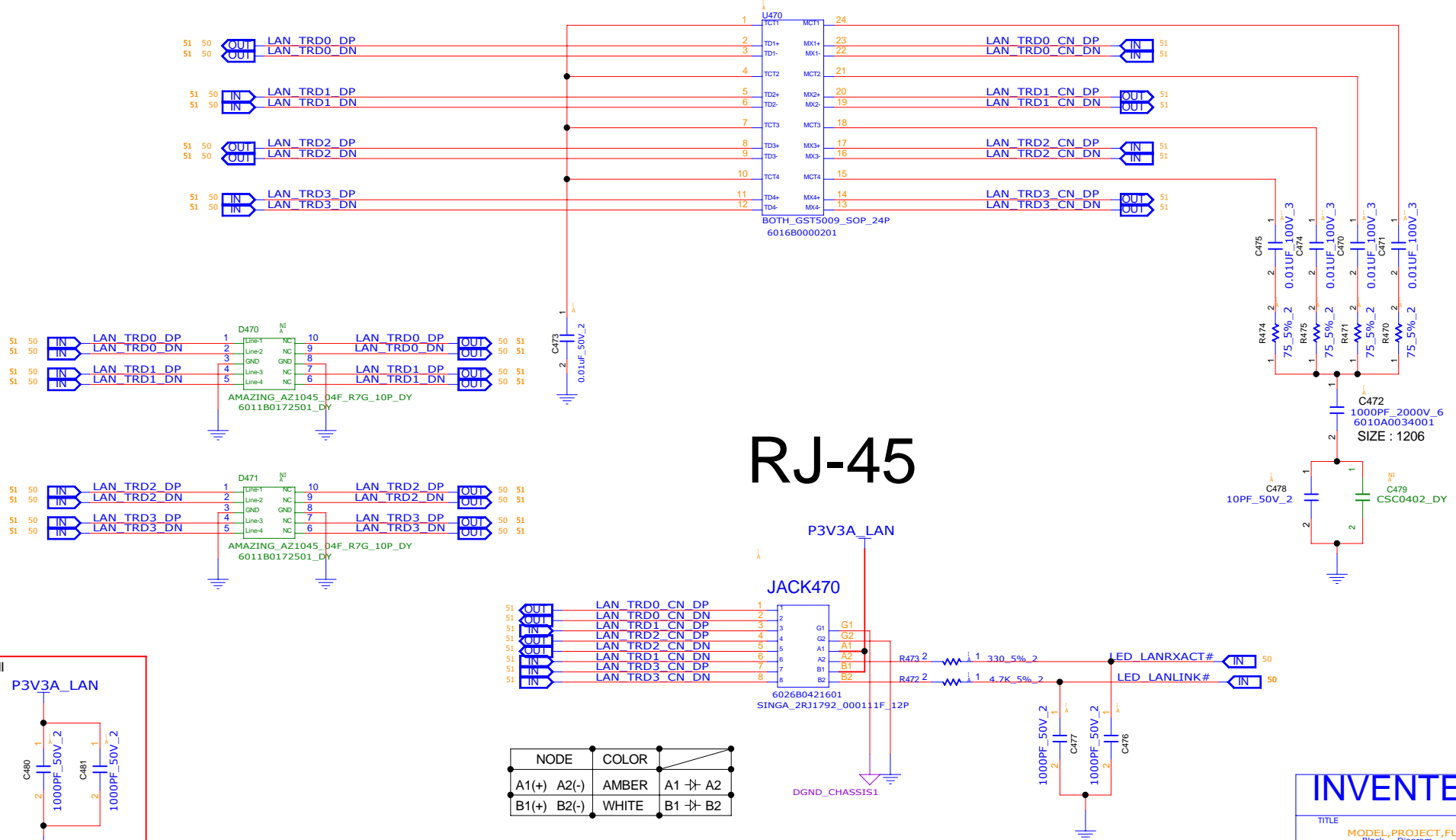
VER.05_20171107

For 10/100 /1000 LAN

GIGA main BOM change to 6016B0000201

10/100/1000 MAIN====> BOTHHAND P/N : 6016B0000201 GST5009

10/100/1000 2ND====> UDE P/N : 6016B0022201 L22N001-0



INVENTEC

TITLE
MODEL,PROJECT,FUNCTION

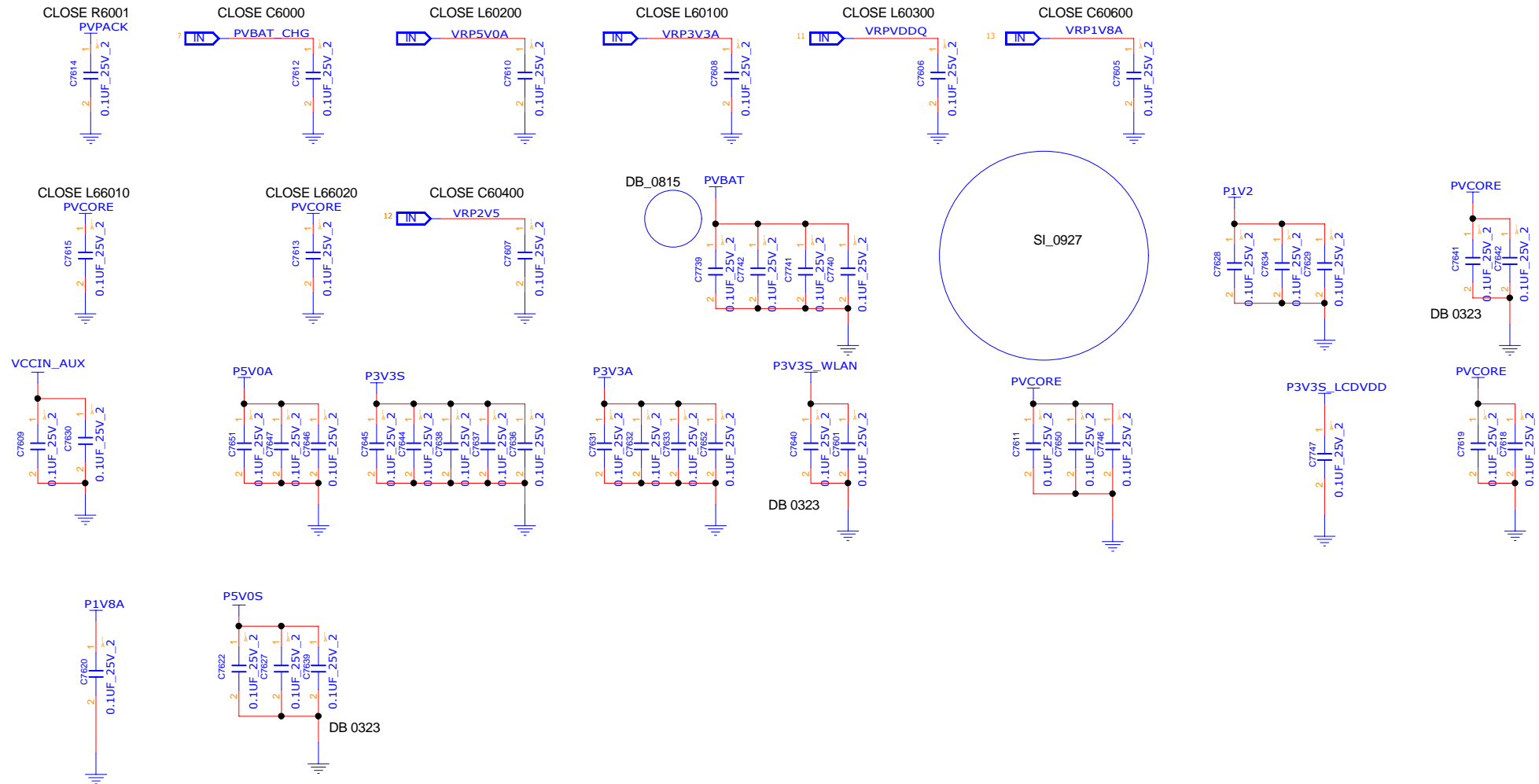
SIZE CODE DOC NUMBER REV
A3 CS 1310xxxxx-0-0 X01

CHANGE by XXX DATE 21-OCT-2002
PCB P/N 60xxxxxxx PCB VER XXX

SHEET 51 of 77

EMI SOLUTION

LOCATION : 7600 - 7699



INVENTEC

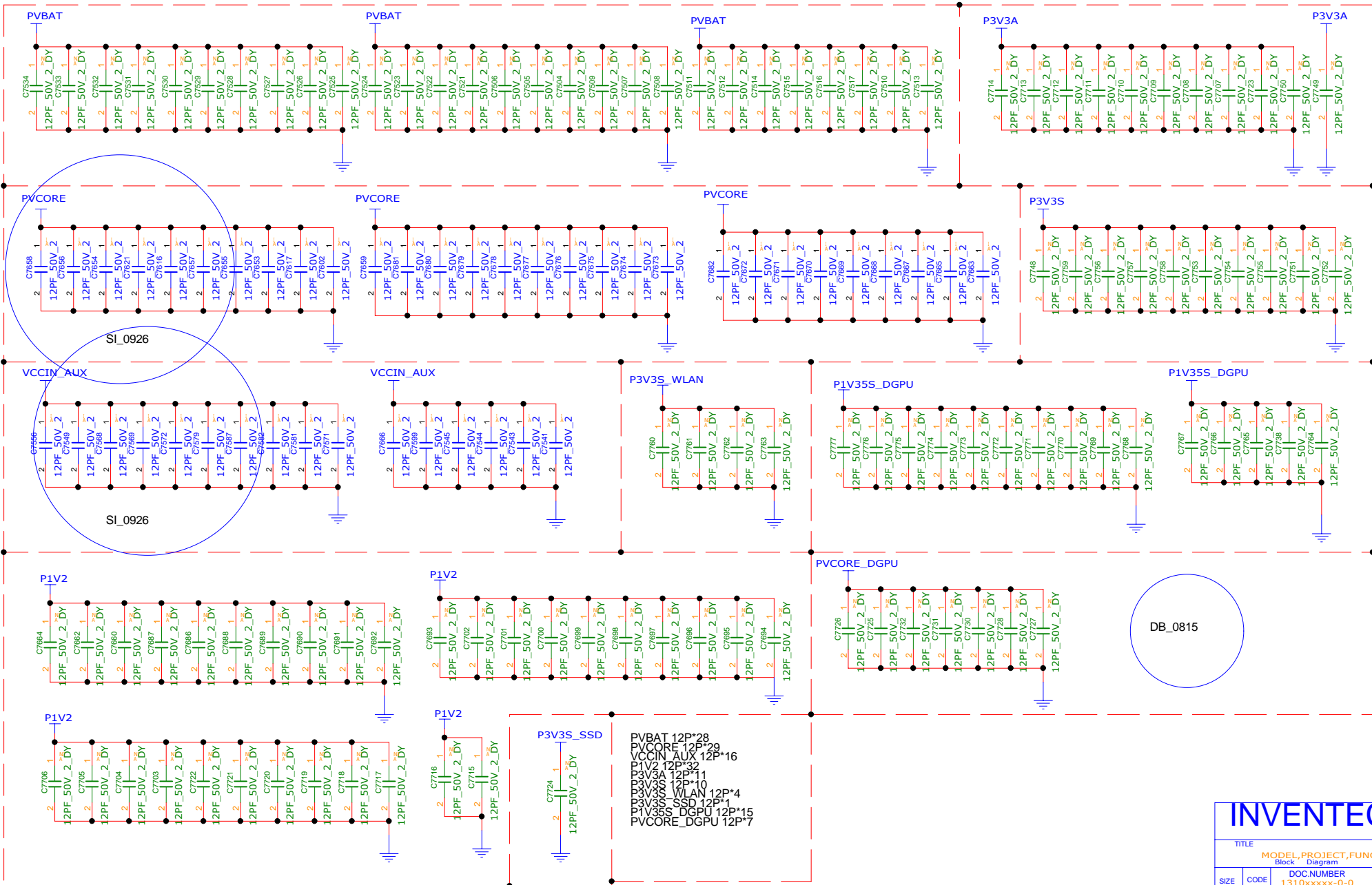
TITLE
MODEL,PROJECT,FUNCTION
Block Diagram

SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
SHEET		52	of 77

CHANGE by PCB P/N	XXX 60xxxxxxxxxxx	DATE PCB VER	21-OCT-2002 XXX
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RF SOLUTION

LOCATION: 7500 - 7599



PVBAT 12P*28
PVCORE 12P*29
VCCIN_AUX 12P*16
P3V3A 12P*10
P3V3S 12P*10
P3V3S_WLAN 12P*4
P1V35S_DGPU 12P*1
P1V35S_DGPU 12P*15
PVCORE_DGPU 12P*7

INVENTEC

TITLE MODEL,PROJECT,FUNCTION

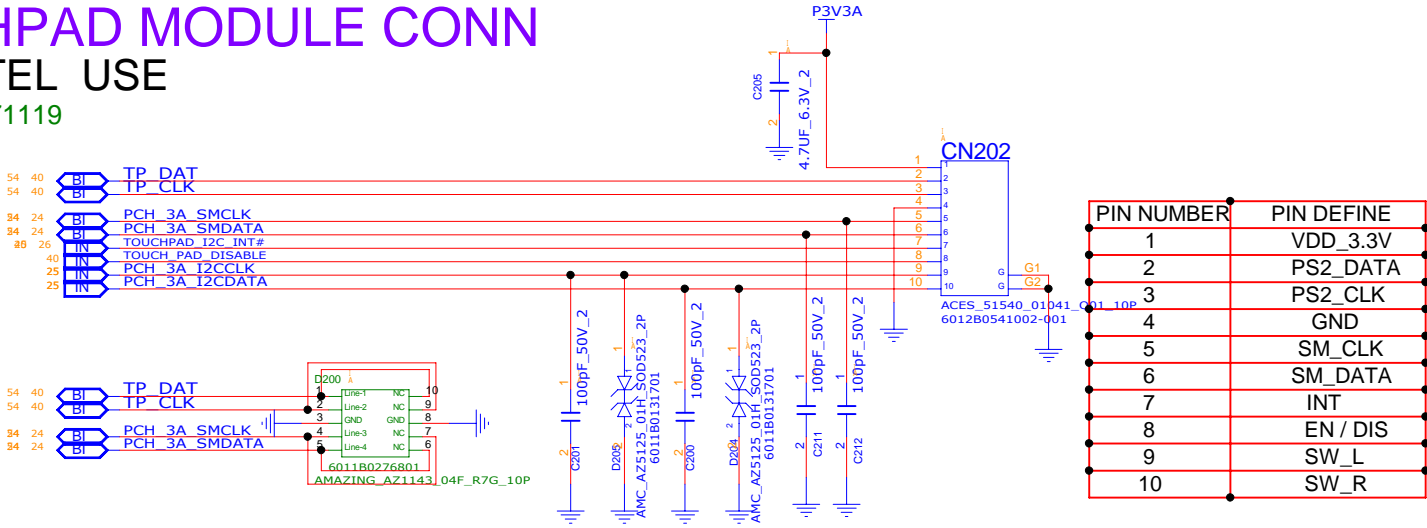
SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
SHEET 53 of 77			

CHANGE by XXX	DATE 21-OCT-2002
PCB P/N 60xxxxxxxxxx	PCB VER XXX

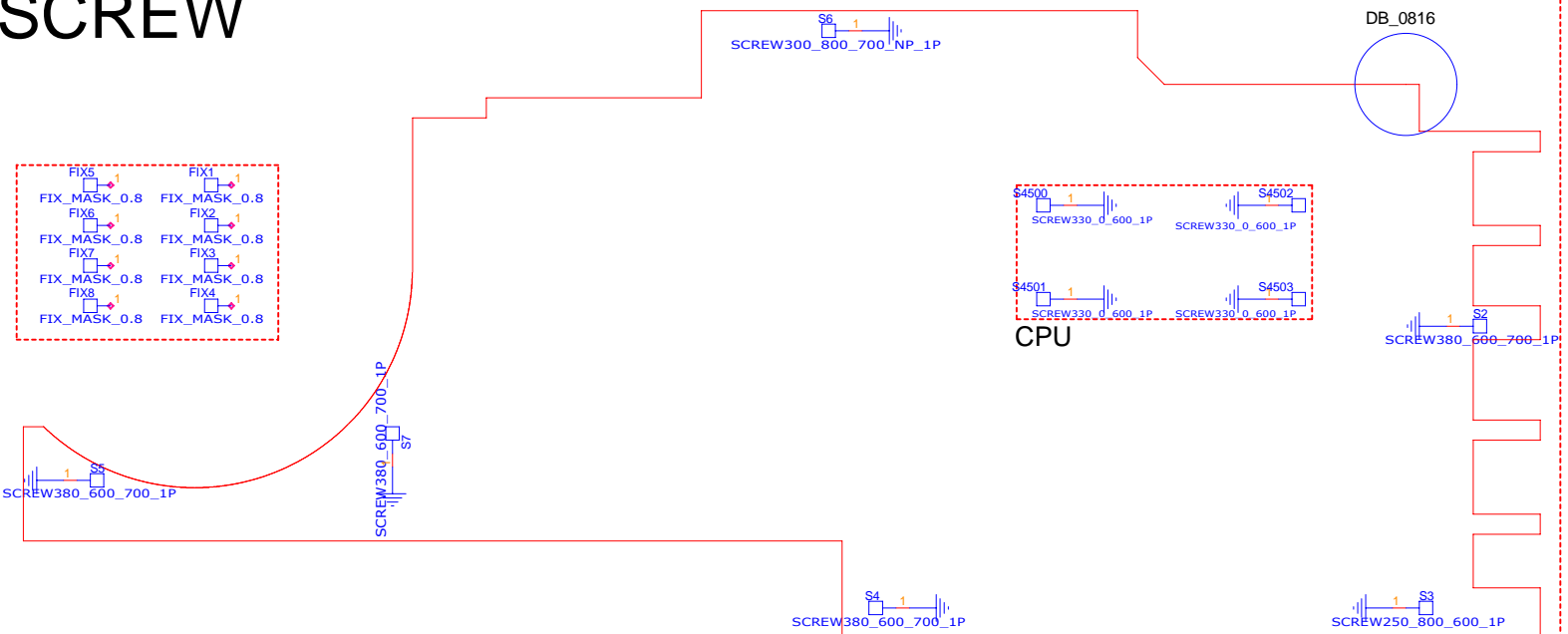
TOUCHPAD MODULE CONN

FOR INTEL USE

VER.14_20171119



SCREW



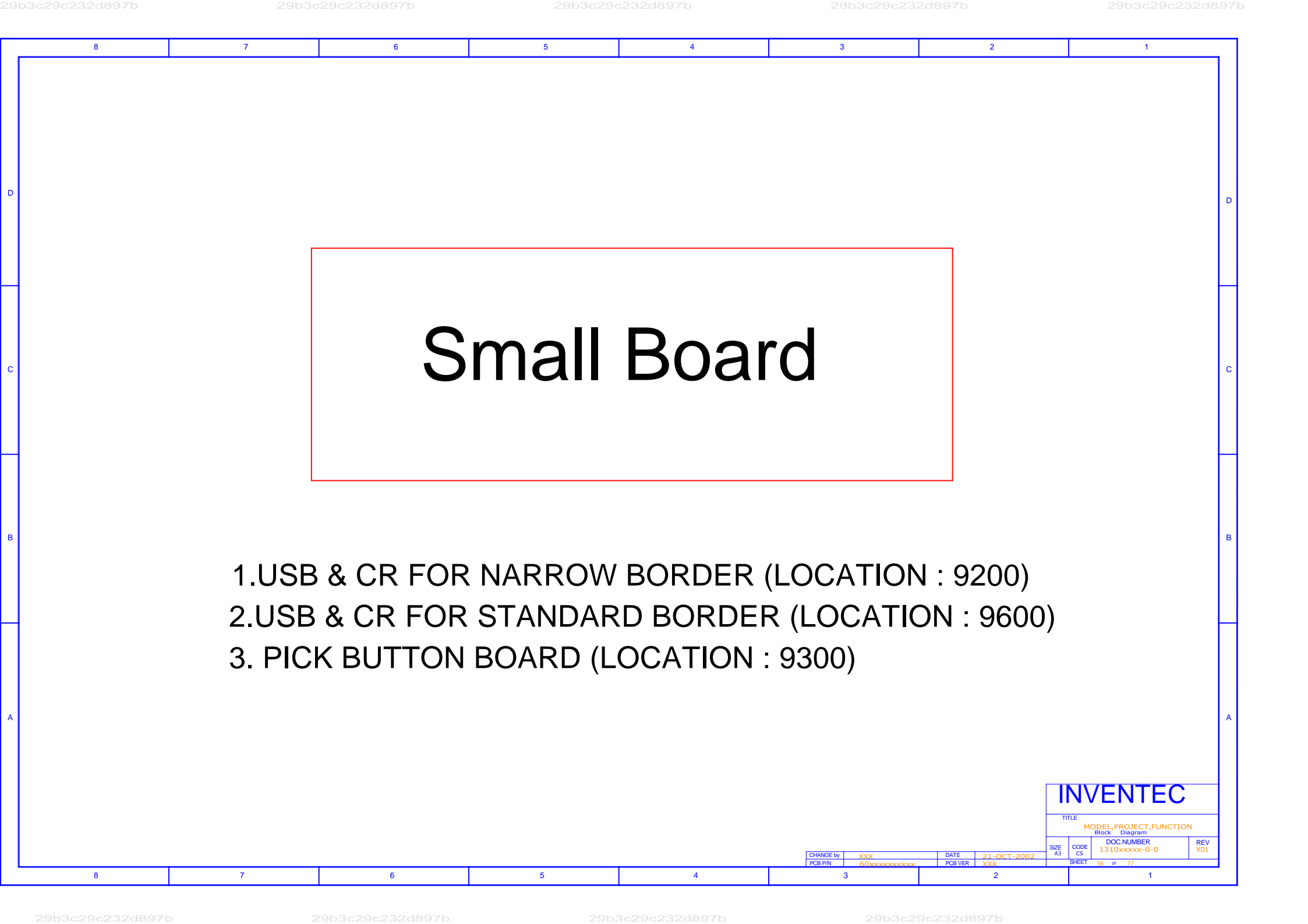
INVENTEC

TITLE			
MODEL PROJECT,FUNCTION			
POWER BUTTON			
DOC NUMBER			
1310xxxxx-0-0			
REV			
X01			
SIZE	CODE	SHEET	
A3	CS	of 54 77	

CHANGE by	XXX	DATE	2017-11-19
PCB P/N	6011B0131701	PCB VER	001
REV			
001			

VER.12_20171120





Small Board

- 1.USB & CR FOR NARROW BORDER (LOCATION : 9200)
- 2.USB & CR FOR STANDARD BORDER (LOCATION : 9600)
- 3. PICK BUTTON BOARD (LOCATION : 9300)

INVENTEC			
TITLE			
MODEL,PROJECT,FUNCTION			
Block Diagram			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxx-0-0	X01
SHEET 56 of 77			
CHANGE by	XXX	DATE	21-OCT-2002
PCB PIN	60xxxxxxxxxx	PCB VER	XXX

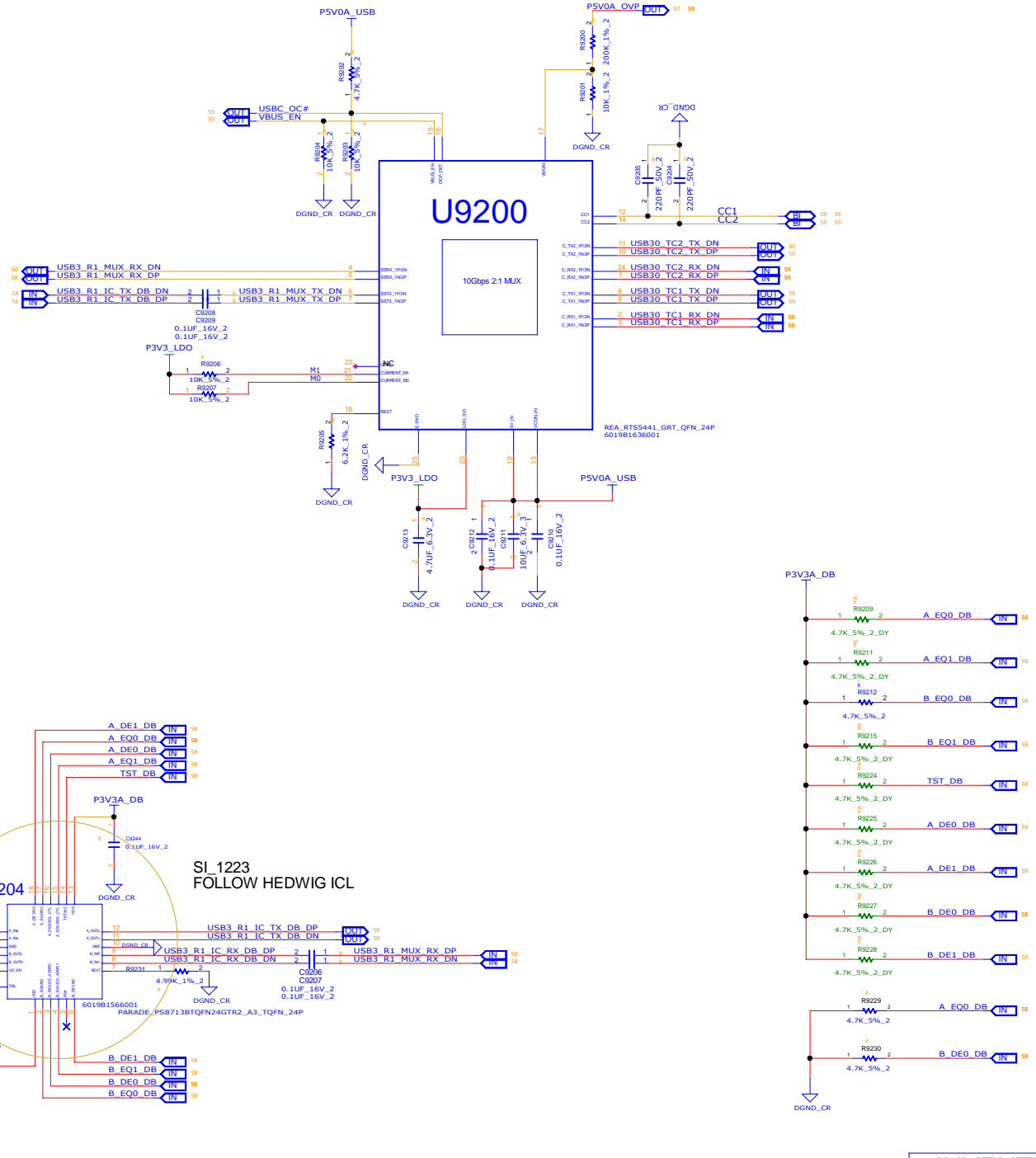
VER.09_20171109



USB3.0 MUX

FOR NARROW BORDER USE

VER.02_20170919



INVENTEC

Title			
MODEL,PROJECT,FUNCTION			
Block Diagram			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310XXXX-0-0	X01
SHEET		SB	# 77

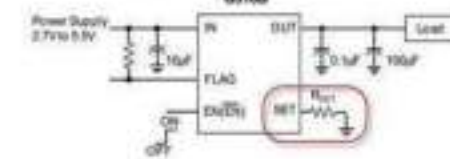
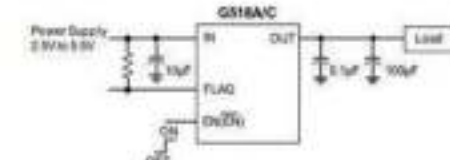
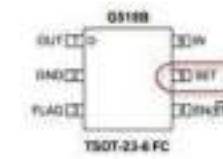
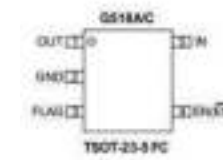
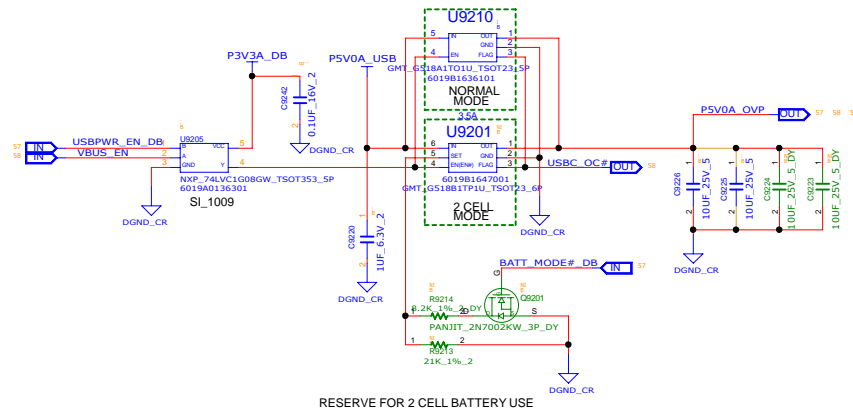
CHANGED	XXX	DATE	21-OCT-2002
PCB PIN	60XXXXXXXXXX	PCB VER	XXX

USB3.0 TYPEC CNTR

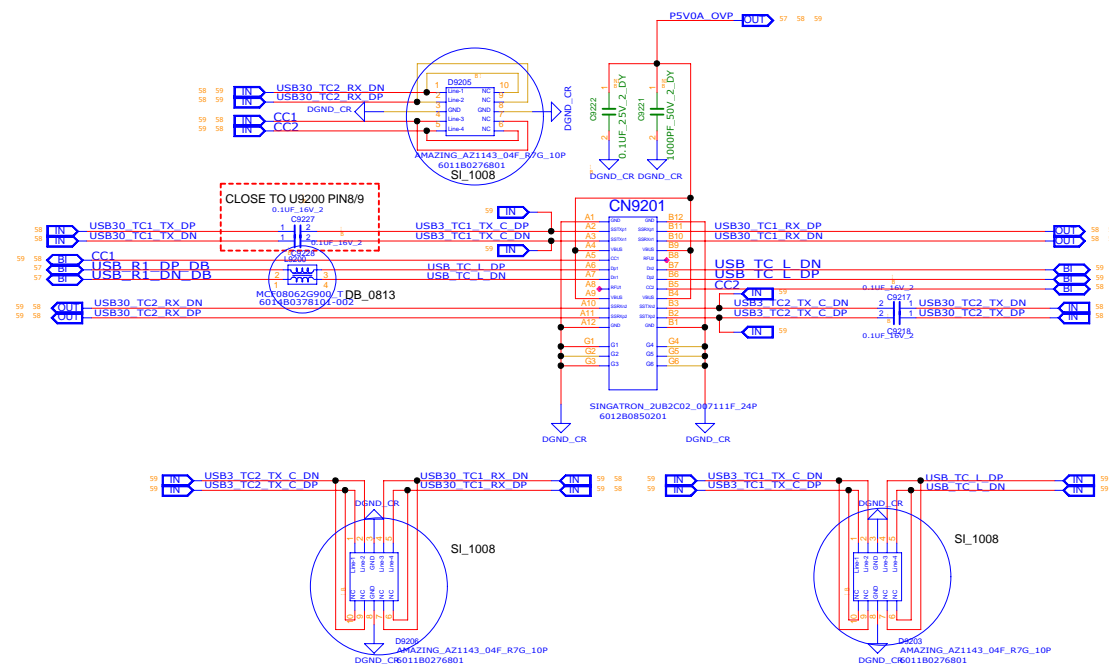
FOR NARROW BORDER USE

VER.13_20171119

TYPE C OVP



			MIN	TYPE	MAX	UNIT	
NORMAL SUPPORT 2 CELL	G518A (TSOT-23-5)	6019B1636101	3.1	3.5	4	A	
	G518B (TSOT-23-6)	AC MODE R_SET=6K	3.1	3.5	4	A	BATT_MODE#_DB = HIGH
	6019B1647001	DC MODE R_SET=21K	0.8	1	1.2	A	BATT_MODE#_DB = LOW

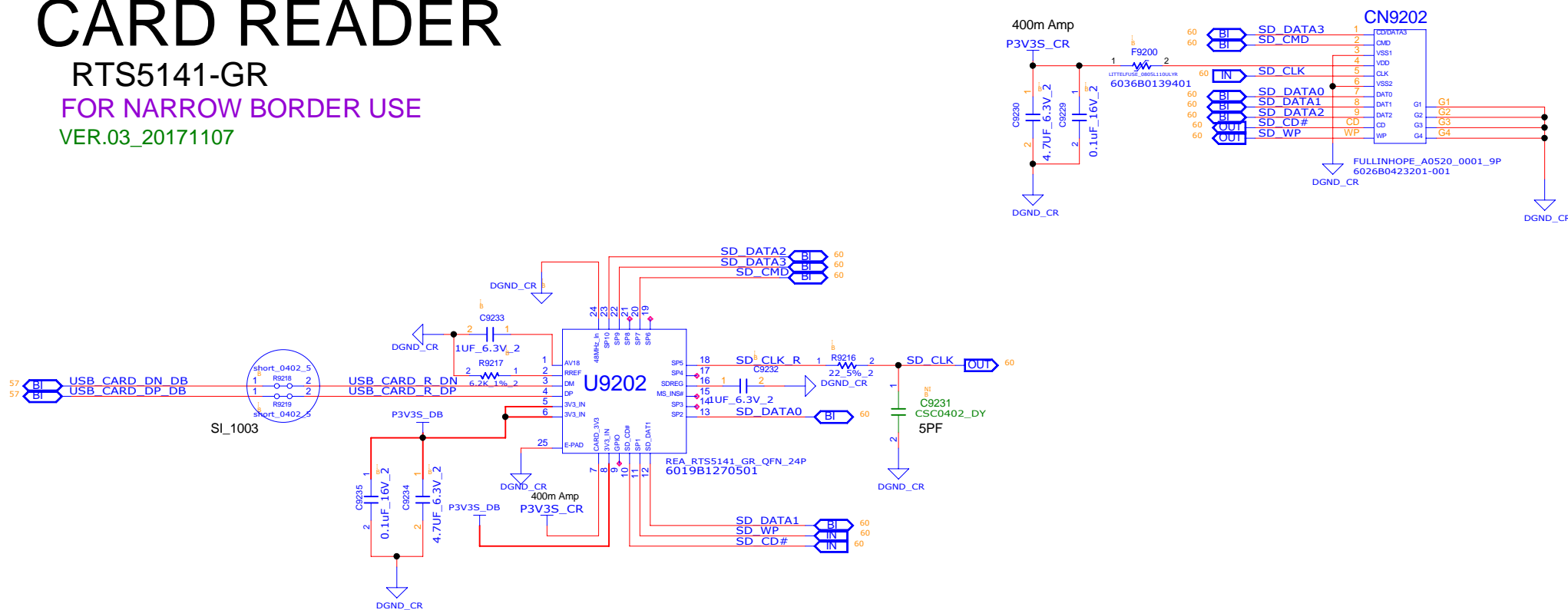


INVENTEC

TITLE			
MODEL,PROJECT,FUNCTION DDR3_SO-DIMM0			
SIZE C	CODE CS	DOC NUMBER 1310xxxxxx-0-0	REV X01
SHEET		of 59	77

CHANGE by	XXX	DATE	
PCB P/N	60xENGxxxx	PCB VER 2	0002002

VER.03 20171107



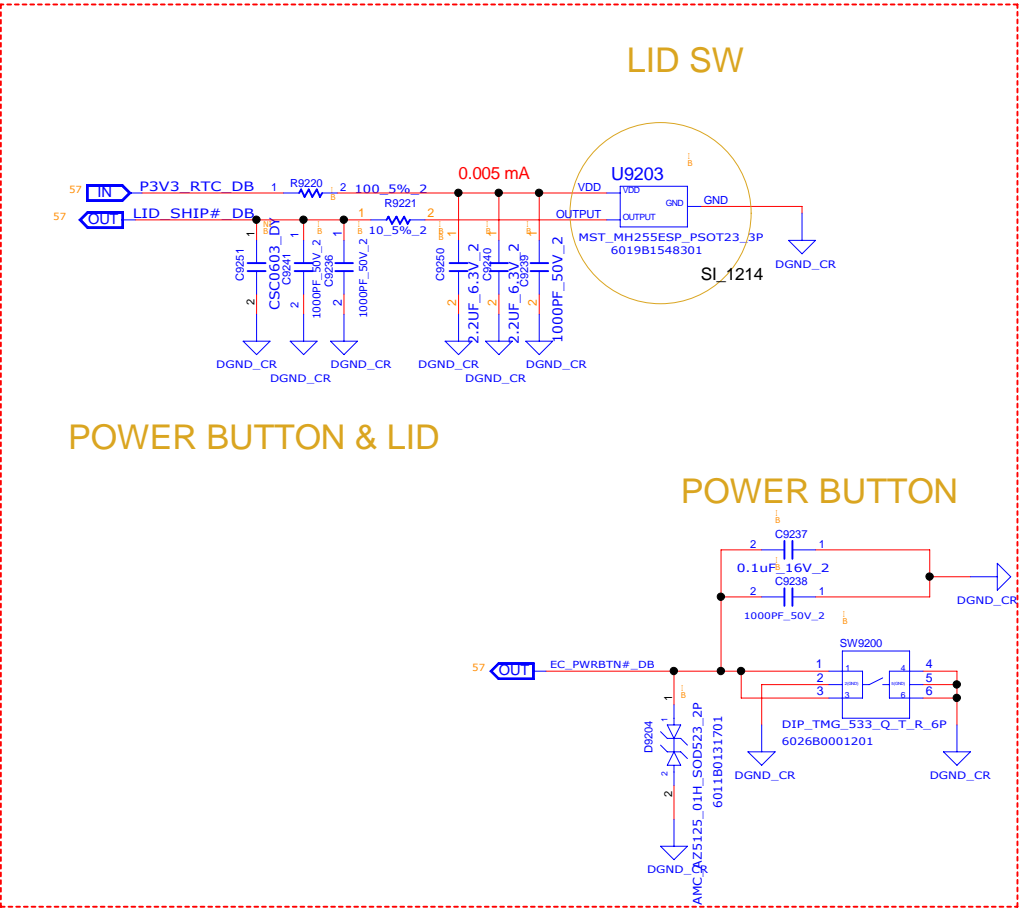
SHEET 60 of 77

CHANGE by	XENG>	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxx	PCB VER	XXER>

LID SW & POWER BUTTON

FOR NARROW BORDER USE

VER.07_20171120



INVENTEC

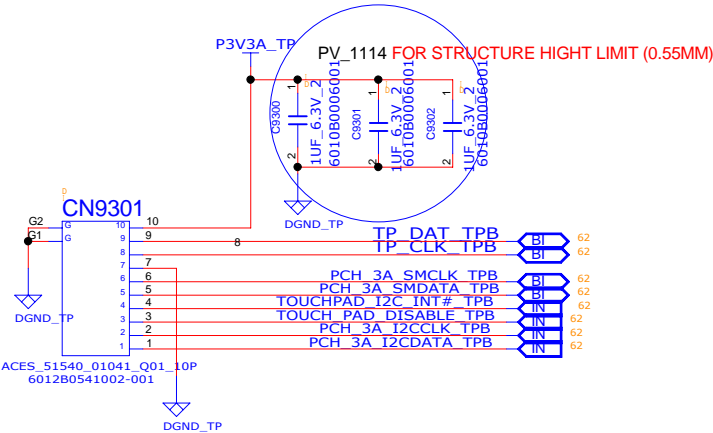
TITLE			
MODEL, PROJECT, FUNCTION			
Block Diagram			
SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
SHEET 61 of 77			

CHANGE by	XXX	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxxx	PCB VER	XXX

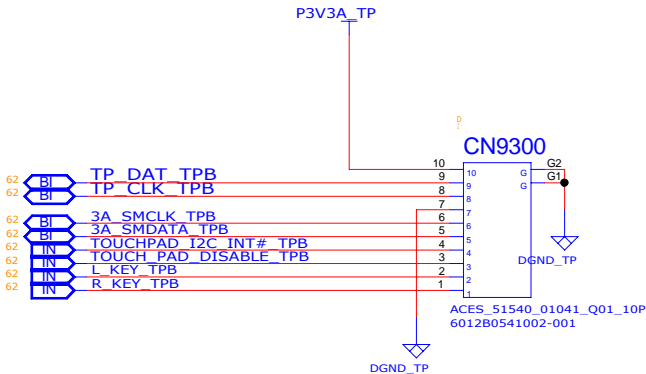
PICK BUTTON (TYPE_C)

TOUCHPAD R / L BOARD

VER.03_20171119

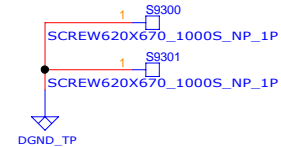
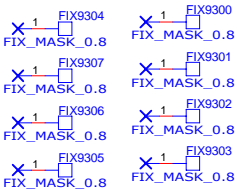
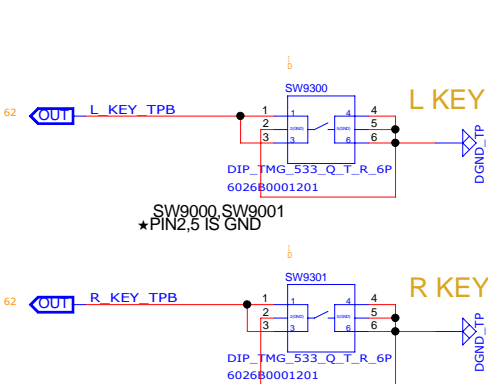
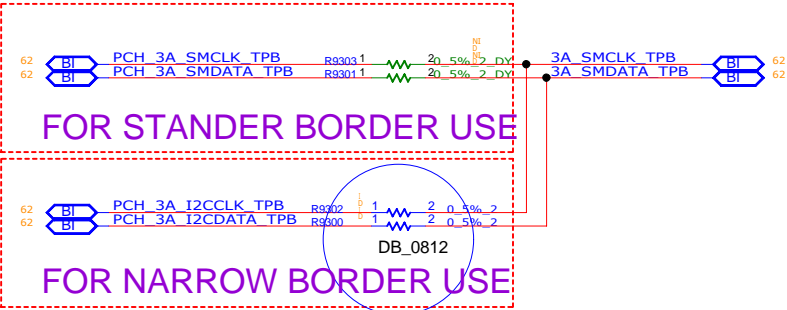


TO MAIN BOARD



TO TP MODULE

PIN DEFINE	PIN NUMBER
VDD_3.3V	1
PS2_DATA	2
PS2_CLK	3
GND	4
SM_CLK	5
SM_DATA	6
INT	7
EN / DIS	8
SW_L	9
SW_R	10



INVENTEC

N18S-G5
GDDR5 SINGL RANK 23X23

2021.03.02

PCA CODE NAME : N18S-G5-A1 GPU
PCB VERSION : AX1

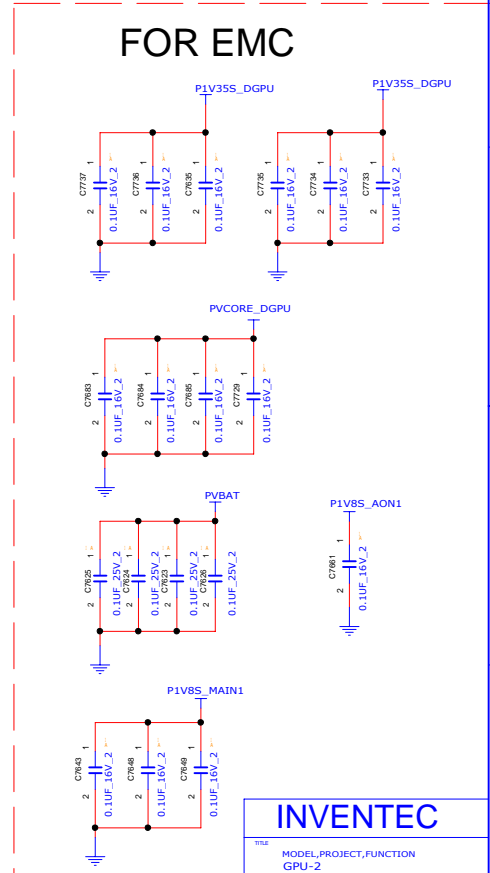
BOARD SIZE:

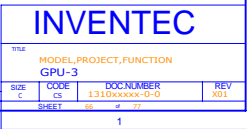
HP
SCH P/N:
PCB P/N:
PCA P/N:

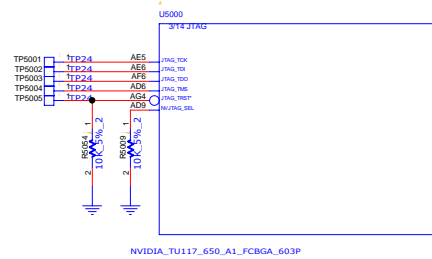
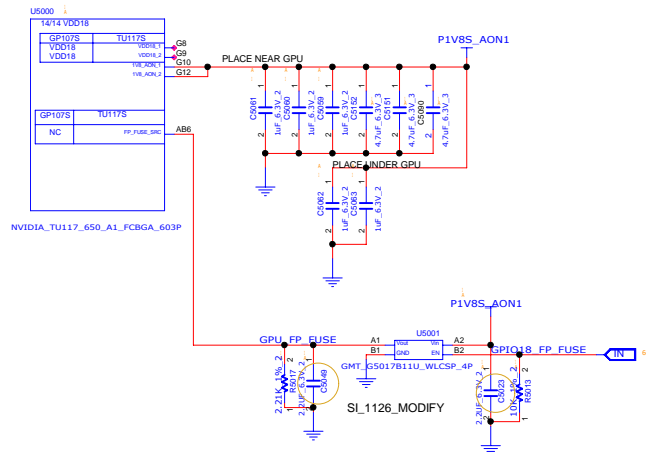
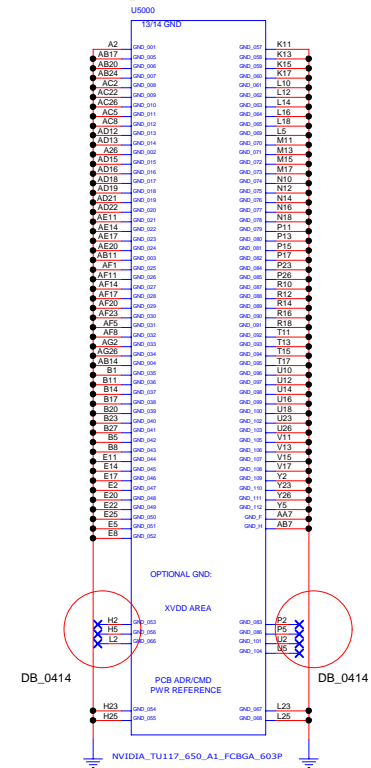
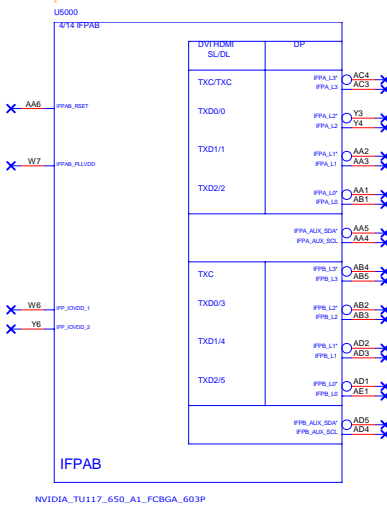
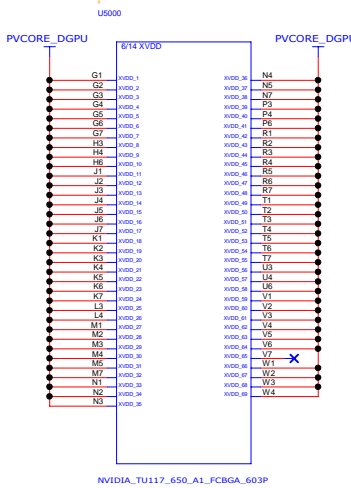
21-OCT-2002	2013-ECO-002392	A
DATE	CHANGE NO.	REV

INVENTEC			
TITLE MODEL, PROJECT, FUNCTION			
DESIGN / DRAWER	XXX	DATE	21-OCT-2002
CHECK	HSuAndy		
APPROVAL	HSuAndy		
FILE NAME	MLB P23-RANGERS		
PCB P/N	50XXXXXXXXXX	PCB VER	XXX
SHEET 61		REV 22	
1			









INVENTEC			
MODEL/PROJECT/FUNCTION			
GPU-4			
SIZE	CODE	DOC NUMBER	REV
C	CS	1310VXXXX-0-0	X01
SHEET	67	of 75	

CHANGES	XXXX	DATE	21-OCT-2002
PCB PIN	XXXX	PCB VER	XXXX

Table 11. N18S-G5 GDDR5 Recommended Memories

Memory Density	Allowed Memory Configuration	FBVDDQ5	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Data Cache Alert	Qual. Plan	Status
8 GB	256Mb G5 512Mb18	1.37V	Hynix	MT51J256M32HF-80B	B-0b	Strap1	8 Gbps	N/A	Full	Production candidate
			Hynix	H5GC8H24AJR-R2C	A-2b	Strap2	8 Gbps	N/A	Full	Production candidate
			Samsung	K4G80325FC-HC25	C-0b	Strap5	8 Gbps	N/A	Full	Production candidate

NOTE:
1. For H5GS-G5, the maximum allowable memory case temperature is 85 °C.

Strap Pins			RAMCFG Setting Number	
STRAP1	STRAP0	STRAP5	(see Memory RVL for memory configs corresponding to these numbers)	
L	L	L	0 (0x0000)	
L	L	H	1 (0x0001)	
L	H	L	2 (0x0002)	
L	H	H	3 (0x0003)	
H	L	L	4 (0x0004)	
H	L	H	5 (0x0005)	
H	H	L	6 (0x0006)	
H	H	H	7 (0x0007)	
L	L	L	8 (0x0008)	
L	L	H	9 (0x0009)	
L	L	L	10 (0x000A)	

N18S-G5									
DEFAULT: N18S + SAMSUNG									
VENDER	DENSITY	VENDER PN	IEC PN	STRAP	R5044	R5049	R5045	R5050	R5046
MICRON	256MX32	MT51J256M32HF-80B	6019B1721101	0X1	60130B1040ZT	NI	60130B1040ZT	60130B1040ZT	60130B1040ZT
HYNIX	256MX32	H5GC8H24AJR-R2C	6019B1723701	0X2	NI	60130B1040ZT	60130B1040ZT	NI	NI
SAMSUNG	256MX32	K4G80325FC-HC25	6019B1926601	0X4	NI	60130B1040ZT	NI	60130B1040ZT	60130B1040ZT

Strap Pins		Functions Selected by This Strapping				
STRAP5	STRAP4	STRAP3	SMB_ALT_ADDR	DEVID_SEL	PCI_E_CFG	YGA_DEVICE
L	L	L	0	0	0	0

Table 12.4 FS_OVERT* Strap Enabled

Strap Pins			FS_OVERT* Function	
ROM_SEL	ROM_0	ROM_SEL0	FS_OVERT* Function	
L	L	L	FS_OVERT* Function ENABLED	
L	L	H	FS_OVERT* Function DISABLED (default; do not configure)	

Note 1: Configuration other than the two listed in Table 12.4 must be avoided, as otherwise damage to the inputs may occur.

INVENTEC

MODEL/PROJECT/FUNCTION
GPU-5

CODE 13103XXXXXX-0-0

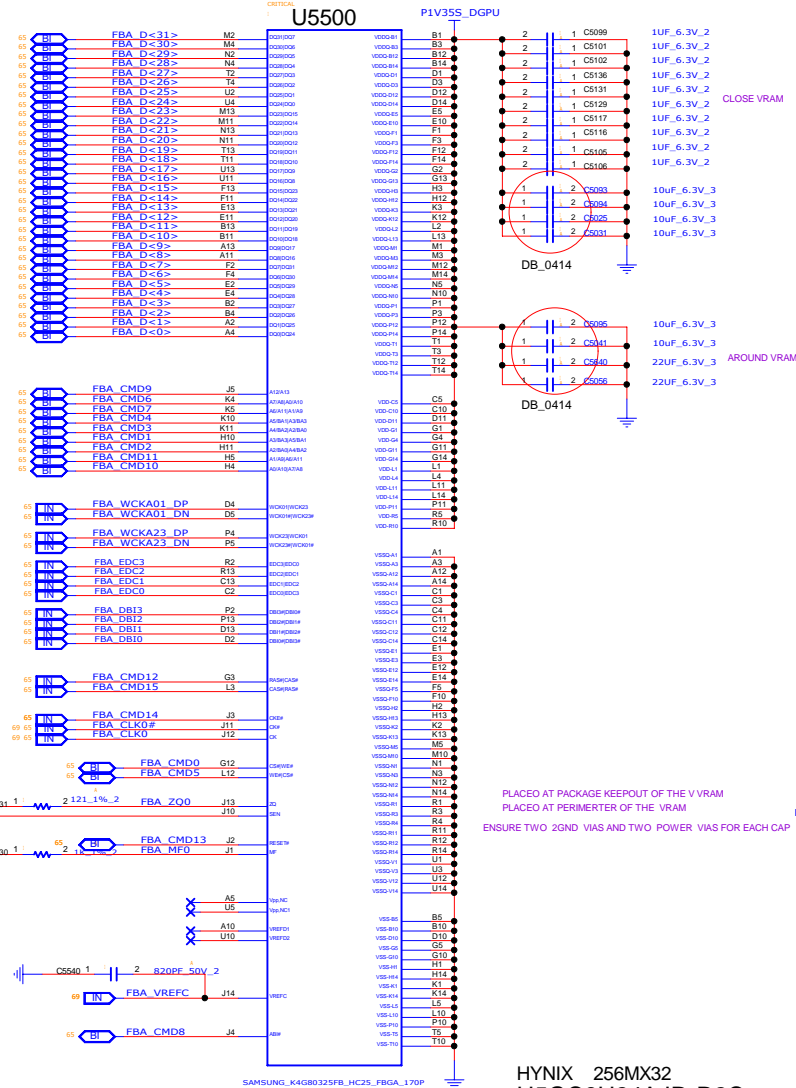
SHEET 68 of 72

CHANGES
PCB PIN XXXXXXXXXXXXXXXX
PCB VER XXX

DATE 21-OCT-2002

REV 001

VRAM A PARTITION

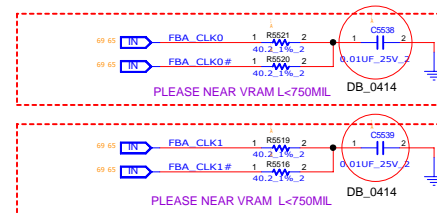
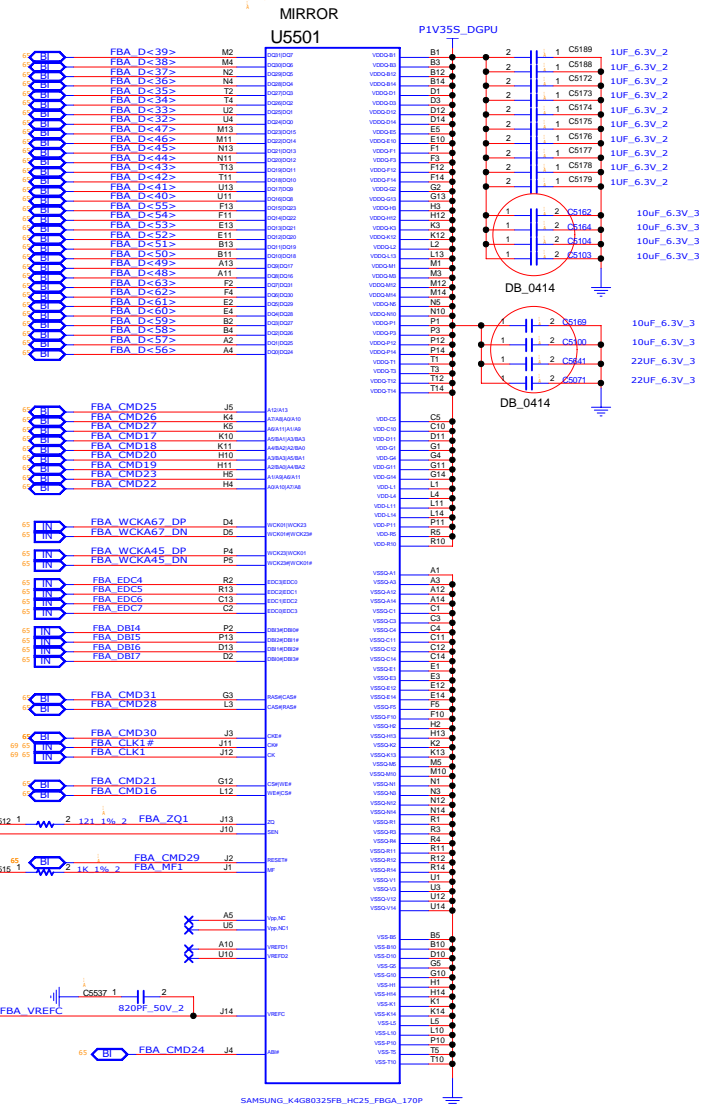



HYNIX 256MX32
H5GC8H24AJR-R2C

MICRON 256MX32
MT51J256M32HF-80:B

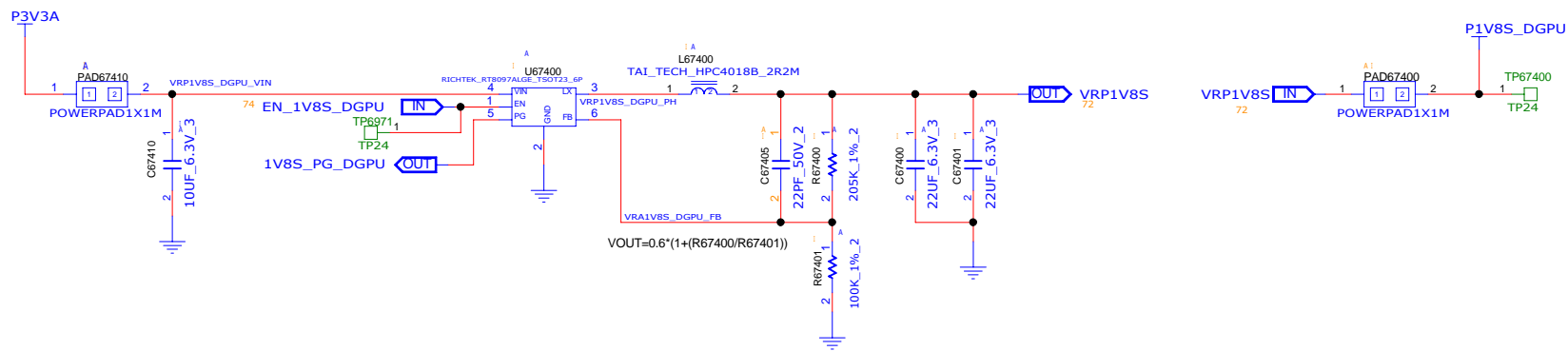
6019B1723701

6019B1721101



 HP RESTRICTED (HP RESTRICTED SECRET) THIS DOCUMENT CONTAINS UNCLASSIFIED PROPRIETARY INFORMATION UNLESS INDICATED OTHERWISE BY THE HP RESTRICTED SECRETARY			
DRAWN BY XXX			
TITLE MODEL,PROJECT,FUNCTION			
SIZE A3	DOC NUMBER 1310xxxxxx-0-0		REV X01
SHEET 69 of 77			

SHEET of 70 77



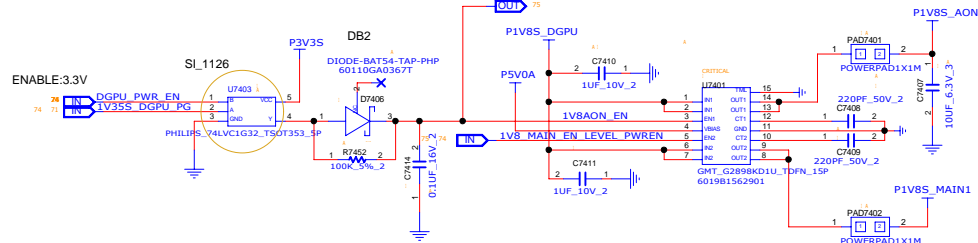
INVENTEC

TITLE			
MODEL PROJECT FUNCTION			
P1V8S_DGPU(AP2132B)			
SIZE	CODE	DOC NUMBER	REV
A3	CS	1310xxxxx-0-0	X01
SHEET 72 of 77			

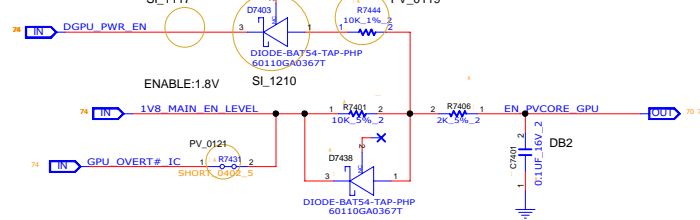
CHANGE by	XXX	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxxx	PCB VER	XXX

POWER_ON:P1V8S_AON1-->P1V8S_MAIN1-->NVVDD-->PEX_VDD-->FBVDD
 POWER_OFF:PEX_VDD-->FBVDD-->NVVDD-->P1V8S_MAIN1-->P1V8S_AON1

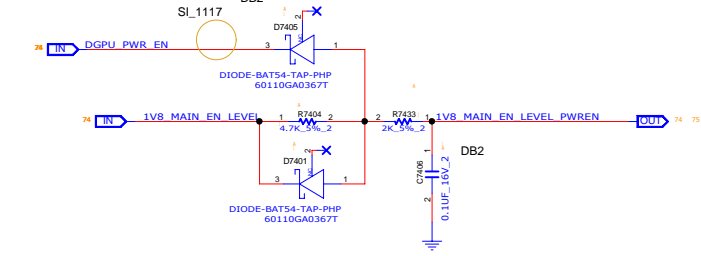
1V8_AON & 1V8_MAIN



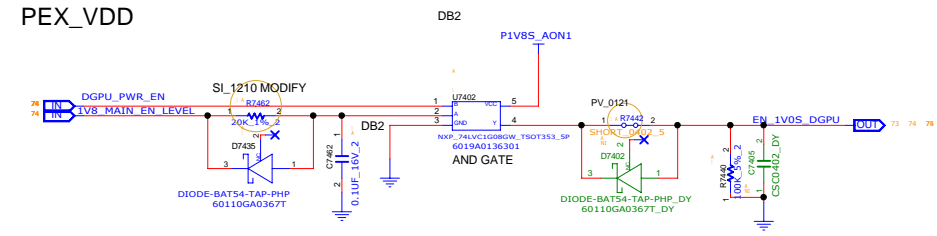
NVVDD



1V8_MAIN_EN

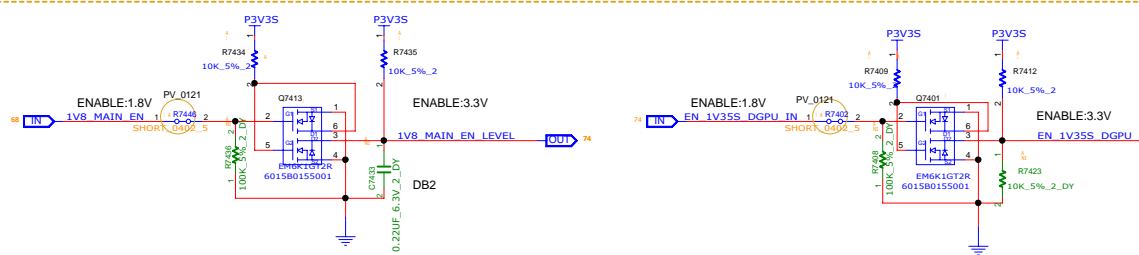
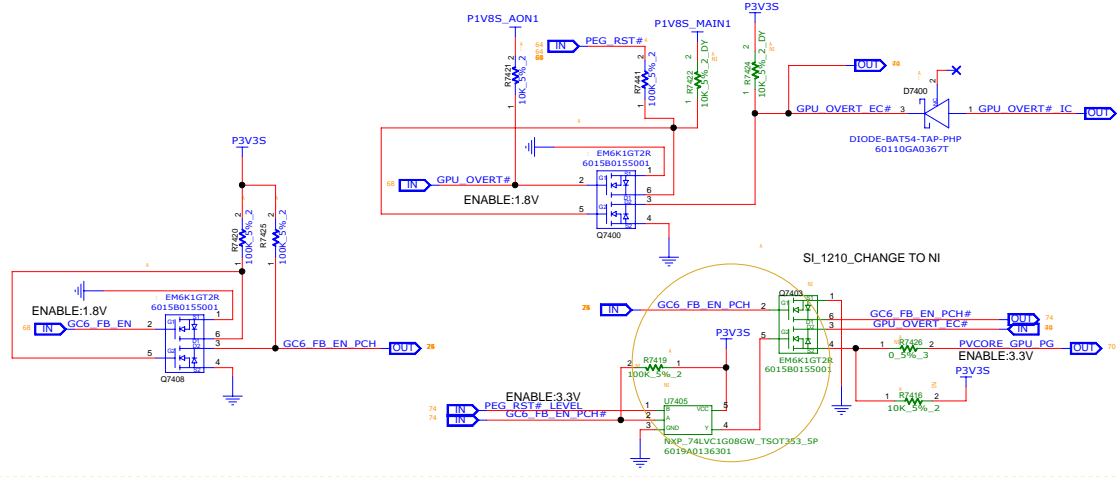
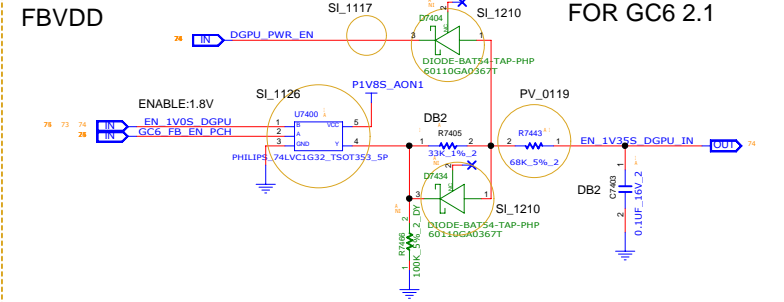


PEX_VDD



FBVDD

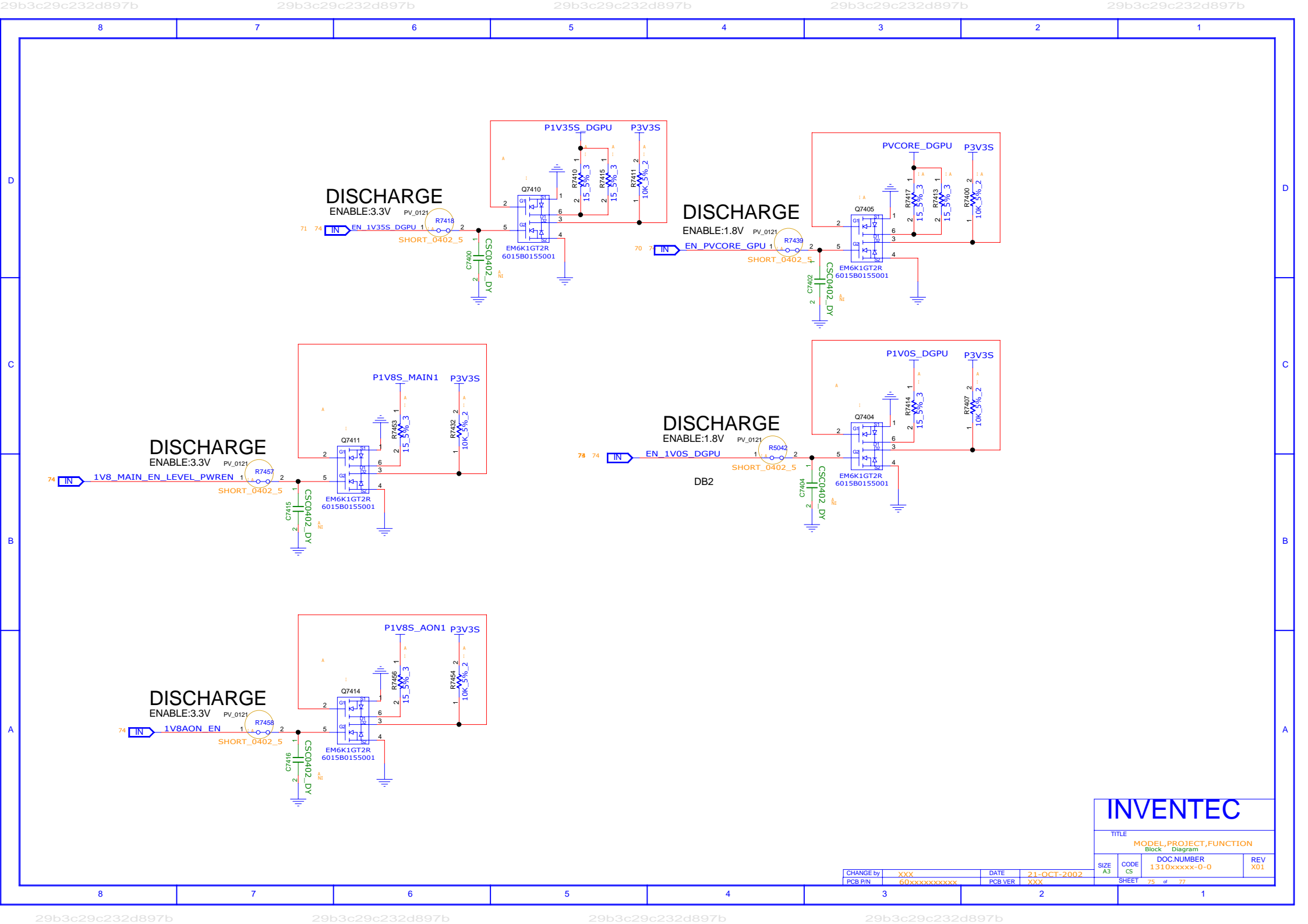
FOR GC6 2.1



INVENTEC

MODEL	PROJECT	FUNCTION
1310	1310	1310
1310	1310	1310
1310	1310	1310

CHANGES	DATE	BY	REV
1	21-OCT-2002	1310	1



INVENTEC

TITLE
MODEL,PROJECT,FUNCTION
Block Diagram

SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
SHEET 75 of 77			

CHANGE by PCB P/N	XXX 60xxxxxxxxxxx	DATE PCB VER	21-OCT-2002 XXX
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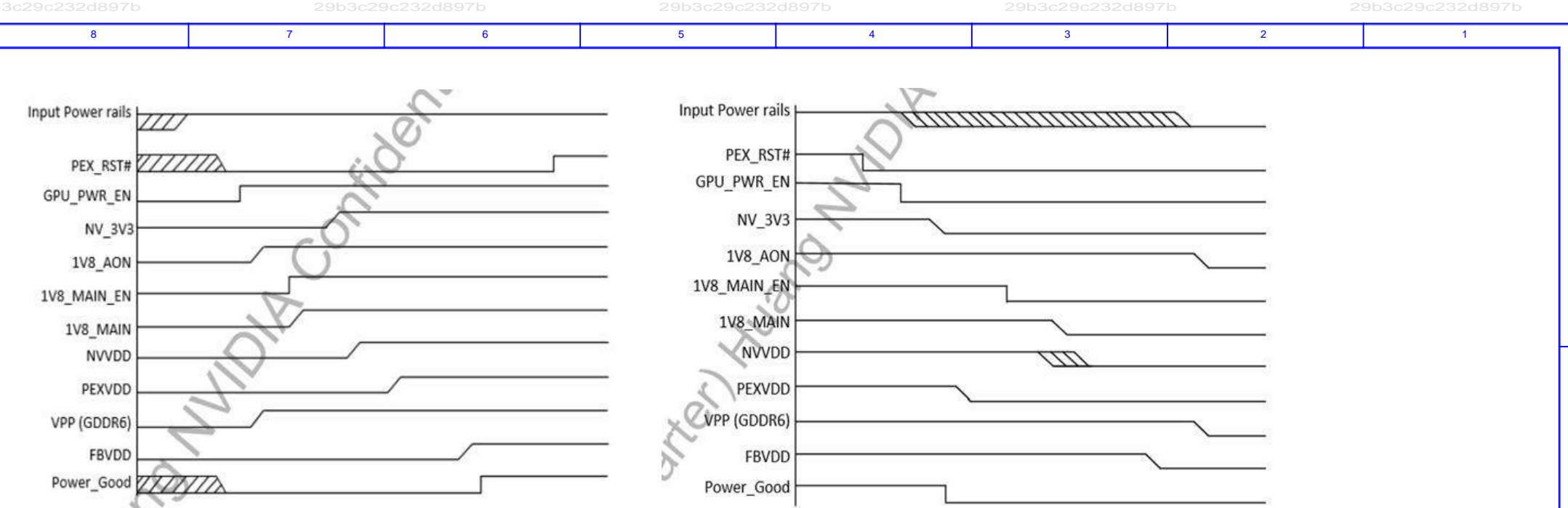


Figure 5.6 Power-Up Sequence

Figure 5.7 Power-Down Sequence

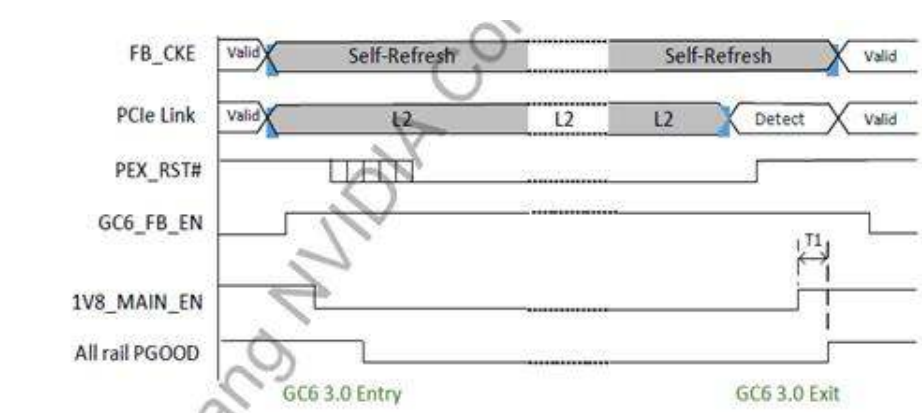
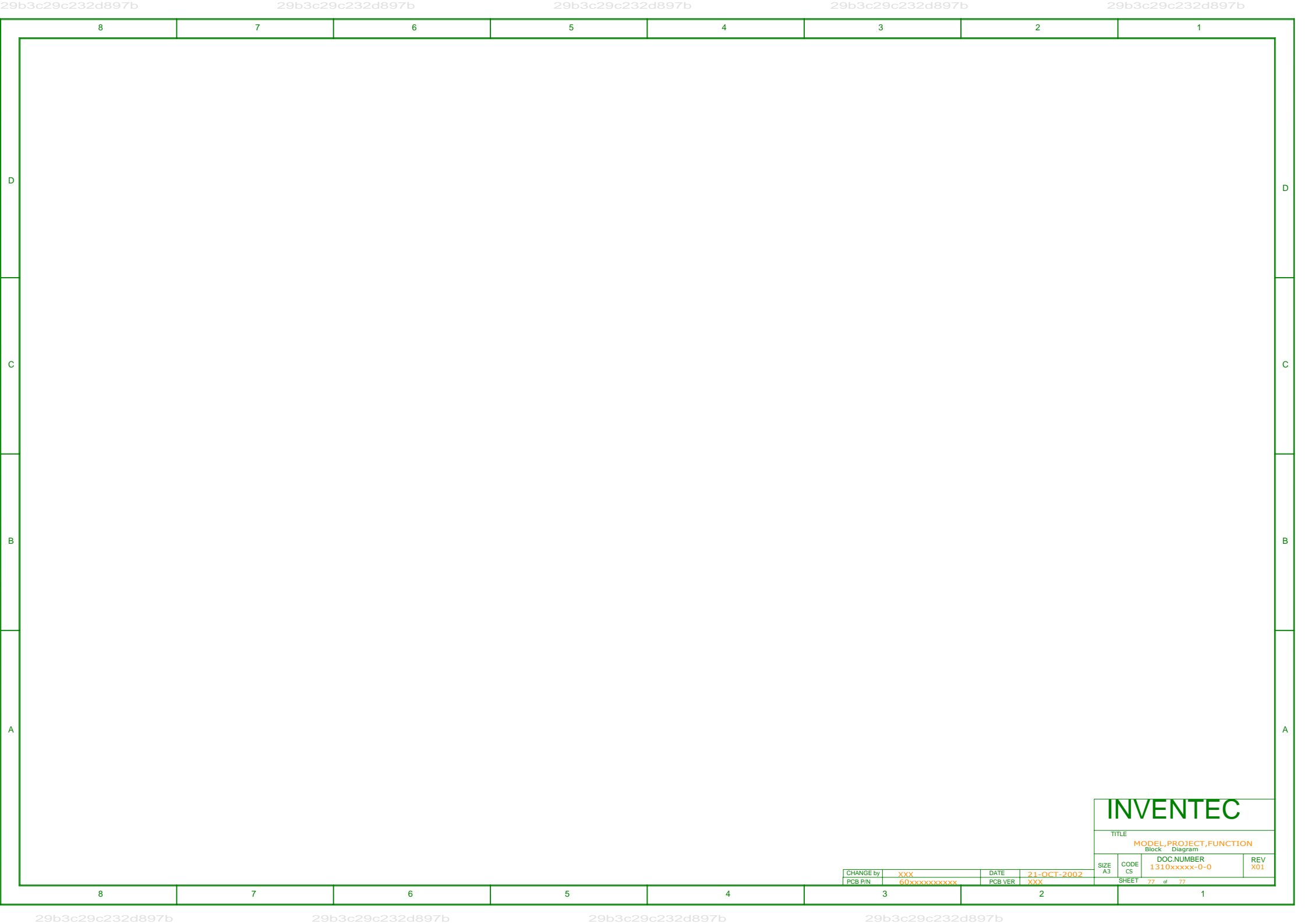


Figure 6.19 GC6 3.0 Entry/Exit Timing Sequence

INVENTEC			
TITLE MODEL, PROJECT, FUNCTION			
SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
SHEET 76 of 77			

CHANGE by PCB P/N	XXX 60xxxxxxxxxx	DATE PCB VER	21-OCT-2002 XXX
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INVENTEC

TITLE			
MODEL,PROJECT,FUNCTION Block Diagram			
SIZE A3	CODE CS	DOC NUMBER 1310xxxxx-0-0	REV X01
SHEET 77 of 77			

CHANGE by	XXX	DATE	21-OCT-2002
PCB P/N	60xxxxxxxxxx	PCB VER	XXX